

ELECTRICAL CHARACTERIZATION OF STANDARD AND RADIATION-HARDENED RCA CDP1856D

JUNE 1979

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HUGHES

HUGHES AIRCRAFT COMPANY
CULVER CITY, CALIFORNIA



ELECTRICAL CHARACTERIZATION OF
STANDARD AND RADIATION-HARDENED RCA CDP1856D
4-BIT, CMOS, BUS BUFFER/SEPARATOR

FINAL REPORT
JUNE 1979

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TEST ABSTRACT

Electrical characterization tests were performed on 25 standard and 15 radiation-hardened RCA CDP1856D, 4-bit, noninverting, bus separators. The tests included functional tests and AC and DC parametric tests at ambient temperatures of -55°C , -20°C , 25°C , 85°C , and 125°C .

All measurements were performed on a Tektronix S-3260 Automated Test System. Temperatures were controlled by a Temptronic TP450A thermal airstream unit.

All 40 devices passed the functional tests and yielded nominal values in the AC and DC parametric tests.

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1.0 INTRODUCTION

This report documents the results of electrical characterization test to determine the electrical performance characteristics of the 25 standard and 15 radiation-hardened RCA CDP1856D, 4-bit, CMOS, bus separators. Electrical characteristics of the devices were measured and recorded under various test conditions. The data was analyzed and tabulated to show the effect of operating conditions on performance and to indicate parameter deviations among devices in each group. Accuracy was given precedence over test-time efficiency where practical, and tests were designed to measure worst-case performance.

The tests were divided into three categories: functional, AC parametric, and DC parametric. The functional tests were performed on a pass/fail basis to verify that the device under test (DUT) was logically correct. All voltage and timing conditions, except supply voltage, were set to nominal values in order to distinguish between functional failures and statistically unusual devices. The AC parametric tests consisted of propagation delays and transition times. These tests were performed using the "one-shot" measurement system. The DC parametric measurements were static measurements made by forcing specified conditions on the DUT and measuring the resultant voltage or current.

All of these tests were performed on a Tektronix S-3260 Automated Test System. All devices were subjected to the full set of tests at ambient temperatures of -55°C , -20°C , 25°C , 85°C , and 125°C . The temperature environment was provided by a Temptronic TP450A thermal airstream unit.

2.0 DEVICE DESCRIPTION

The RCA CDP1856D is a 4-bit, noninverting bus separator designed for use in the CDP-1800 series microprocessor systems. The device can be directly controlled by the CDP1802 microprocessor without the use of additional components. The CDP1856 uses static silicon-gate CMOS circuitry with a single voltage supply. It is compatible with the CD4000 series and may be used as a general purpose bus buffer or separator. It is supplied in a ceramic, 16-lead, hermetic, dual-in-line package. A brief operational description of the device is given below. Pin connections are shown in Figure 1, and a functional diagram appears in Figure 2.

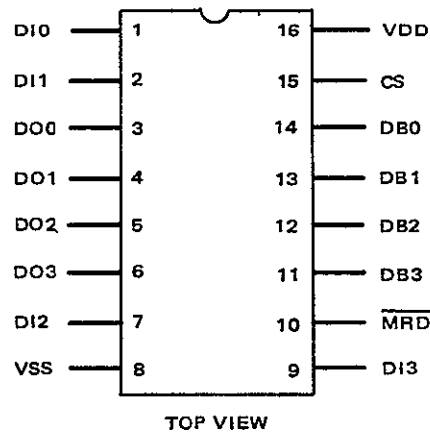


Figure 1. CDP1856D pin connections.

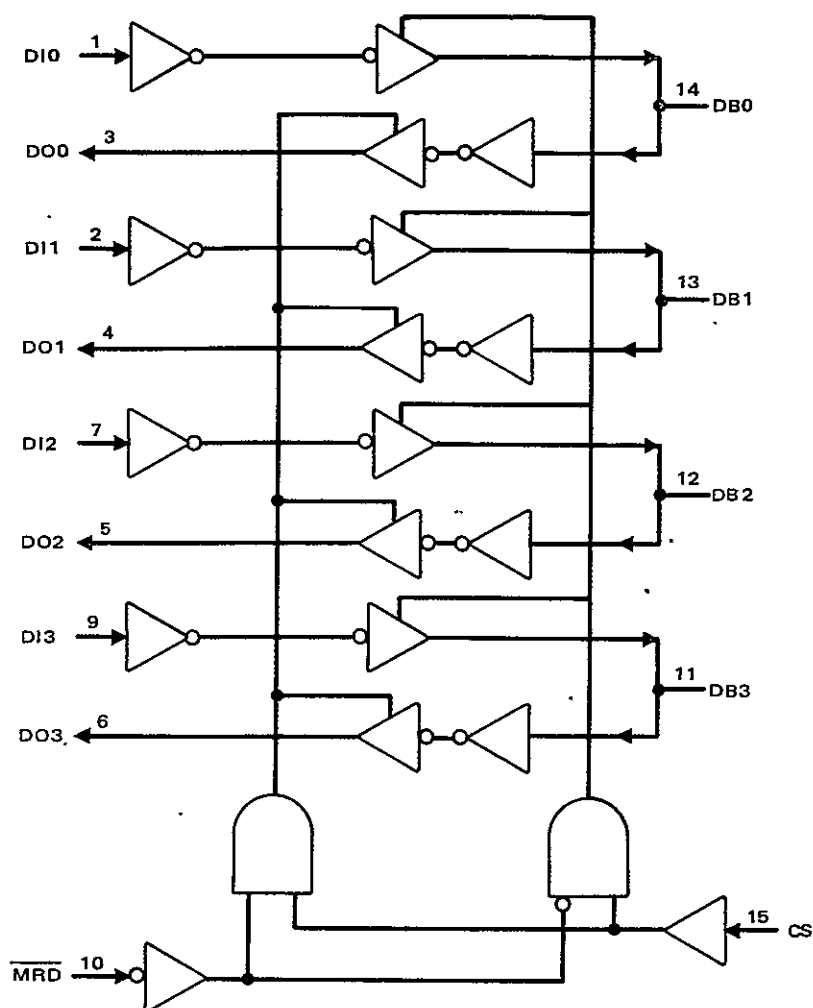


Figure 2. CDP1856D functional diagram.

2.1 PIN DESCRIPTIONS

2.1.1 Chip Select Input (CS)

The chip select input enables (logic "1") or disables (logic "0"), the tristate output drivers.

2.1.2 Memory Read Input (MRD)

The memory read input determines the direction of data flow when the device is enabled.

2.1.3 Data-In Inputs (DI0 to DI3)

The data-in inputs receive input data for transfer to the bus.

2.1.4 Data-Out Outputs (DO0 to DO3)

The data-out outputs transfer output data from the bus tristate drivers

2.1.5 Data Bus (DB0 to DB3)

The data bus provides inputs or outputs, depending on the direction of data flow.

2.2 DEVICE OPERATION

When CS is low (logic "0"), all outputs are disabled. When CS is high (logic "1"), MRD determines the direction of data flow. When MRD = 0, the bus drivers are enabled and data is transferred from the DATA-IN terminals to the bus. When MRD = 1, the bus drivers are disabled and the DATA-OUT drivers are enabled, allowing transfer of data from the bus to the DATA-OUT outputs.

3.0 DESCRIPTION OF TESTS

3.1 FUNCTIONAL TESTS

Functional tests were performed on a pass/fail basis with the pattern given in Table 1 and under the test conditions given in Table 2. (See Figure 3 for timing.) In general, the purpose of the functional tests was to verify that each device performed in accordance with its expected truth table. Performing the tests at both VDD = 3V and VDD = 15V (13V for the radiation-hardened devices) guaranteed that the devices operated over the specified voltage extremes. The lower VDD voltage of 13V for the radiation-hardened devices was used to accommodate the lowered transistor breakdowns common to irradiated CMOS devices.

The functional tests were performed at ambient temperatures of -55°C, -20°C, 25°C, 85°C, and 125°C using a Temptronic TP450A thermal airstream unit to control the device test temperature. All 40 devices passed the functional tests at the specified temperature and voltage extremes.

3.2 AC PARAMETRIC TESTS

AC parametric tests performed on the 1856 included propagation delays and transition times. Propagation delays were measured by a "one-shot" (real time) method, which makes a direct measurement of the time between two transitions. Transition times were measured by measuring the delay to the output under test at two levels (usually the 10-percent and 90-percent points of output swing). The difference between the two delays is the transition time between the two levels. See Figure 4 for propagation delay definitions and Figure 5 for transition time. AC-parametric test conditions are given in Table 3.

TABLE 1. FUNCTIONAL TEST PATTERN

Name		Pin	Time Slot																																					
			1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	23	24	25	26	27	28	29	30	31	32	33	34	35			
Input	CS	15	0	0	1	1																	1																	
	MRD	10	0	1	1	0																1																		
	DI0	1	1			0	1	0	0	0	1	1	1	0	1	1	0	1	0	0	1																			
	DI1	2	1			0	0	1	0	0	1	1	0	1	1	0	1	0	1	0	1																			
	DI2	7	1			0	0	0	1	0	1	0	1	1	0	1	1	0	0	1	1																			
	DI3	9	1			0	0	0	0	1	0	1	1	1	0	0	0	1	1	1	1																			
Bidirectional			Input			Output																			Input															
	DB0	14	0			1	0	1	0	0	0	1	1	1	0	1	1	0	1	0	0	1	1	0	0	0	1	1	0	1	1	0	1	0	1	0	0	1		
	DB1	13	0			1	0	0	1	0	0	1	1	0	1	1	0	1	0	1	0	1	0	1	0	1	0	1	1	0	1	1	0	1	0	1	0	1		
	DB2	12	0			1	0	0	0	1	0	1	0	1	1	0	1	1	0	0	1	1	0	0	1	1	0	1	1	0	1	1	0	0	1	1	1			
	DB3	11	0			1	0	0	0	0	1	0	1	1	1	0	0	0	1	1	1	1	0	0	1	0	1	1	1	0	0	0	1	1	1	1	1			
Output	DO0	3	X		0	X																	1	0	0	0	1	1	1	0	1	1	0	1	0	0	1			
	DO1	4	X		0	X																	0	1	0	0	1	1	0	1	1	0	1	0	1	0	1			
	DO2	5	X		0	X																	0	0	1	0	1	0	1	1	0	1	1	0	0	1	1			
	DO3	6	X		0	X																	0	0	0	1	0	1	1	1	0	0	0	1	1	1	1			
				Leakage Test																																				
X denotes high-impedance state; blank indicates no change from previous state																																								

TABLE 2. FUNCTIONAL TEST CONDITIONS

Parameter	At VDD=3V	At VDD=15V (Standard)	At VDD=13V (Rad-Hard)
Input Driver Level, High (Logic "1")	3V	15V	13V
Input Driver Level, Low (Logic "0")	0V	0V	0V
Output Compare Level, High	1.5V	7.5V	6.5V
Output Compare Level, Low	1.5V	7.5V	6.5V
Cycle Time (Period)	16 μ s	16 μ s	16 μ s
Compare Window:			
Start	15.95 μ s	15.95 μ s	15.95 μ s
Duration	8 ns	8 ns	8 ns

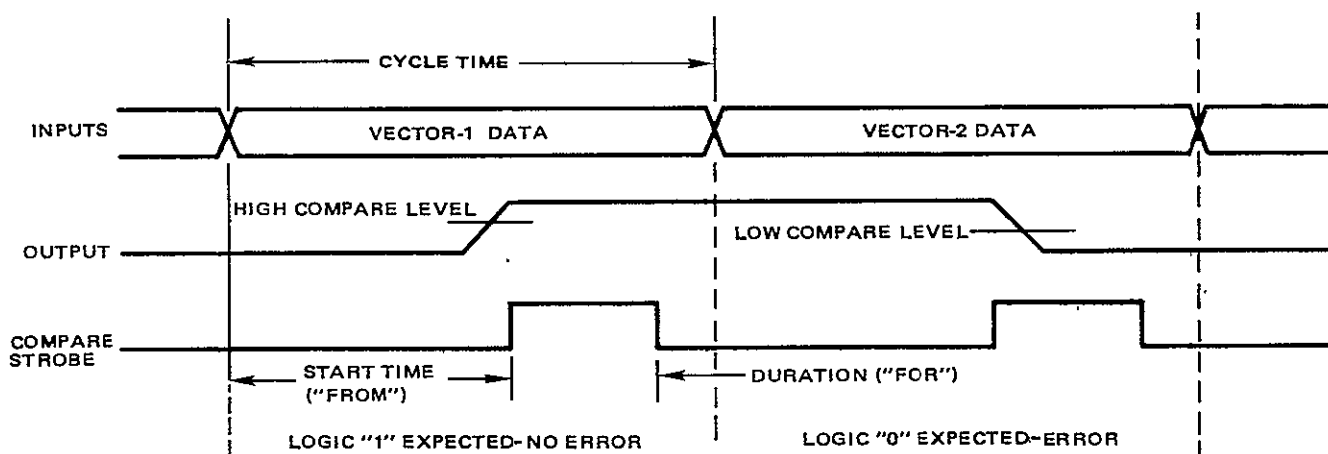


Figure 3. Functional test timing.

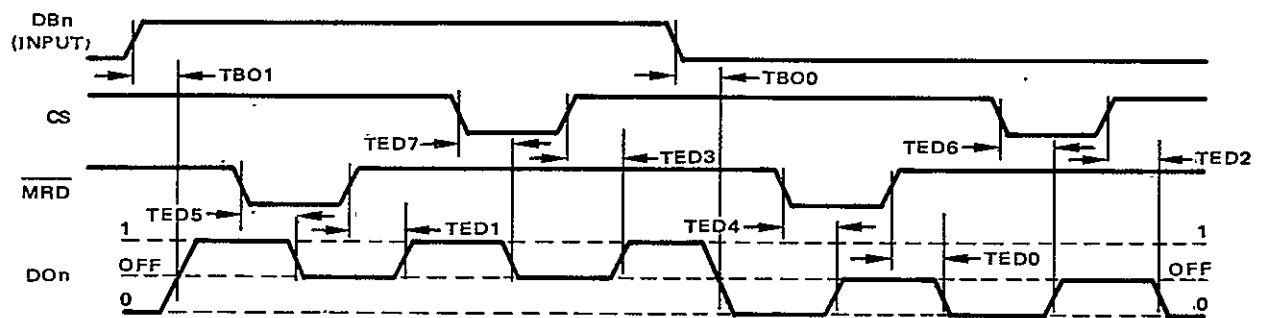
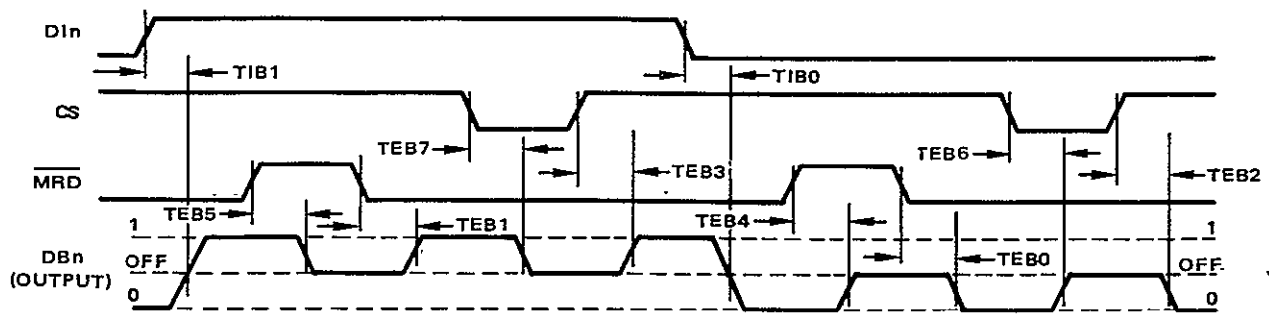


Figure 4. Propagation delay definitions.

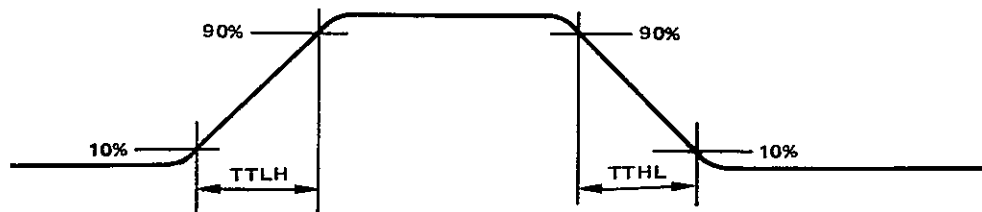
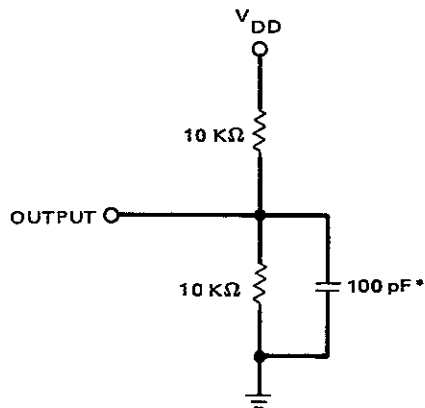


Figure 5. Transition time.

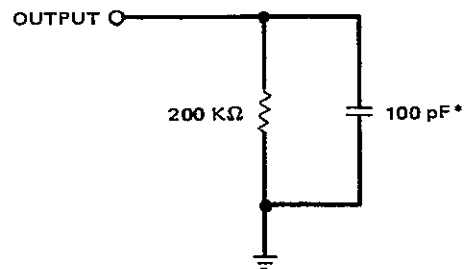
TABLE 3. AC-PARAMETRIC TEST CONDITIONS

Parameter	At VDD=5V	At VDD=10V
Drivers, High	5V	10V
Drivers, Low	0V	0V
Comparators		
Delays to On/Off		
High	3.75V	7.5V
Low	1.25V	2.5V
Other Delays		
High	2.5V	5V
Low	2.5V	5V
Transition Time		
High	4.5V	9V
Low	0.5V	1V
Cycle Time	5 μ s	5 μ s
Output Loads		
On/Off	Figure 6	Figure 6
Other	Figure 7	Figure 7



*INCLUDES SYSTEM CAPACITANCE

Figure 6. Output load (on/off).



*INCLUDES SYSTEM CAPACITANCE

Figure 7. Output Load

The following AC parameters were measured at VDD voltage of 5V and 10V:

<u>Parameter</u>	<u>Symbol</u>
1. MRD to DB on, low	TEB0
2. MRD to DB on, high	TEB1
3. CS to DB on, low	TEB2
4. CS to DB on, high	TEB3
5. MRD to DB off, low	TEB4
6. MRD to DB off, high	TEB5
7. CS to DB off, low	TEB6
8. CS to DB off, high	TEB7
9. MRD to DO on, low	TED0
10. MRD to DO on, high	TED1
11. CS to DO on, low	TED2
12. CS to DO on, high	TED3
13. MRD to DO off, low	TED4
14. MRD to DO off, high	TED5
15. CS to DO off, low	TED6
16. CS to DO off, high	TED7
17. DI to DB, low	TIB0
18. DI to DB, high	TIB1
19. DB to DO, low	TBO0
20. DB to DO, high	TBO1
21. Transition time low-to-high	TTLH
22. Transition time high-to-low	TTHL

3.3 DC PARAMETRIC TESTS

Most of the DC parametric tests were performed in a straightforward manner. Input conditions were applied using the drivers as in the functional and AC tests, and the pin under test was forced with a regulated voltage or current supply (depending on the specific parameter). The parameter under test was then measured and recorded.

The exceptions were the V_{IH} (minimum logic "1" input voltage) and V_{IL} (maximum logic "0" input voltage) tests. These were performed by running a functional test pattern while varying the input level under test. In the V_{IH} test, all inputs except the one under test had drive levels of V_{DD} and 0V. Timing conditions were generous. The logic "0" level of the input under test was set at 0V, and the logic "1" level was set to a low enough voltage to ensure that the device would fail to function properly. The functional test was run repeatedly, with the logic "1" level on the input under test raised each time, until the device passed. The voltage at which the device first passed was the minimum logic "1" voltage for the input under test. The V_{IL} test was performed in a similar manner.

Table 4 lists the DC parameters measured. V_{IH} and V_{IL} were measured using the functional test pattern of Table 5. The timing and output comparator conditions were the same as those for the functional tests (Table 2). The input voltages were varied in 0.1-volt increments as shown in Table 5. Each input was tested separately at each voltage.

TABLE 4. DC-PARAMETRIC TESTS

Symbol	Parameter Name	Pin(s)	Voltage or Current Forced	VDD-VSS	Comments ¹
VICP	Input clamp voltage, positive	Each input	1 mA	0V	VDD and VSS grounded.
VICN	Input clamp voltage, negative	Each input	-1 mA	0V	VDD and VSS grounded.
IIH	Input current, high	Each input	15V ²	15V ²	0V on other inputs.
IIL	Input current, low	Each input	0V	15V ²	15V ² on other inputs.
IOH	Output current, high	Each output	4.6V 4.6V 9.5V 9.0V 10.5V	5V 5V 10V 10V 12V	Output under test is in Logic "1" (high) state.
IOL	Output current, low	Each output	0.4V 0.5V 0.5V 1.0V 1.5V	5V 5V 10V 10V 12V	Output under test is in Logic "0" (low) state.
IOZ1	High-impedance output current	Each output	12V ³ 15V ²	12V ³ 15V ²	0V on all data inputs. Outputs disabled.
IOZ2	High-impedance output current	Each output	0V 0V	12V ³ 15V ²	VDD on all data inputs. Outputs disabled.
ISS	Quiescent supply current	VSS	0V 0V	10V 15V ²	Inputs forced with functional test pattern at time slots 1, 2, 3, 35, 4, and 5 for 6 tests at each voltage. Logic 1 = VDD, logic 0 = VSS on inputs. Outputs are open.

¹ Bidirectional bus pins are included in both input and output measurements.

² 13V for radiation-hardened parts.

³ 10V for radiation-hardened parts.

TABLE 5. VIH AND VIL TEST CONDITIONS

Parameter	VDD (V)	Varied		Pin Under Test		Other Pins		Compare Levels	
		From (V)	To (V)	VIH (V)	VIL (V)	VIH (V)	VIL (V)	High (V)	Low (V)
VIH	5	0	5	—	0	5	0	2.5	2.5
VIL	5	5	0	5	—	5	0	2.5	2.5
VIH	10	0	10	—	0	10	0	5	5
VIL	10	10	0	10	—	10	0	5	5
VIH	12	0	12	—	0	12	0	6	6
VIL	12	12	0	12	—	12	0	6	6

1.0 INTRODUCTION

This report documents the results of electrical characterization tests to determine the electrical performance characteristics of the 25 standard and 15 radiation-hardened RCA CDP1856D, 4-bit, CMOS, bus separators. Electrical characteristics of the devices were measured and recorded under various test conditions. The data was analyzed and tabulated to show the effect of operating conditions on performance and to indicate parameter deviations among devices in each group. Accuracy was given precedence over test-time efficiency where practical, and tests were designed to measure worst-case performance.

The tests were divided into three categories: functional, AC parametric, and DC parametric. The functional tests were performed on a pass/fail basis to verify that the device under test (DUT) was logically correct. All voltage and timing conditions, except supply voltage, were set to nominal values in order to distinguish between functional failures and statistically unusual devices. The AC parametric tests consisted of propagation delays and transition times. These tests were performed using the "one-shot" measurement system. The DC parametric measurements were static measurements made by forcing specified conditions on the DUT and measuring the resultant voltage or current.

~~All of these tests were~~ performed on a Tektronix S-3260 Automated Test System. All devices were subjected to the full set of tests at ambient temperatures of -55°C , -20°C , 25°C , 85°C , and 125°C . The temperature environment was provided by a Temptronic TP450A thermal airstream unit.

4.0 TEST RESULTS

4.1 SUMMARY

All of the devices in both groups passed the functional tests and yielded nominal values in the parametric tests.

4.2 DATA TABULATION

For each parameter the data was tabulated by device serial number and temperature. The sign "<*" to the right of a value was used to indicate out-of-range measurements. The minimum, maximum, mean, standard deviation, and median values were listed at the bottom of each temperature column. Out-of-range measurements were excluded from the statistics.

The standard parts were numbered 3 through 27; the radiation-hardened parts were numbered 28 through 42. The statistics for each group were calculated separately.

In addition to the printed data, histograms of some of the parameters were provided. Each histogram displays data for one or more parameters at all five temperatures, in ascending order (-55°C, -20°C, 25°C, 85°C, 125°C). The histograms illustrate the effect of temperature and the distribution of devices for each parameter. The standard and radiation-hardened parts were plotted separately. Table 6 is a list of the parameters plotted. The histograms are provided in Appendix A.

TABLE 6. LIST OF HISTOGRAMS

Parameters	Conditions	
Propagation Delays	VDD	
TEB0, TEB1, TEB2, TEB3	5V, 10V	
TEB4, TEB6	5V, 10V	
TEB5, TEB7	5V, 10V	
TED0, TED1, TED2, TED3	5V, 10V	
TED4, TED6	5V, 10V	
TED5, TED7	5V, 10V	
TIB0, TIB1	5V, 10V	
TBO0, TBO1	5V, 10V	
TTLH, TTHL	5V, 10V	
DC Parameters	VDD	VO
IOH	5V	4.6V
IOH	10V	9.5V
IOL	5V	0.4V
IOL	10V	0.5V
IOZ	15V*	15V*
IOZ	15V*	0V
ISS	10V	—
ISS	15V	—
*13V for radiation-hardened parts.		

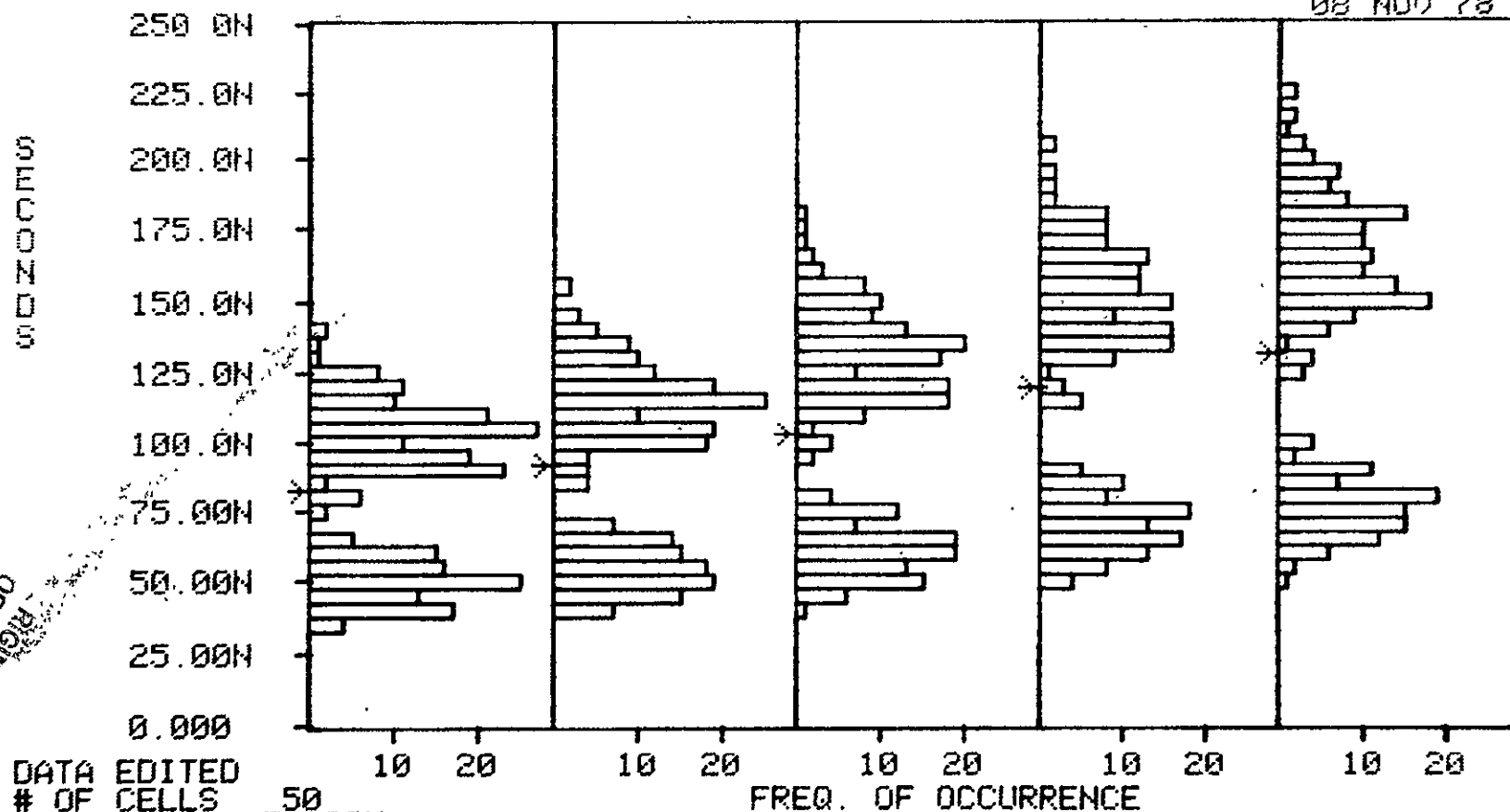
APPENDIX A HISTOGRAMS

RADIATION-HARDENED DEVICES

DATA FOR TEB03A

TEBO, 1, 2, 3 AT 50

02 NOV 78



READINGS:	239	239	240	240	238
MAXIMUM:	140.0N	156.0N	177.5N	206.0N	225.5N
MEAN:	82.19N	91.00N	102.9N	119.4N	131.3N
MINIMUM:	34.65N	37.70N	41.85N	48.40N	52.30N
STD. DEV.:	28.45N	32.03N	37.12N	43.77N	48.04N

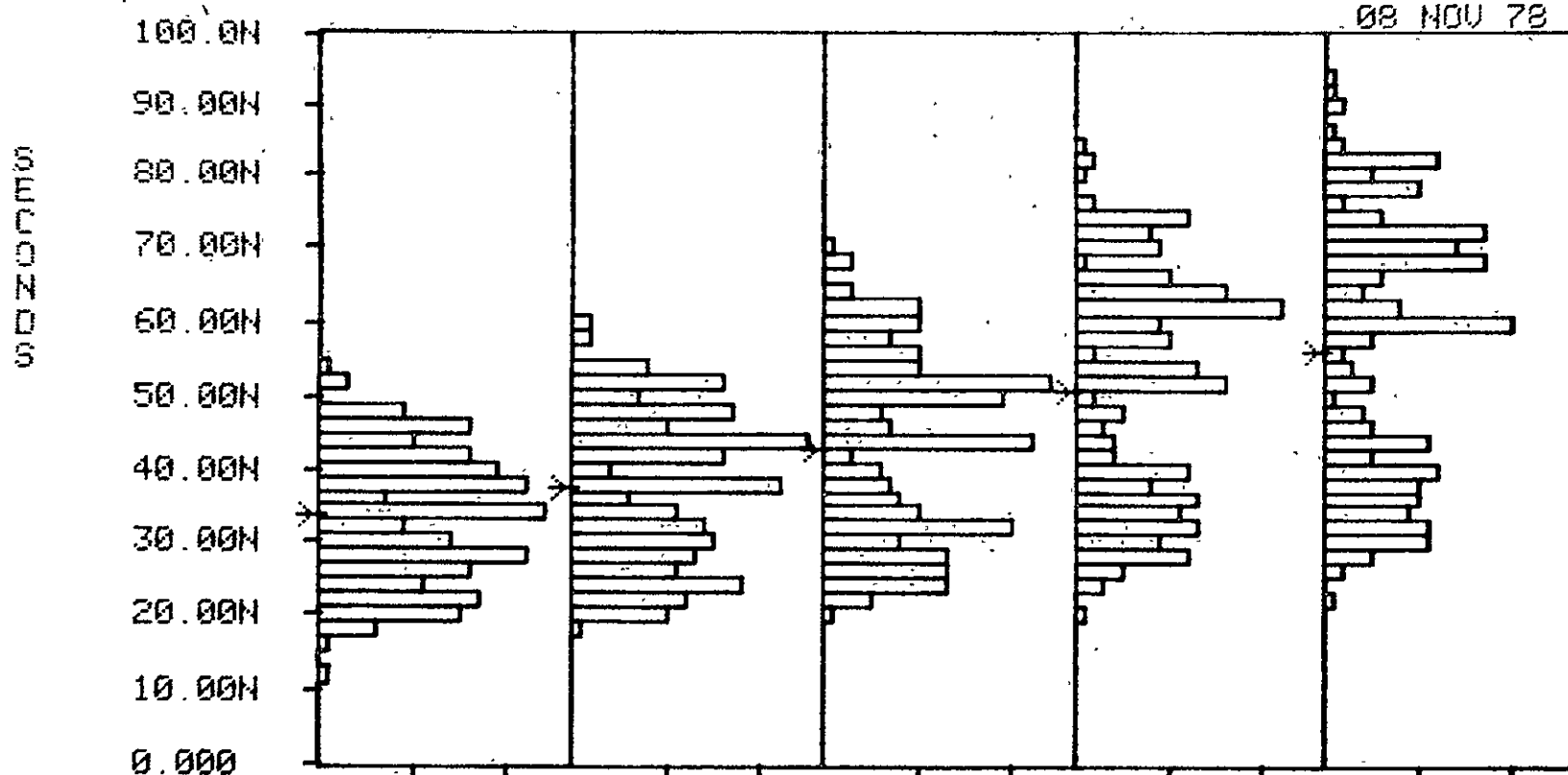
A-1

S-3260

DATA FOR TEB03B

TEB0,1,2,3 AT 100

08 NOV 78



DATA EDITED

OF CELLS

CELL SIZE

50
2.000N

FREQ. OF OCCURRENCE

READINGS:

MAXIMUM

MEAN

MINIMUM

STD. DEV.

239

53.10N

33.36N

11.95N

8.998N

240

60.65N

37.23N

18.45N

10.46N

239

70.85N

42.87N

20.65N

12.56N

239

84.70N

50.81N

19.70N

15.67N

240

94.40N

56.27N

22.10N

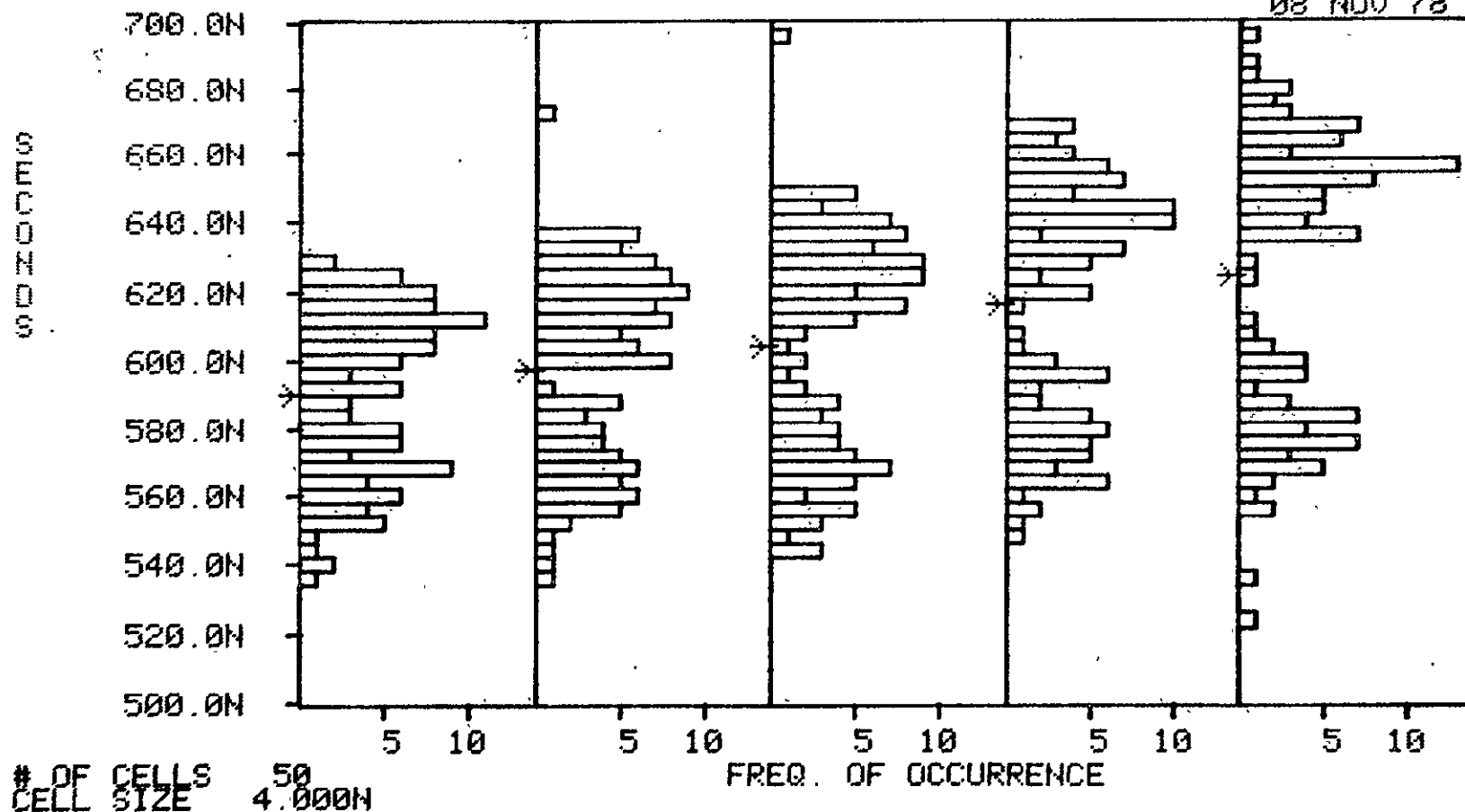
17.80N

S-3260

DATA FOR TEB46A

TEB4/TEB6 AT 50

08 NOV 78

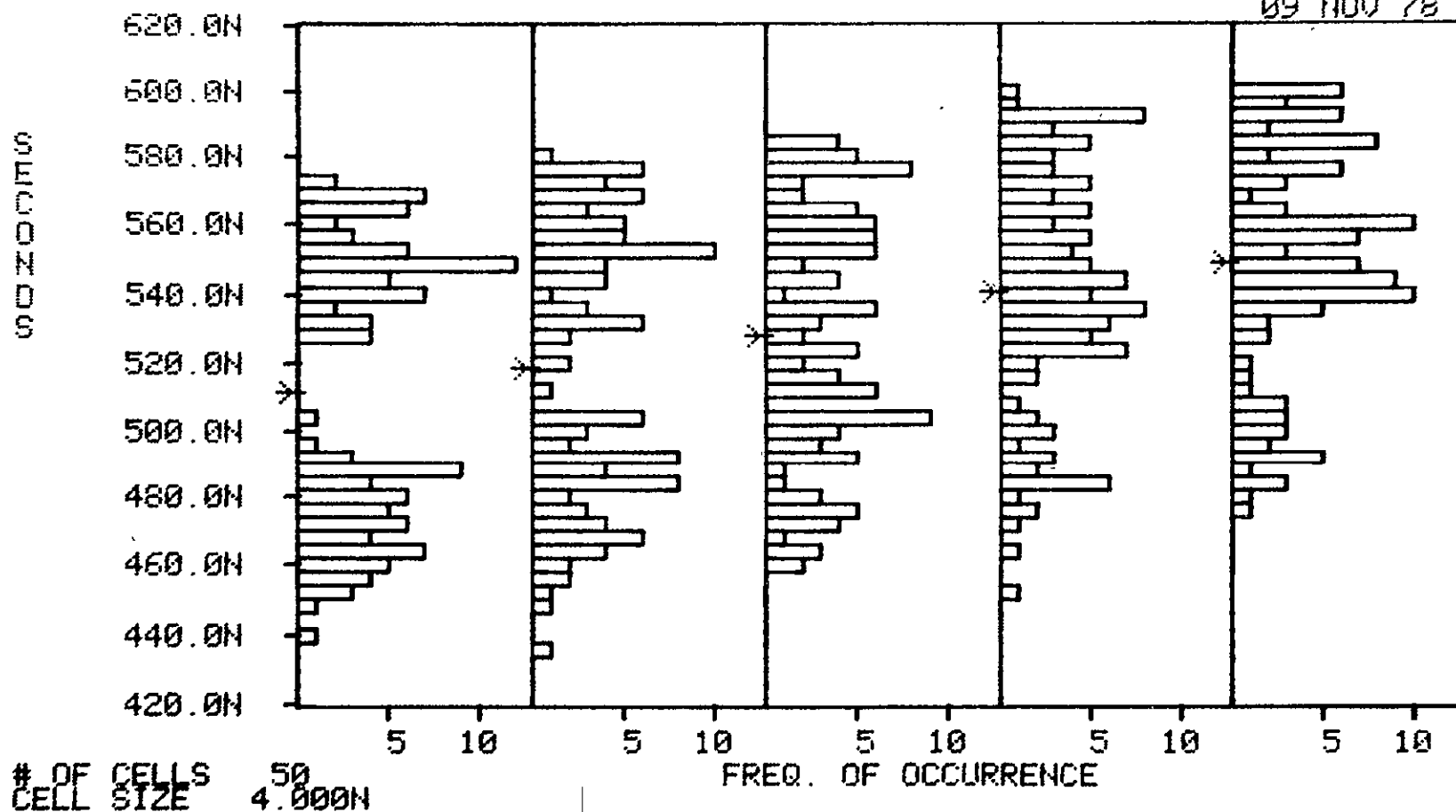


A-3

DATA FOR TEB46B

TEB4/TEB6 AT 10V

09 NOV 78



READINGS:

MAXIMUM:

MEAN:

MINIMUM:

STD. DEV. : .

120

571.0M

111.1M

438. OM

40.9014

120

578.0N

Figure 1

4350 GN

39. 3021

120

584.5N

7-0000

4500.0M

36.24N

120

599.0N

546 32

453. 0N

34.78N

129

601.0N

548.8N

477.0N

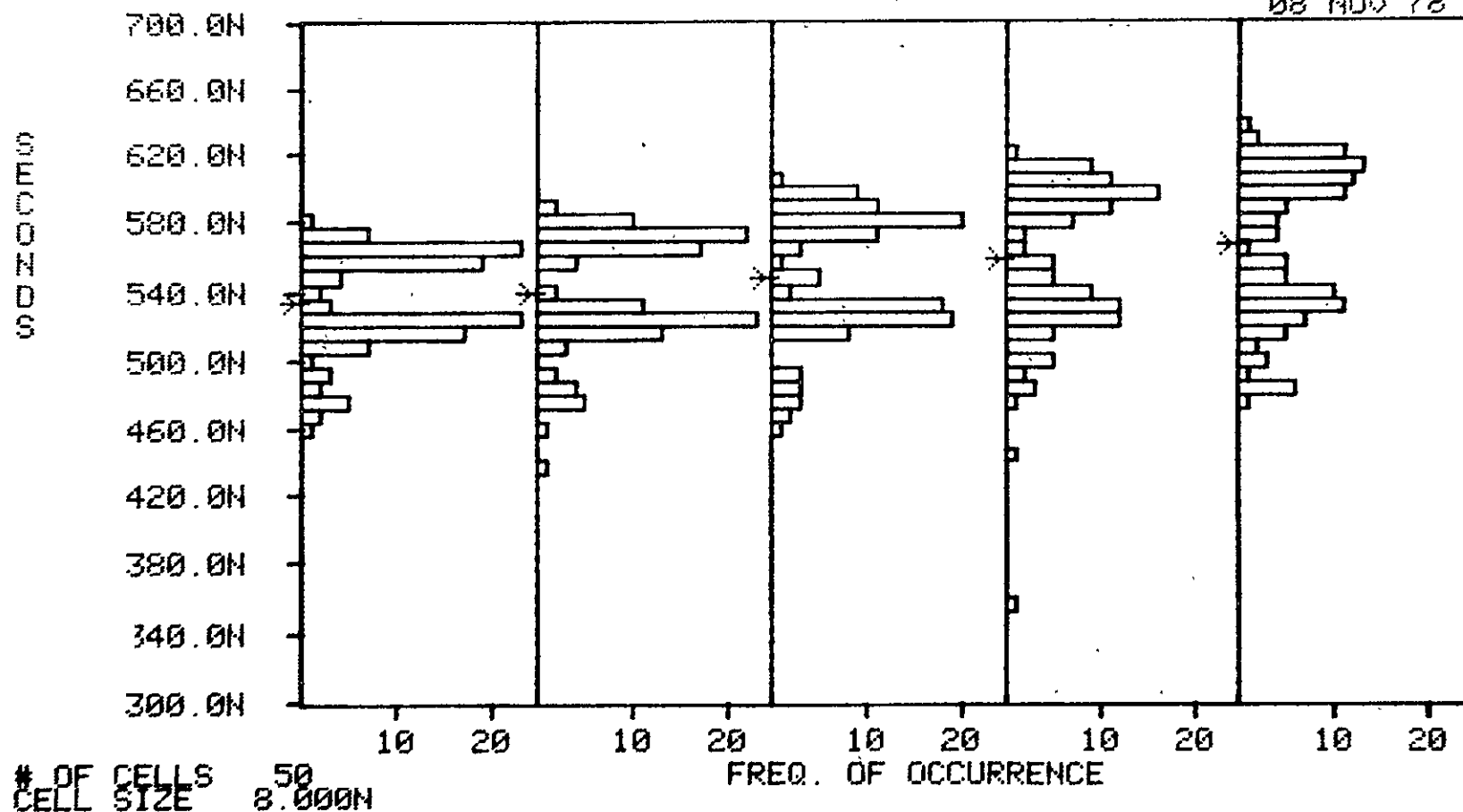
33. 12N

S-3260

DATA FOR TEB57A

TEB5/TEB7 AT 50

08 NOV 78

# OF CELLS
CELL SIZE50
8.000N

READINGS:
 MAXIMUM:
 MEAN:
 MINIMUM:
 STD. DEV.:

120
 576.5N
 533.7N
 460.5N
 28.77N

120
 587.0N
 539.4N
 435.0N
 32.28N

120
 604.5N
 548.2N
 458.0N
 35.64N

120
 618.5N
 557.7N
 356.0N
 43.62N

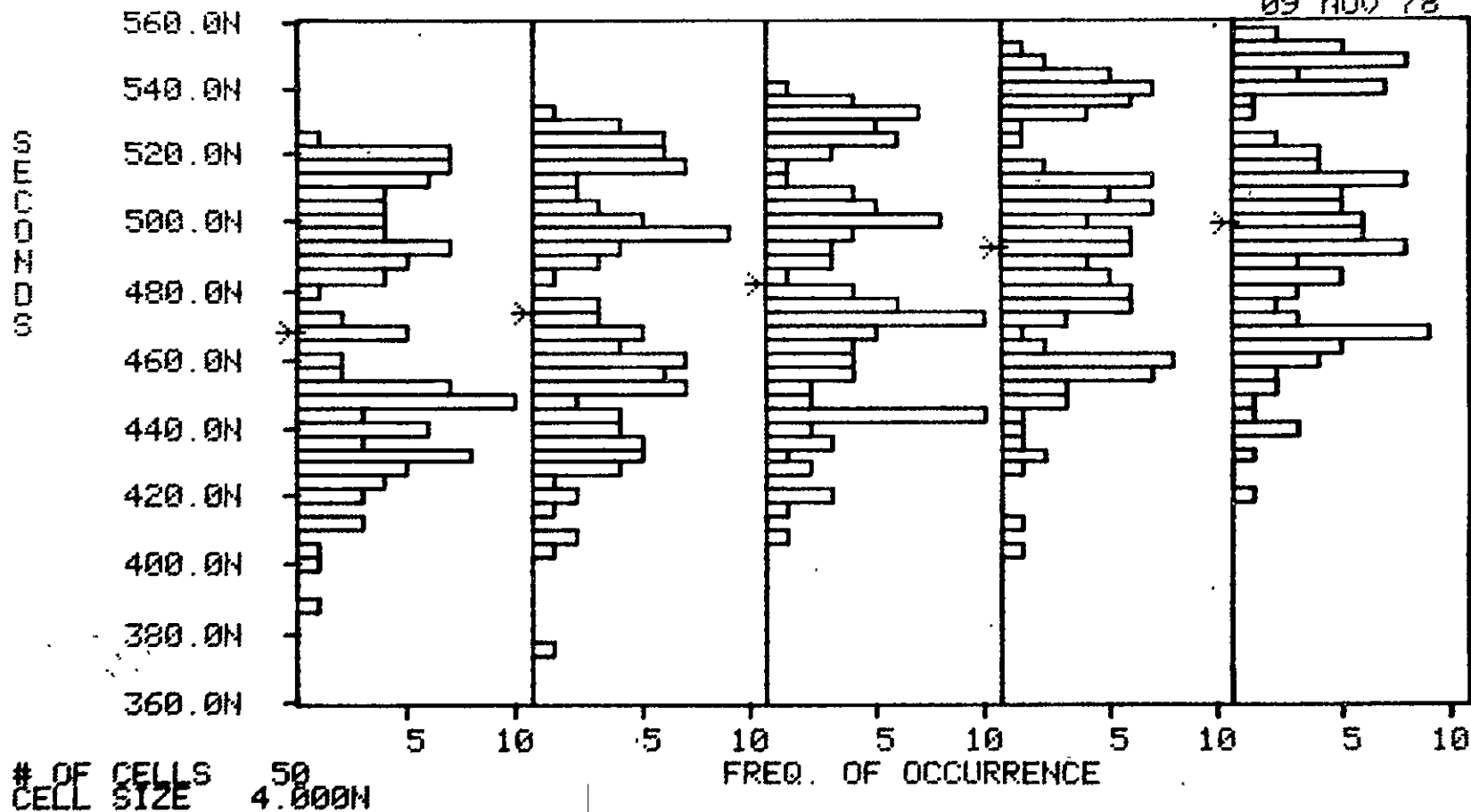
120
 632.0N
 566.3N
 476.0N
 43.24N

S-3260

DATA FOR TEB57B

TEB5/TEB7 AT 10U

09 NOV 78



READINGS:

MAXIMUM:

MEAN:

MINIMUM:

STD. DEV.:

120

524.0N

468.0N

386.0N

35.56N

120

531.0N

473.6N

374.5N

35.37N

120

539.0N

482.1N

408.5N

33.68N

120

550.0N

492.1N

405.5N

33.58N

120

556.5N

499.2N

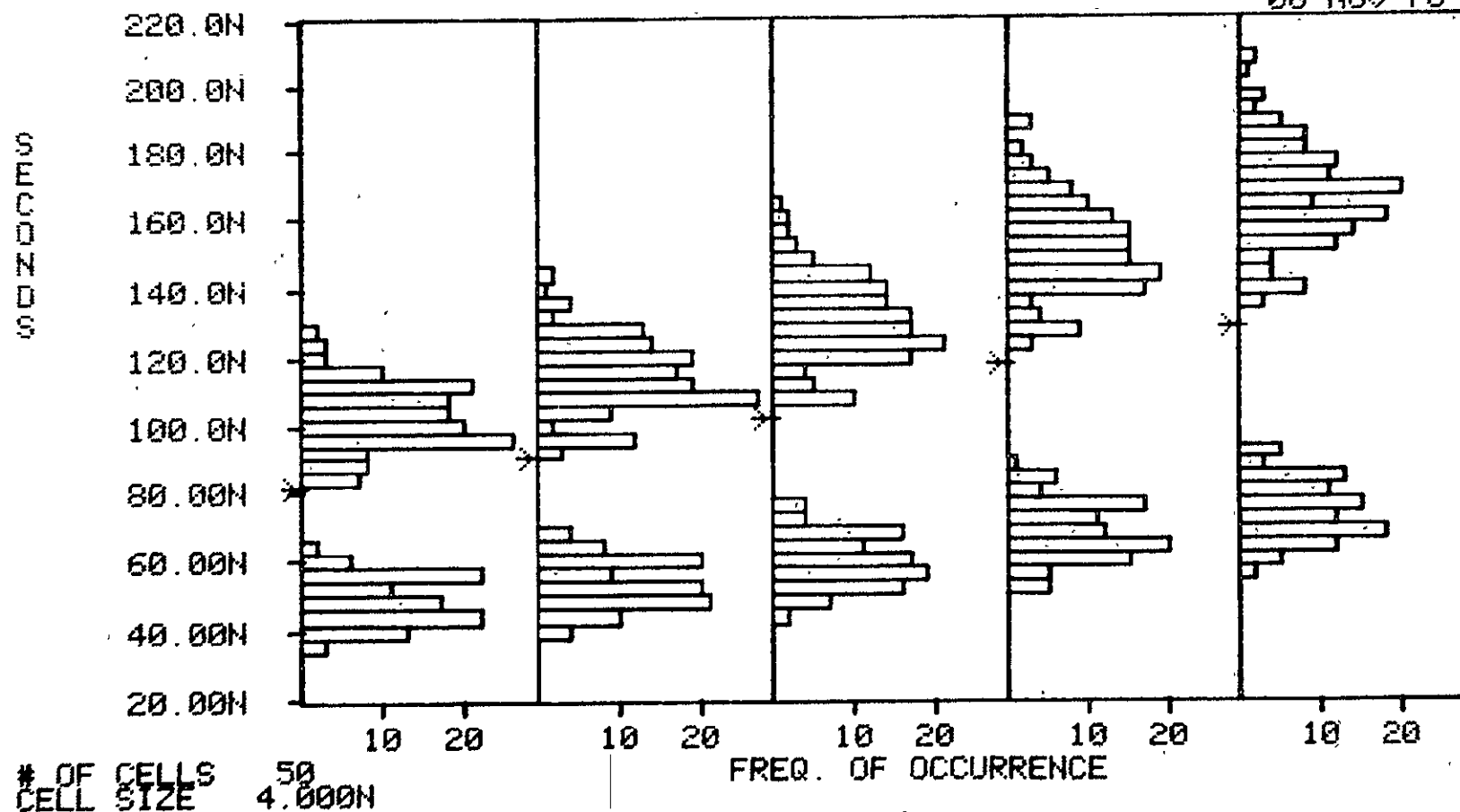
419.0N

32.54N

S-3260 DATA FOR TED03A

TED0,1,2,3 AT 50

08 NOV 78



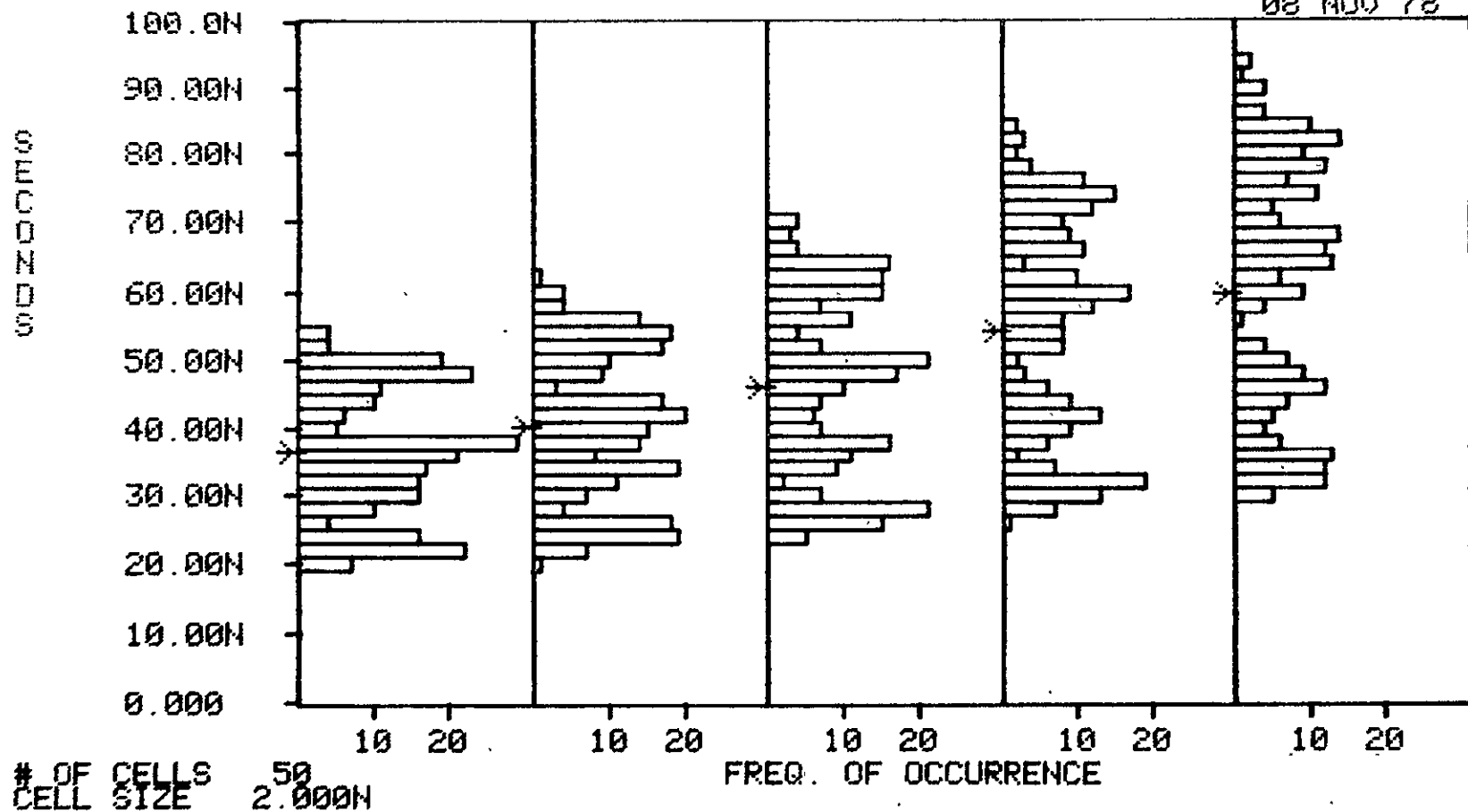
READINGS:	240	240	240	240	240
MAXIMUM:	128.0N	142.5N	162.0N	188.5N	207.0N
MEAN:	81.25N	89.93N	101.8N	117.9N	128.9N
MINIMUM:	37.35N	40.95N	45.80N	52.00N	56.45N
STD. DEV.:	27.89N	31.38N	36.13N	42.48N	46.83N

S-3260

DATA FOR TED03B

TED0,1,2,3 AT 10U

08 NOV 78



READINGS:

MAXIMUM:

MEAN:

MINIMUM:

STD.DEV.:

240
54.20N
36.22N
19.20N
9.531N

240
61.35N
40.22N
20.80N
10.99N

240
70.90N
46.05N
23.30N
13.15N

240
83.90N
54.11N
26.85N
16.09N

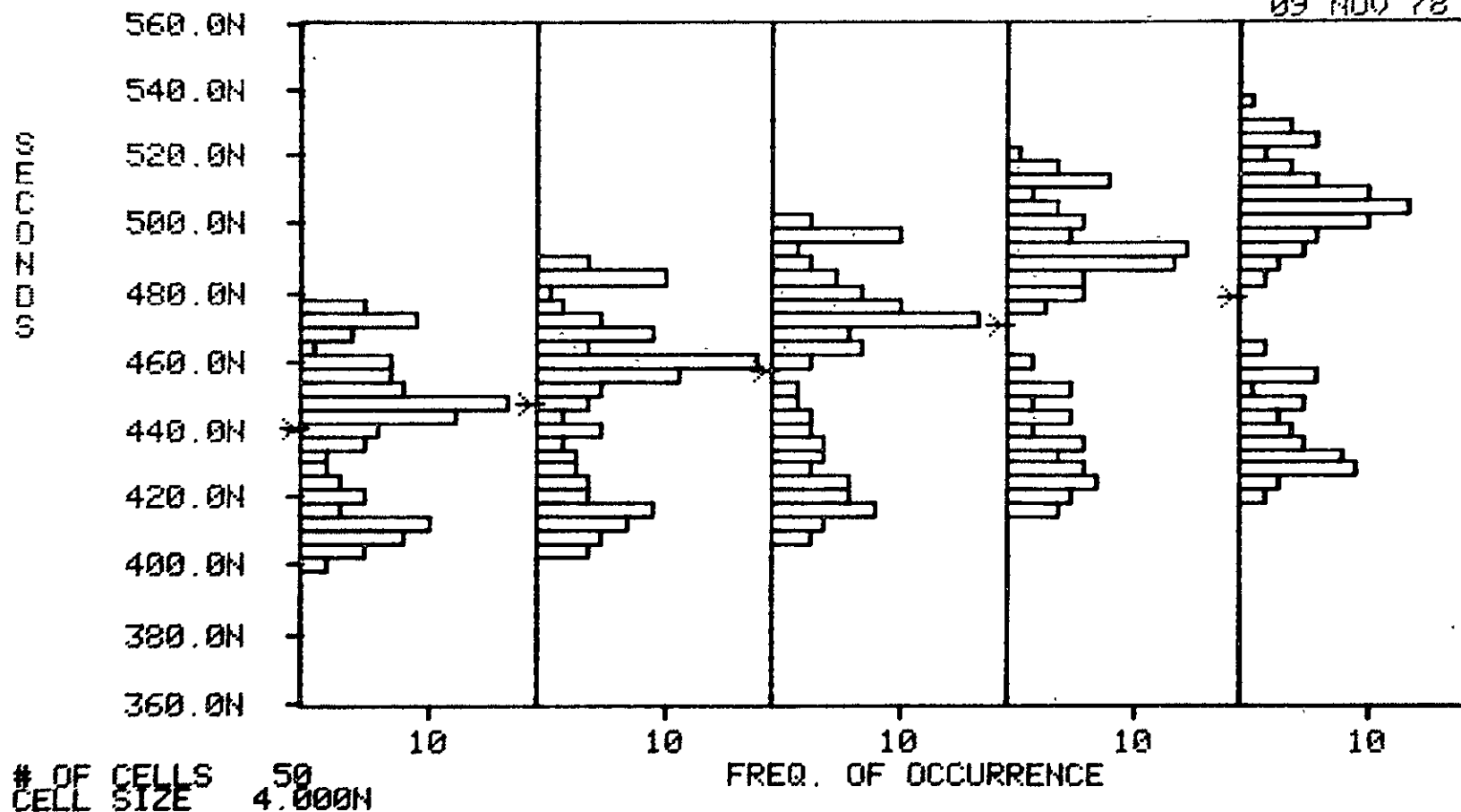
240
93.25N
59.89N
29.30N
18.11N

S-3260

DATA FOR TED46A

TED4/TED6 AT 50

09 NOV 78



READINGS:

MAXIMUM:

MEAN:

MINIMUM:

STD. DEV.:

120
477.5N
440.3N
401.0N
22.00N

120
488.0N
447.8N
403.0N
24.87N

120
500.5N
457.3N
406.5N
28.01N

120
519.5N
470.4N
414.5N
32.38N

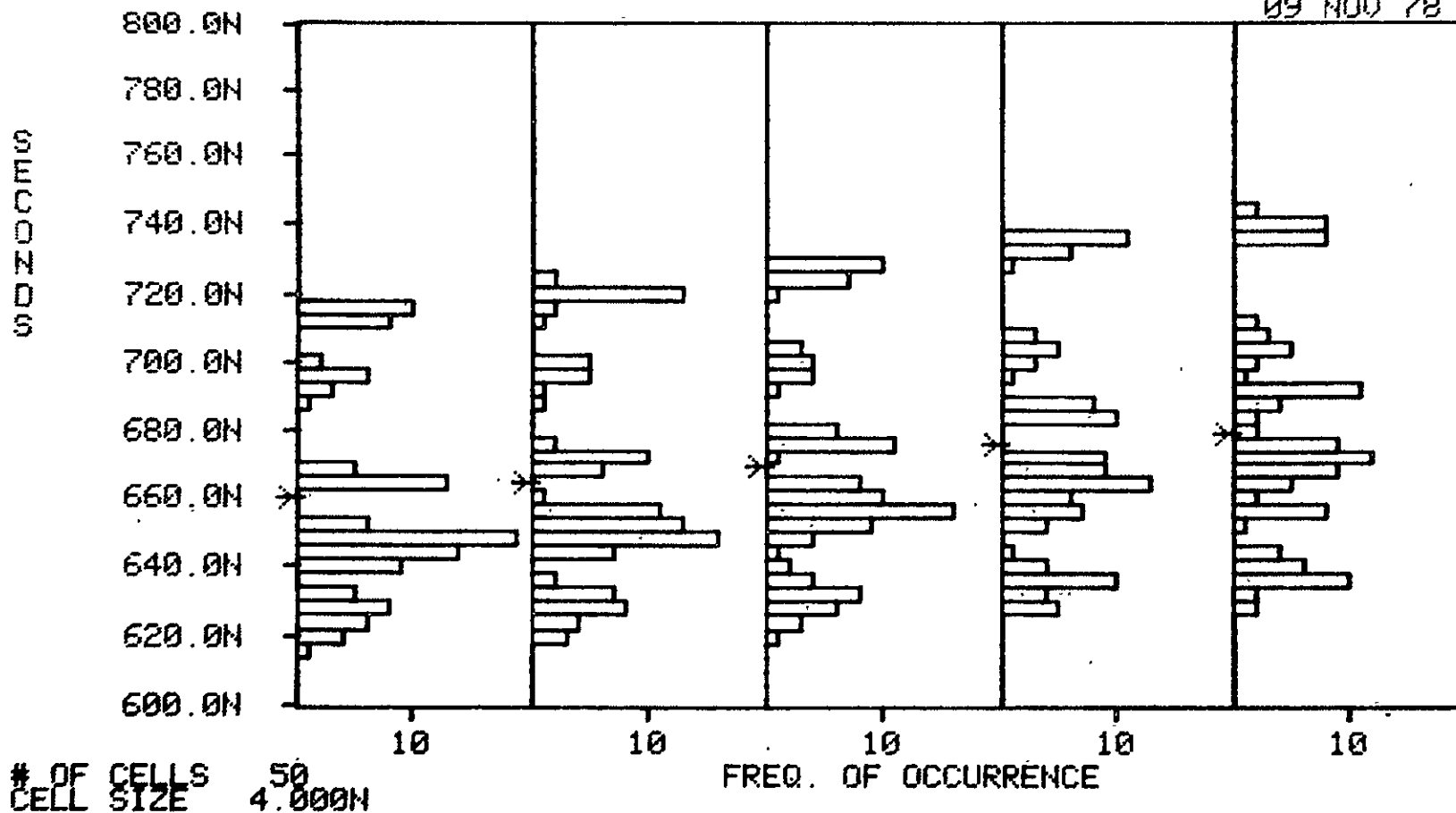
120
535.0N
479.0N
419.5N
35.47N

S-3260

DATA FOR TED46B

TED4/TED6 AT 10U

09 NOV 78



READINGS:

MAXIMUM:

MEAN:

MINIMUM:

STD. DEV.:

120
716.5N
659.7N
617.0N
30.01N

120
722.0N
663.9N
618.5N
30.55N

120
729.0N
668.9N
621.5N
31.08N

120
736.5N
675.3N
627.0N
32.12N

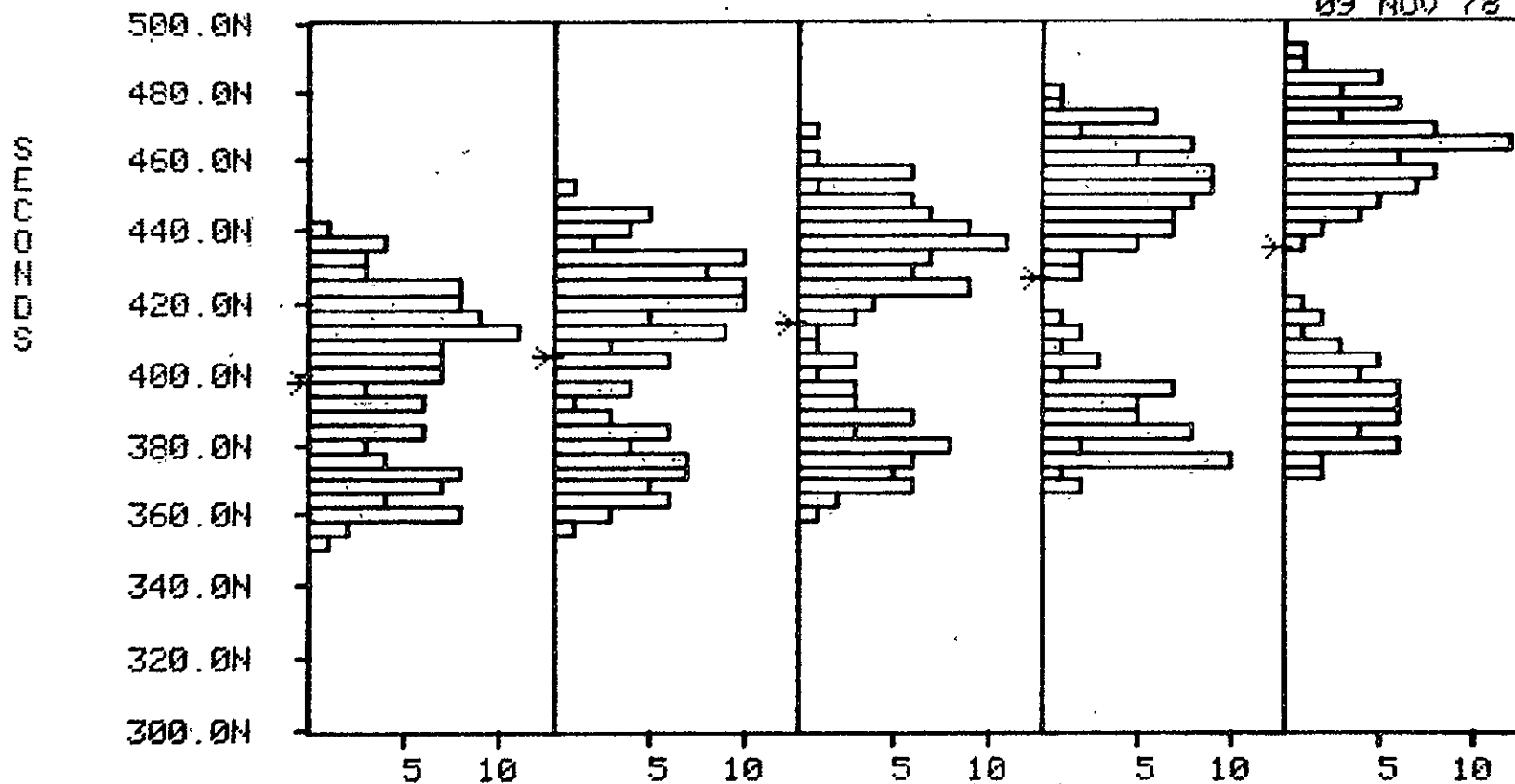
120
744.0N
679.4N
628.5N
32.59N

S-3260

DATA FOR TED57A

TED5/TED7 AT 5U

09 NOV 78

# OF CELLS
CELL SIZE50
4.000N

READINGS:
 MAXIMUM:
 MEAN:
 MINIMUM:
 STD. DEV.:

120
 441.5N
 397.6N
 352.5N
 23.82N

120
 453.0N
 404.7N
 356.5N
 26.16N

120
 466.5N
 414.3N
 360.5N
 29.57N

120
 481.0N
 426.6N
 366.0N
 33.81N

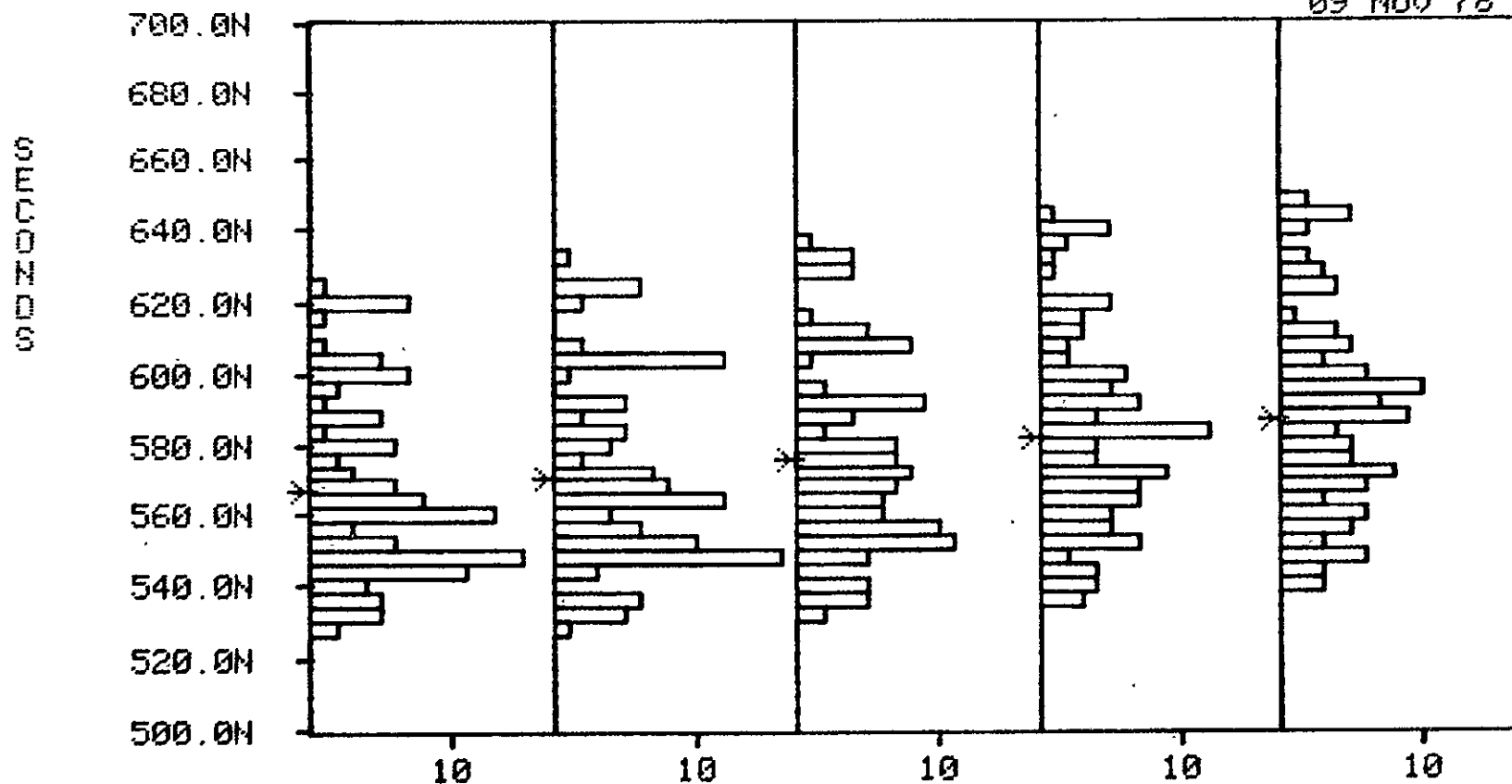
120
 490.0N
 434.8N
 370.5N
 36.38N

S-3260

DATA FOR TED57B

TED5/TED7 AT 10U

09 NOV 78

# OF CELLS
CELL SIZE50
4.000N

READINGS:
MAXIMUM:
MEAN:
MINIMUM:
STD. DEV.:

120
625.0N
566.5N
529.0N
25.59N

120
630.0N
570.1N
529.5N
25.92N

120
637.0N
575.4N
532.5N
26.59N

120
644.0N
582.2N
535.5N
27.29N

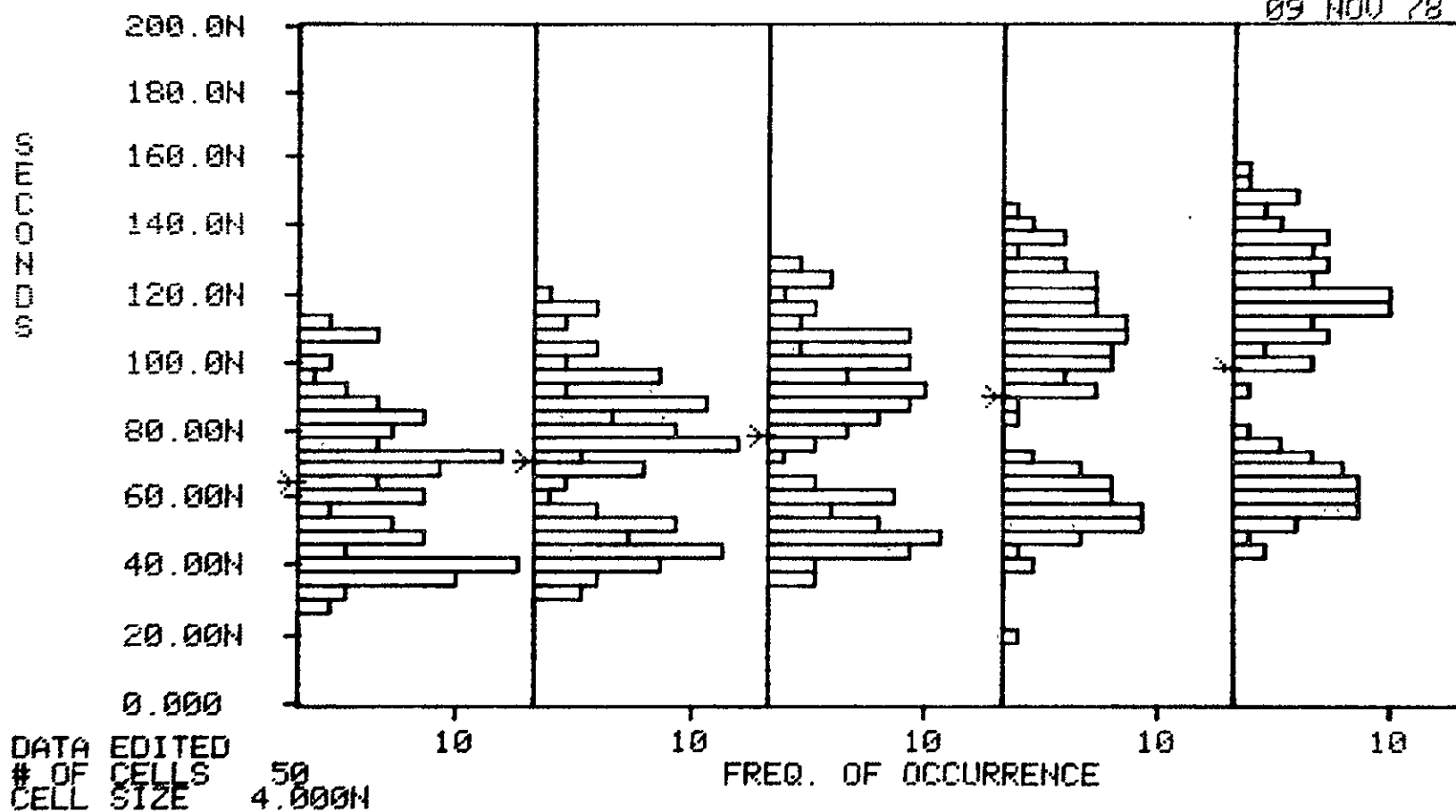
120
649.5N
587.2N
538.5N
28.11N

S-3260

DATA FOR TIB01A

TIB0.1 AT 50

09 NOV 78



READINGS:
MAXIMUM:
MEAN:
MINIMUM:
STD. DEV.:

120
112.0N
63.92N
28.60N
21.76N

120
119.0N
69.98N
31.45N
23.32N

120
129.5N
78.56N
35.45N
25.80N

120
145.0N
89.94N
20.00N
29.98N

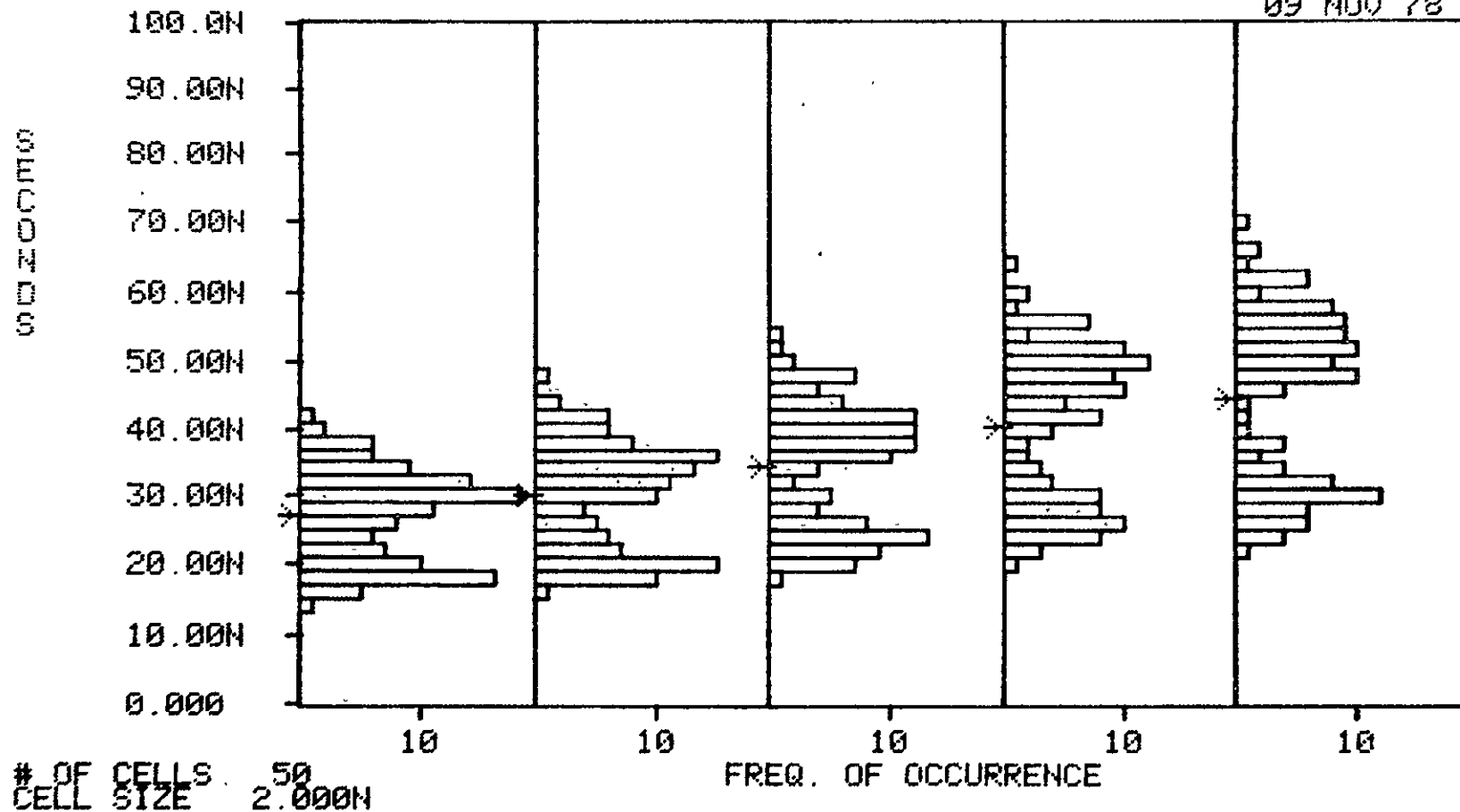
119
156.0N
98.46N
44.60N
31.96N

S-3260

DATA FOR TIB01B

TIB0.1 AT 100

09 NOV 78



READINGS:

MAXIMUM:

MEAN:

MINIMUM:

STD. DEV.:

120

41.80N

26.96N

14.95N

6.760N

120

47.10N

29.98N

16.10N

7.791N

120

53.80N

34.29N

17.95N

9.256N

120

63.35N

40.36N

20.40N

11.27N

120

69.75N

44.59N

22.25N

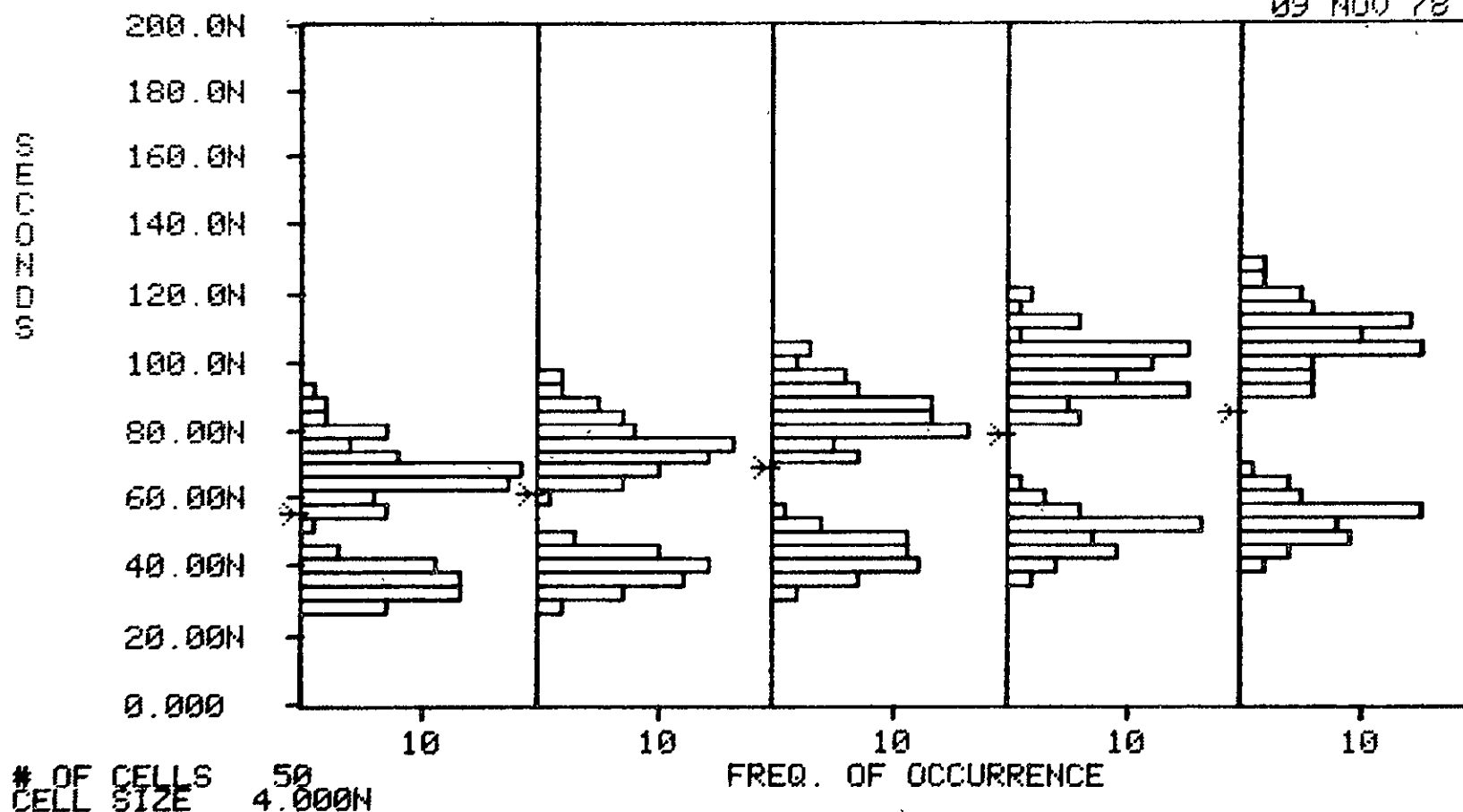
12.59N

S-3260

DATA FOR TB001A

TB00.1 AT 50

09 NOV 78

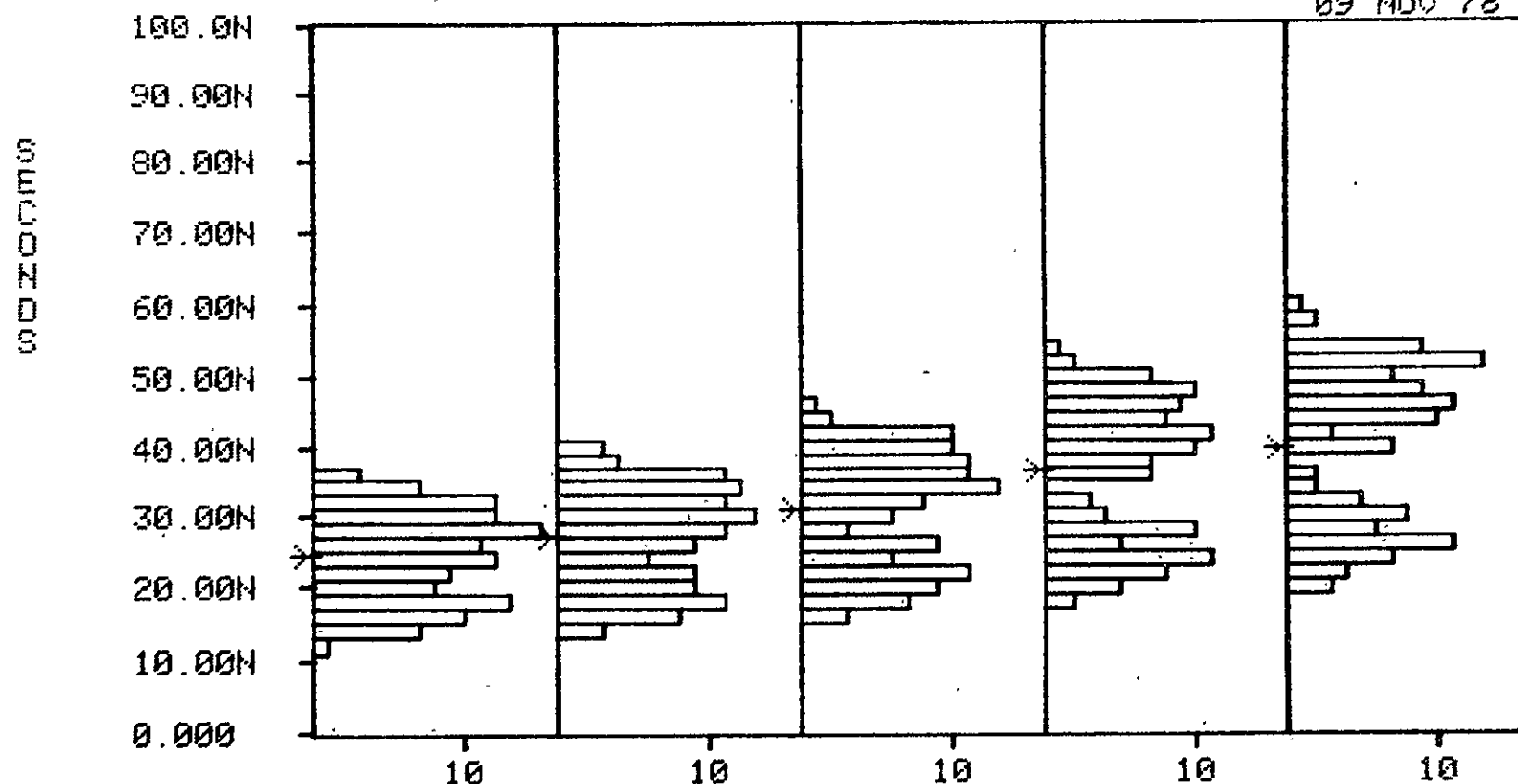


READINGS:	120	120	120	120	120
MAXIMUM:	90.85N	96.30N	105.5N	118.5N	127.5N
MEAN:	55.40N	60.75N	68.38N	78.69N	85.74N
MINIMUM:	26.25N	28.45N	31.80N	36.65N	39.80N
STD. DEV.:	17.57N	19.40N	21.78N	25.13N	27.56N

S-3260 DATA FOR TB001B

TB00.1 AT 10V

09 NOV 78



OF CELLS
CELL SIZE 50 2.000N

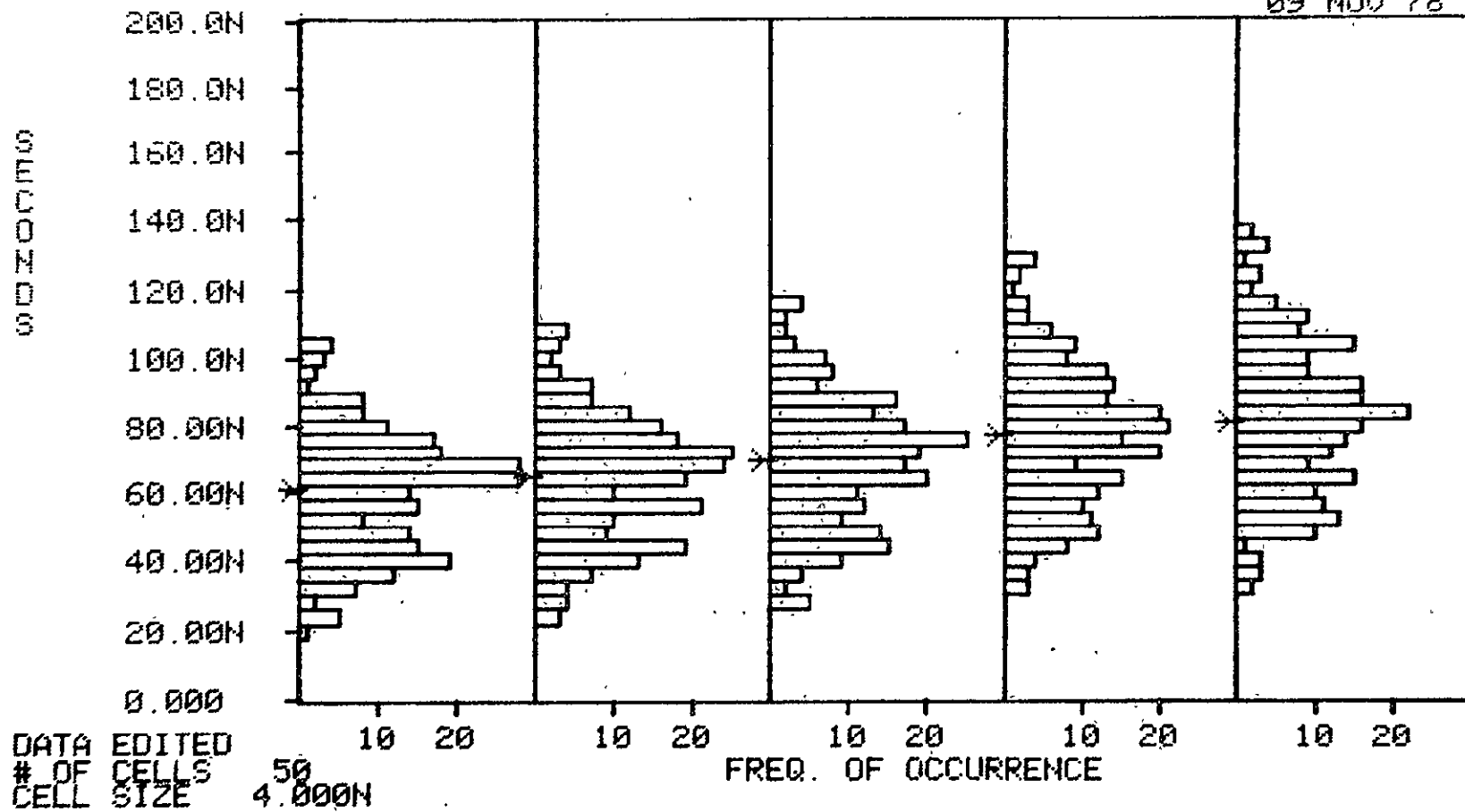
FREQ. OF OCCURRENCE

READINGS:	120	120	120	120	120
MAXIMUM:	35.90N	40.00N	46.05N	53.60N	59.25N
MEAN:	24.46N	27.10N	30.87N	36.10N	39.79N
MINIMUM:	12.70N	13.90N	15.45N	18.00N	19.65N
STD. DEV.:	6.135N	7.035N	8.222N	10.01N	11.18N

S-3260 DATA FOR TTA

TTLH/TTHL AT 5U

09 NOV 78



DATA EDITED
OF CELLS
CELL SIZE

50
4.000N

FREQ. OF OCCURRENCE

READINGS:
MAXIMUM:
MEAN:
MINIMUM:
STD. DEV.:

240
105.2N
60.85N
21.85N
17.88N

240
109.9N
64.28N
23.45N
18.46N

240
117.5N
69.27N
26.60N
19.41N

239
128.2N
76.47N
30.10N
21.08N

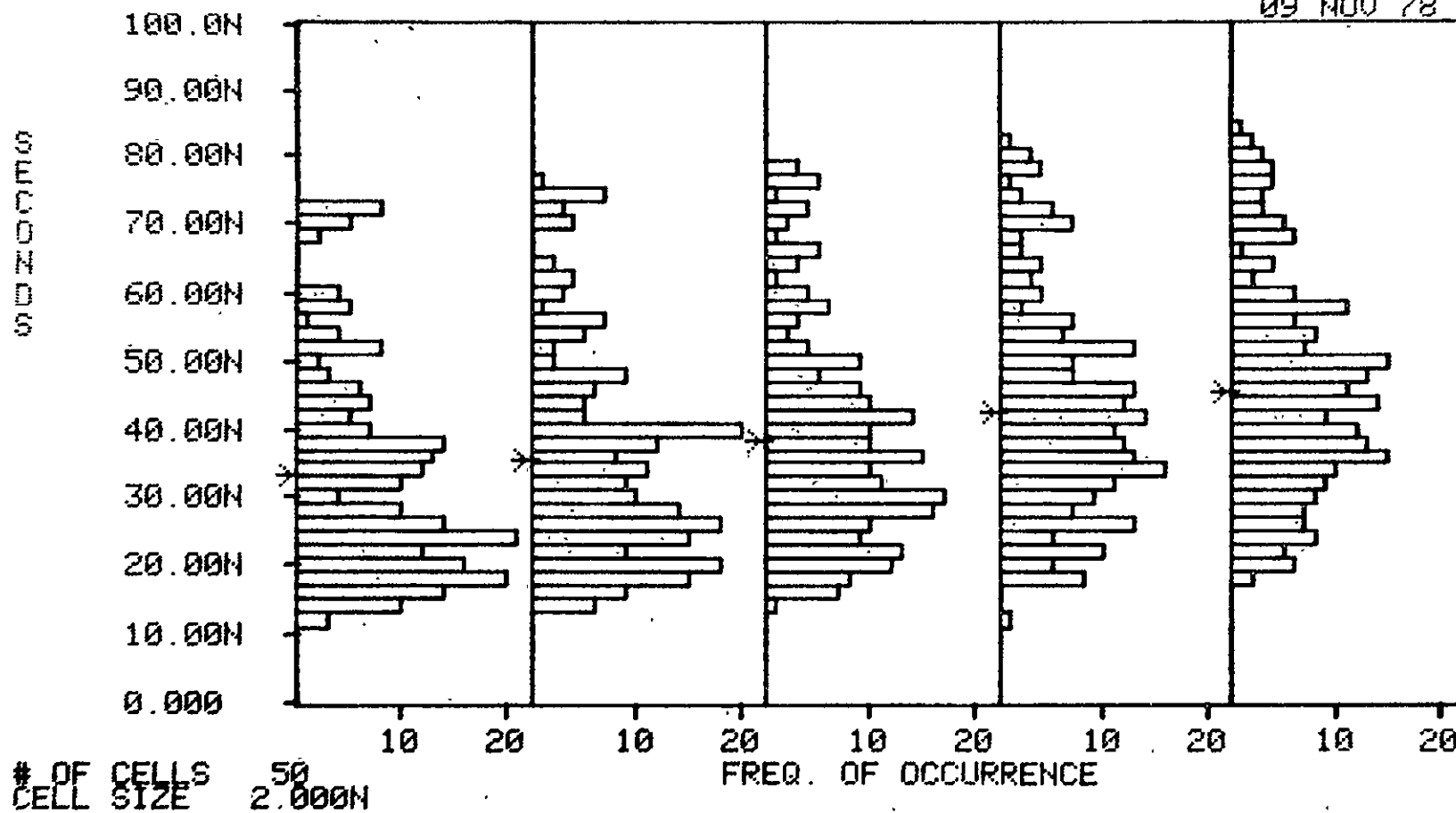
240
136.3N
81.31N
33.25N
22.50N

S-3260

DATA FOR TTB

TTLH/TTHL AT 10U

09 NOV 78



READINGS:

MAXIMUM:

MEAN:

MINIMUM:

STD. DEV.:

240

72.60N

33.06N

12.55N

15.45N

240

75.30N

35.29N

13.20N

15.54N

240

78.90N

38.39N

14.95N

15.57N

240

81.45N

42.59N

12.20N

15.61N

240

83.70N

45.64N

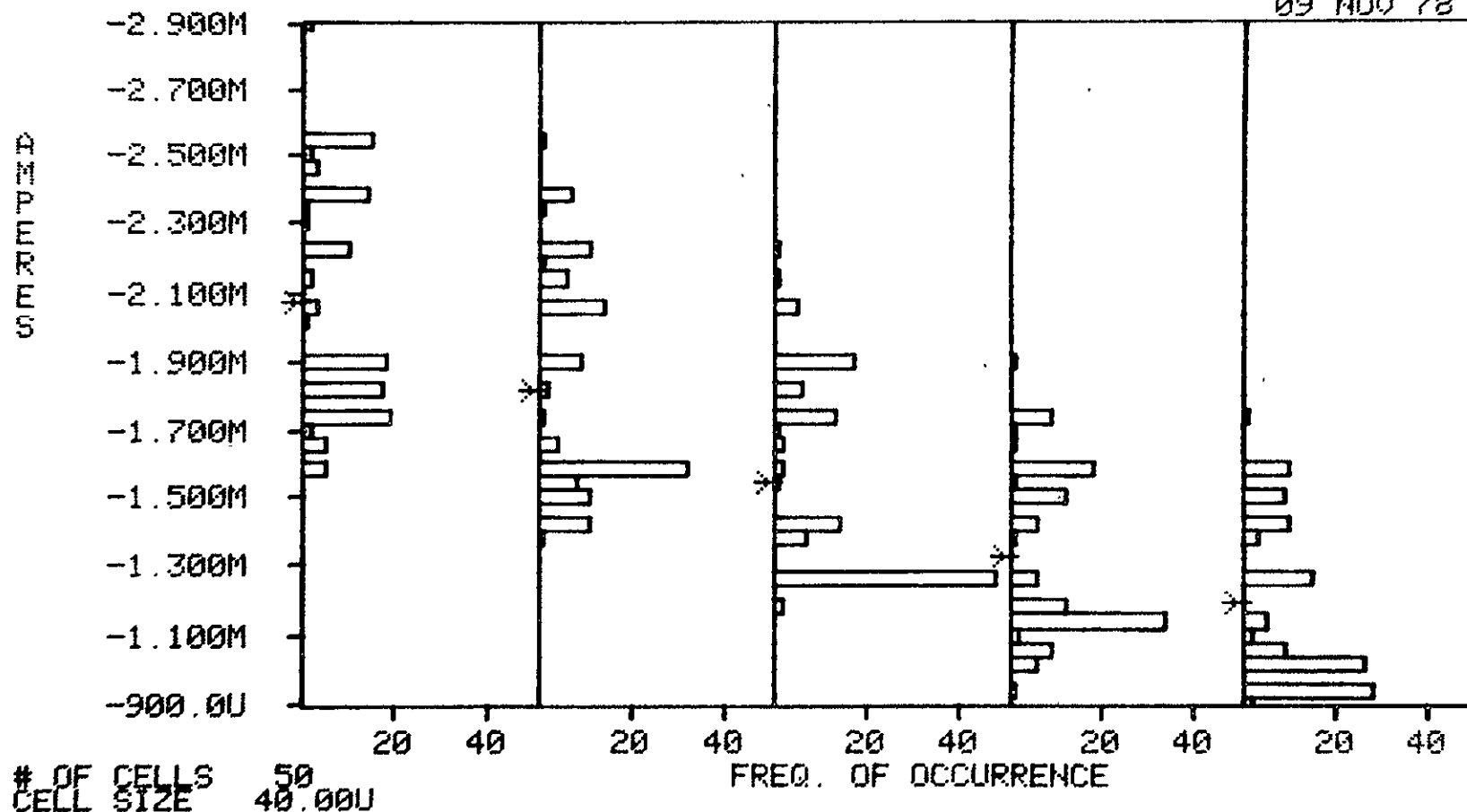
18.60N

15.51N

S-3260 DATA FOR IOH1

IOH: UDD=5U UO=4 6U

09 NOV 78

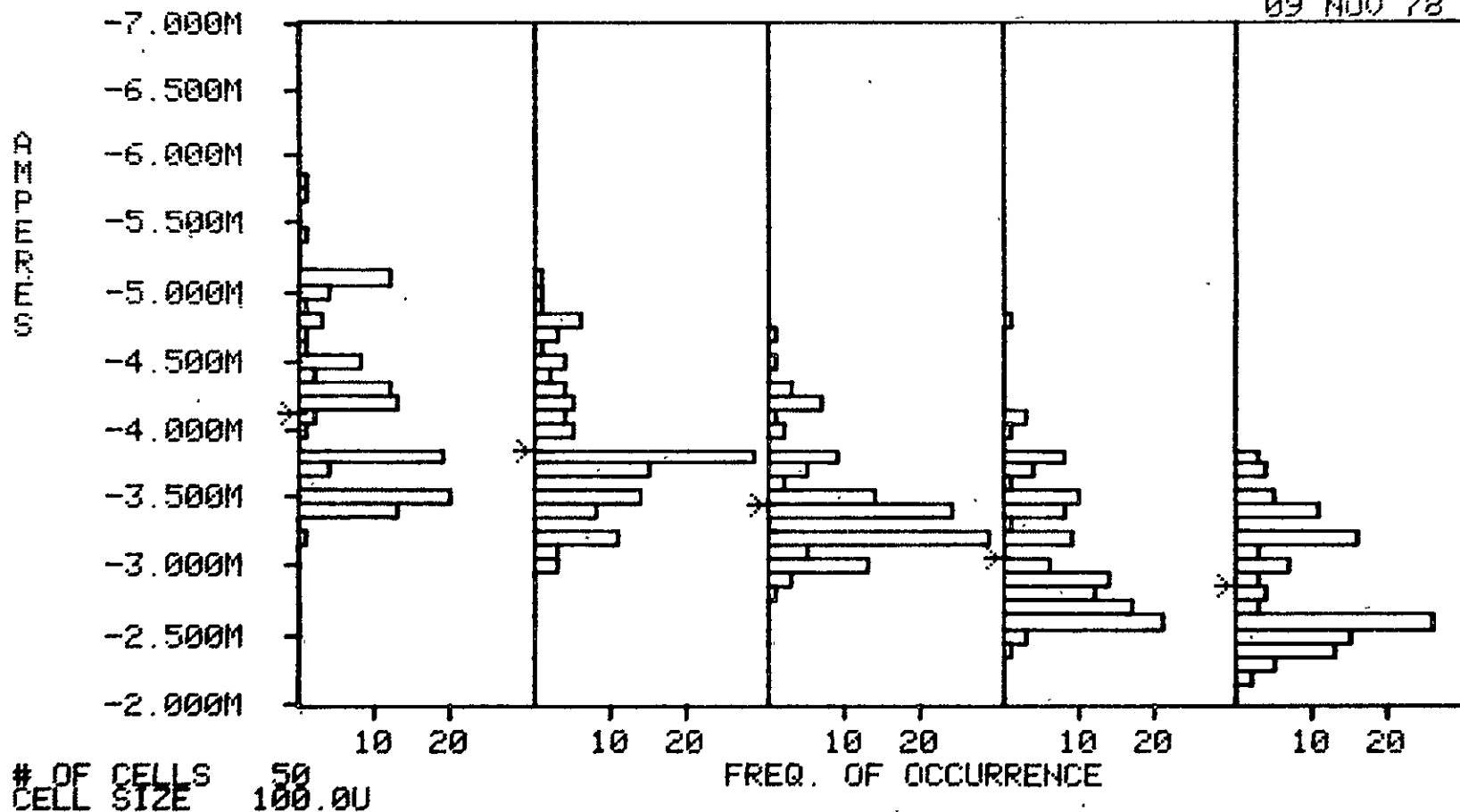


READINGS:	120	120	120	120	120
MAXIMUM:	-1.600M	-1.400M	-1.200M	-960.0U	-920.0U
MEAN:	-2.074M	-1.814M	-1.540M	-1.324M	-1.187M
MINIMUM:	-2.880M	-2.560M	-2.240M	-1.920M	-1.760M
STD. DEV.:	331.9U	316.8U	287.4U	246.2U	229.2U

S-3260 DATA FOR IOH3

IOH: VDD=10V VO=9.5V

09 NOV 78

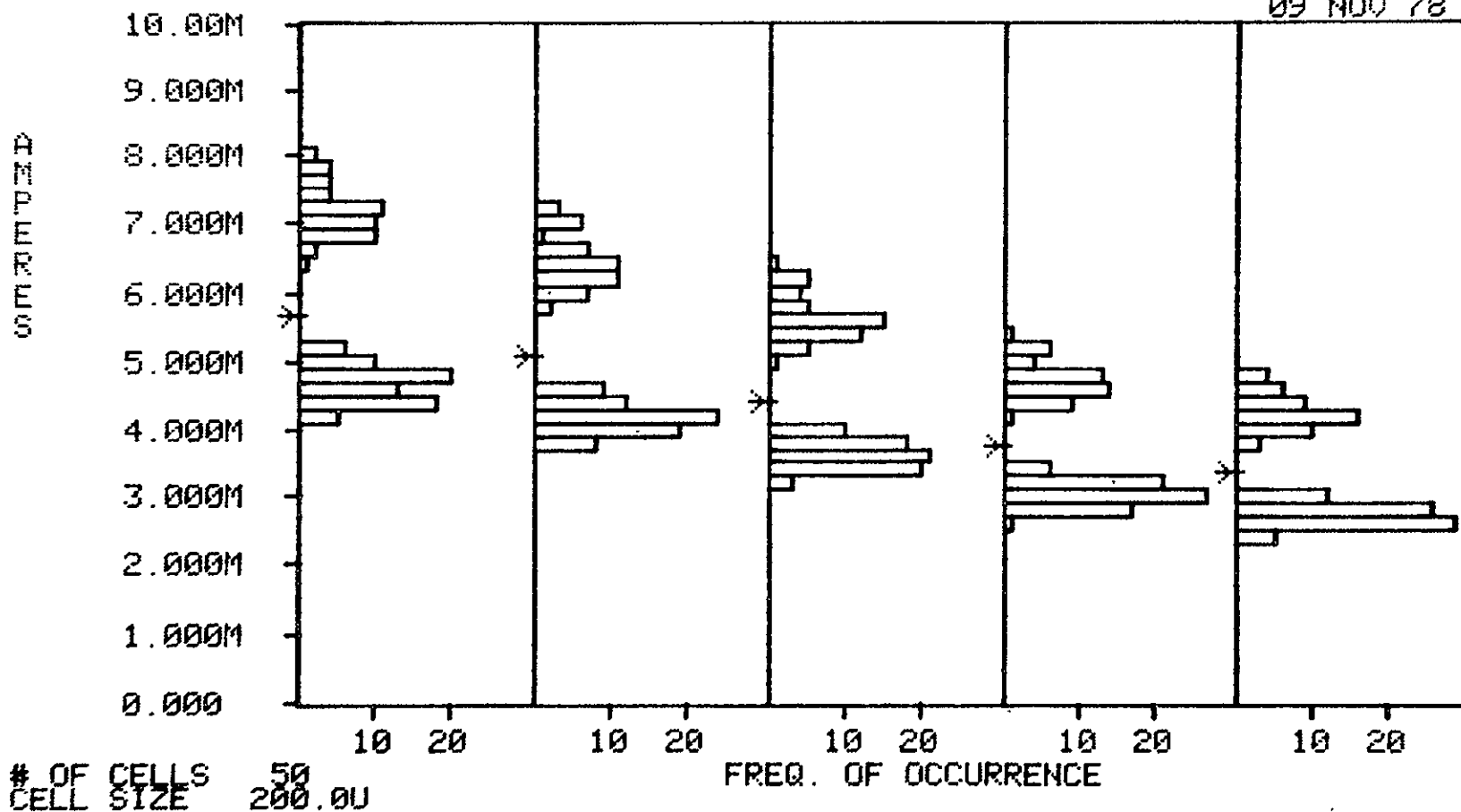


READINGS:	120	120	120	120	120
MAXIMUM:	-3.200M	-3.040M	-2.800M	-2.400M	-2.200M
MEAN:	-4.124M	-3.831M	-3.443M	-3.052M	-2.848M
MINIMUM:	-5.760M	-5.120M	-4.720M	-4.800M	-3.760M
STD. DEV.:	602.5U	488.0U	382.7U	470.8U	429.9U

S-3260 DATA FOR IOL1

IOL: UDD=5U U0=0.4U

09 NOV 78

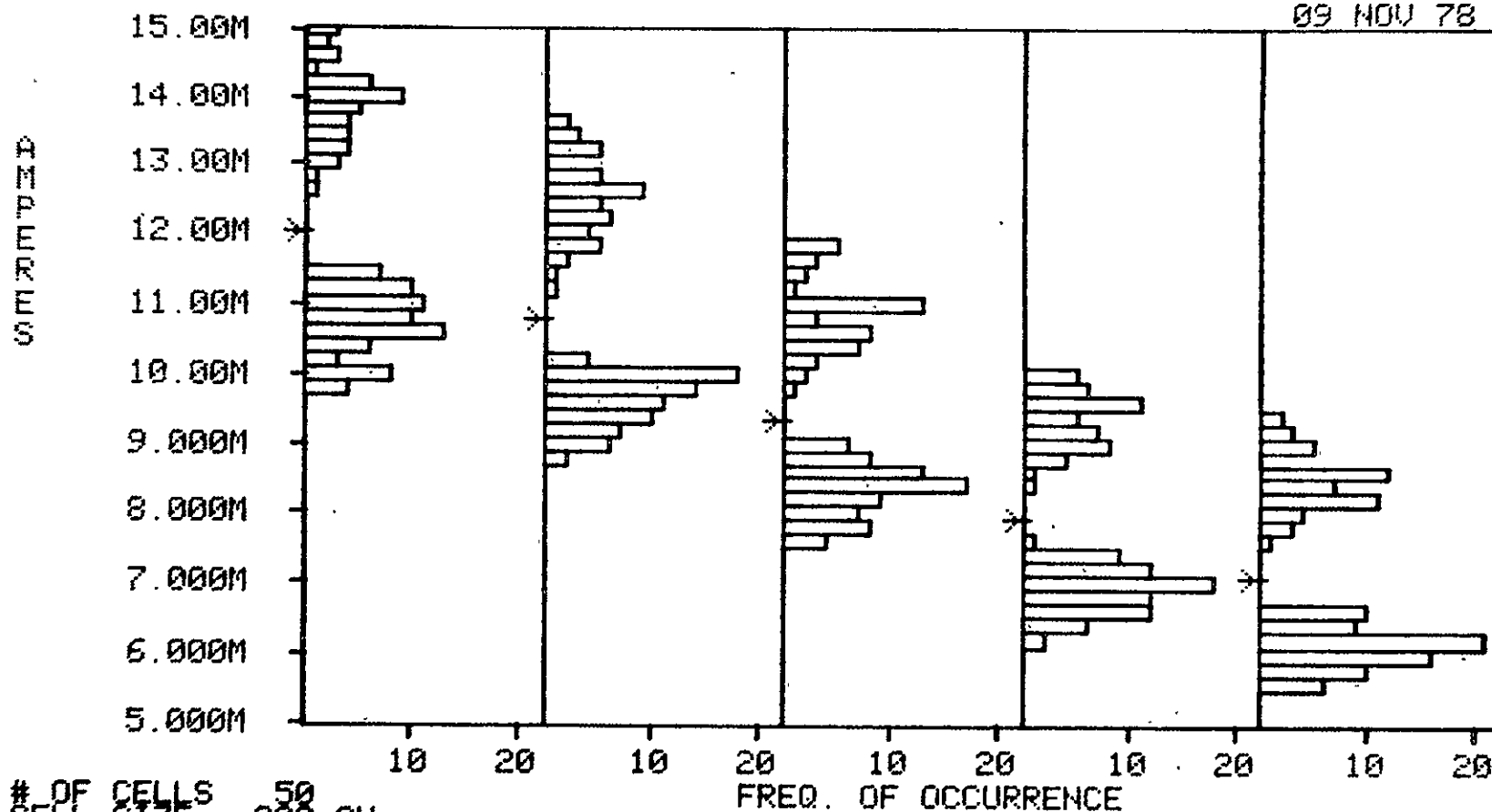


READINGS:	120	120	120	120	120
MAXIMUM:	8.020M	7.280M	6.400M	5.375M	4.630M
MEAN:	5.670M	5.088M	4.425M	3.722M	3.335M
MINIMUM:	4.160M	3.725M	3.215M	2.695M	2.380M
STD. DEV.:	1.257M	1.152M	1.018M	866.7U	786.6U

S-3260 DATA FOR IOL3

IOL: UDD=10V UO=0.5V

09 NOV 78



OF CELLS 50
 CELL SIZE 200.0U
 DATA OUTSIDE= '+'
 READINGS:
 MAXIMUM:
 MEAN:
 MINIMUM:
 STD. DEV.:

120
 15.10M
 11.99M
 9.750M
 1.672M

120
 13.55M
 10.77M
 8.870M
 1.463M

120
 11.85M
 9.349M
 7.580M
 1.308M

120
 10.05M
 7.906M
 6.280M
 1.268M

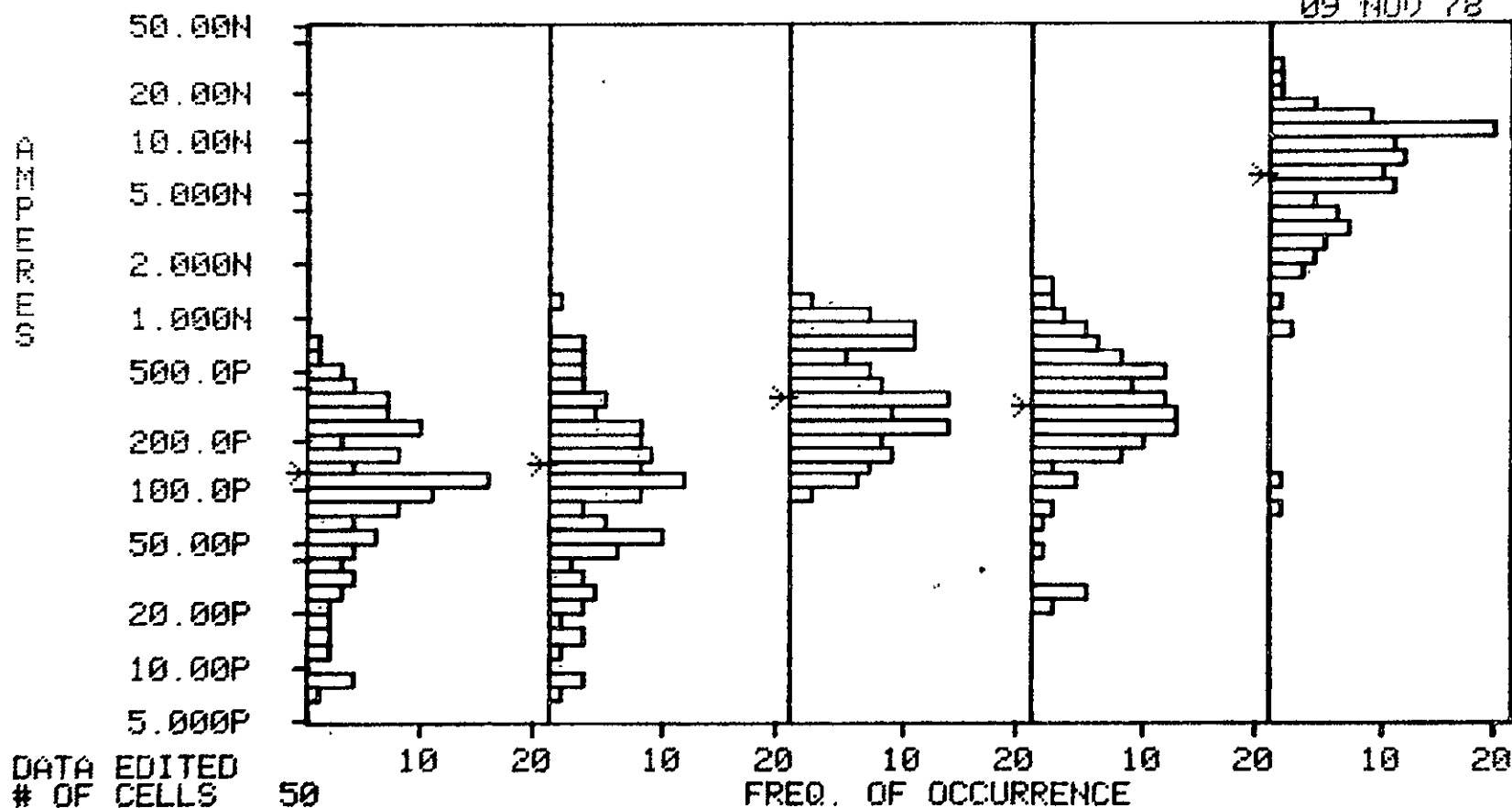
120
 9.330M
 7.065M
 5.540M
 1.207M

S-3260

DATA FOR IOZ1

IOZ. UDD=130 UO=130

09 NOV 78



READINGS:
MAXIMUM:
MEAN:
MINIMUM:
STD.DEV.:

120
585.0P
124.4P
6.157P
111.7P

120
986.2P
139.1P
6.337P
151.7P

120
960.6P
351.5P
72.23P
237.9P

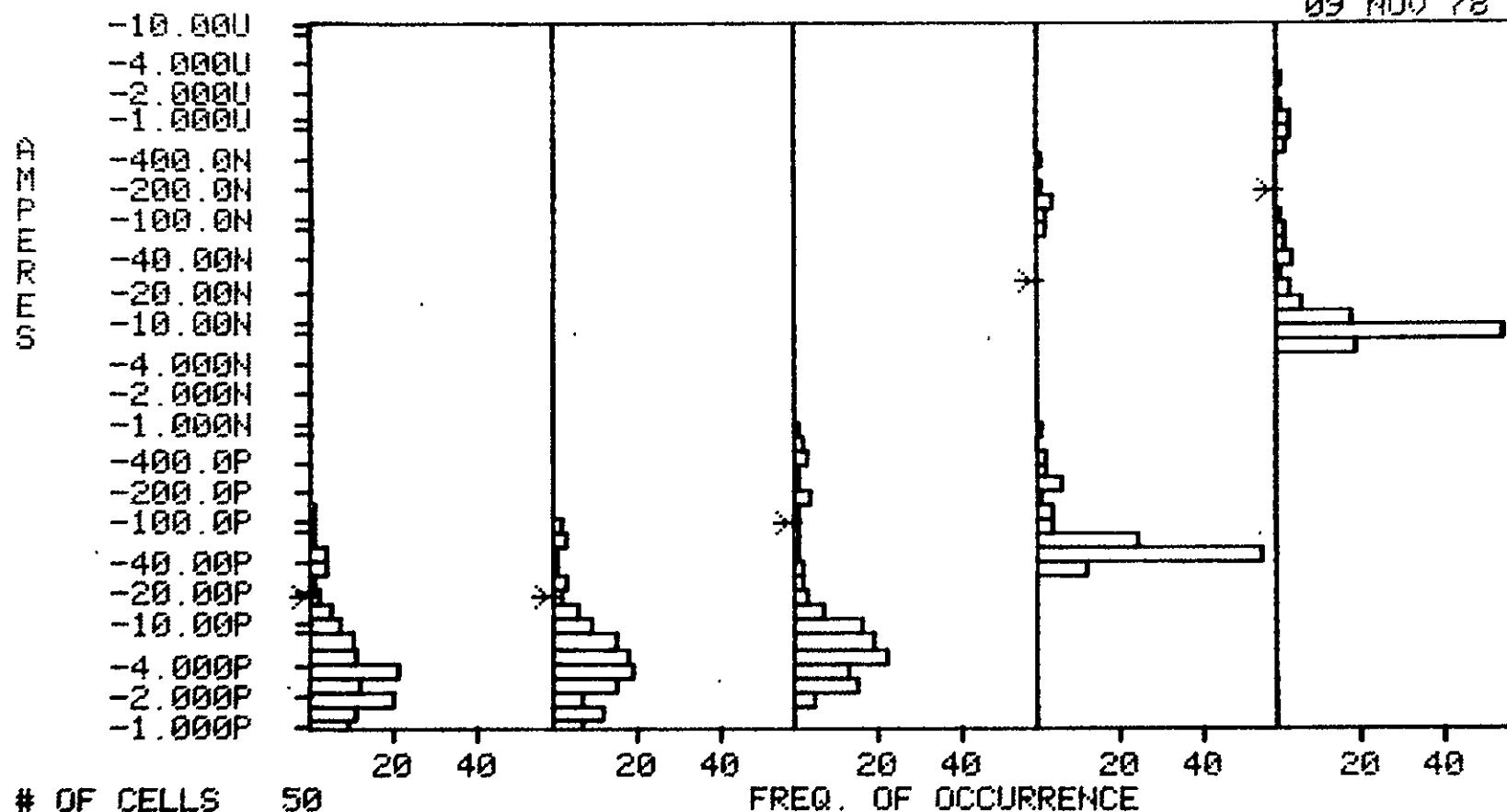
120
1.229N
315.8P
16.00P
239.1P

114
21.51N
6.334N
66.67P
3.843N

S-3260 DATA FOR 1022

102: UDD=13U UD=0U

09 NOV 78

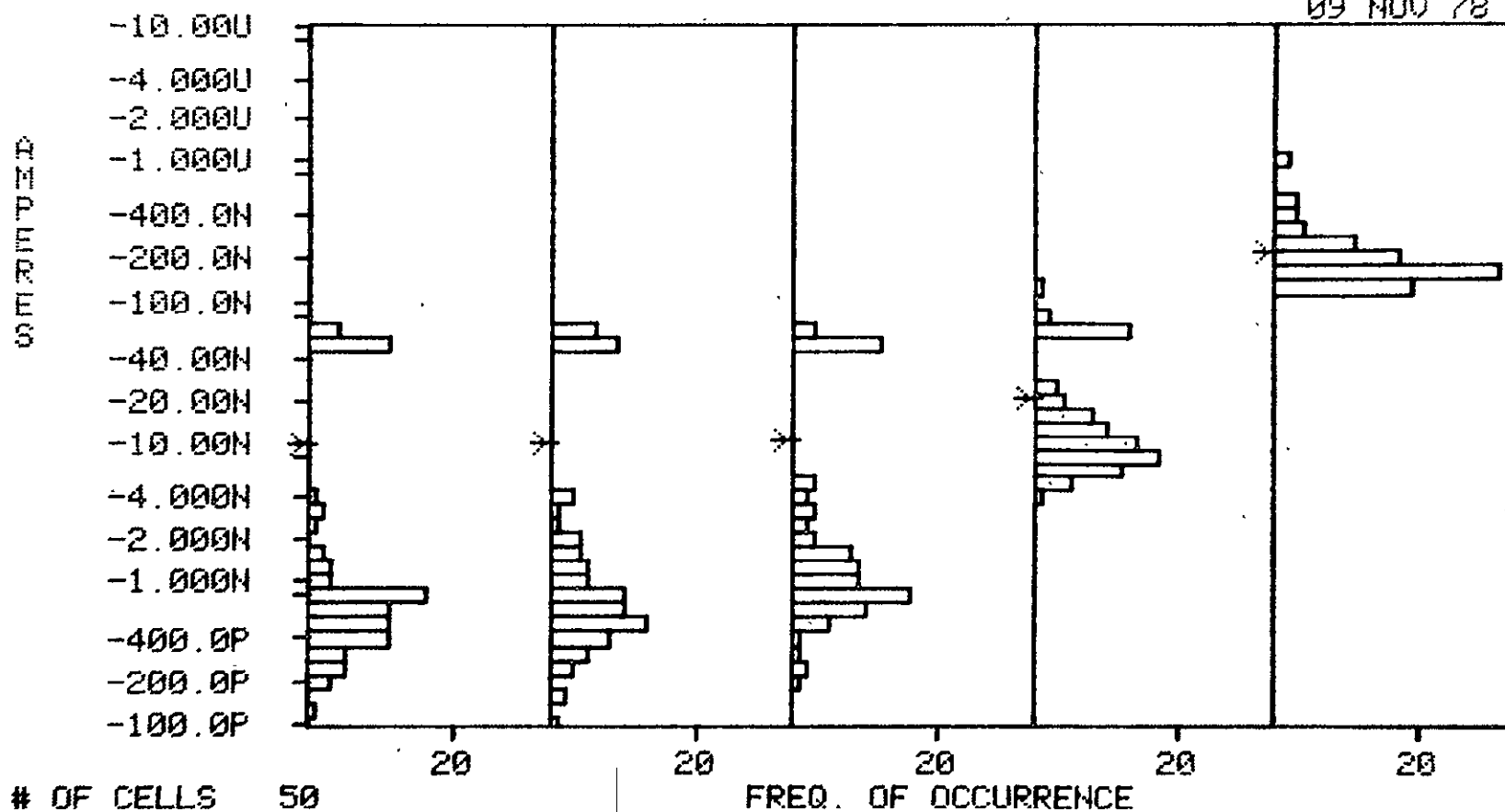


READINGS:	120	120	120	120	120
MAXIMUM:	-1.893P	-1.833P	-4.020P	-64.67P	-11.65N
MEAN:	-18.43P	-18.31P	-97.14P	-25.63N	-196.4N
MINIMUM:	-247.0P	-212.7P	-2.024N	-744.5N	-4.690U
STD. DEV.:	34.76P	33.18P	279.0P	97.24N	627.5N

S-3260 DATA FOR ISSA

ISS UDD=100

09 NOV 78

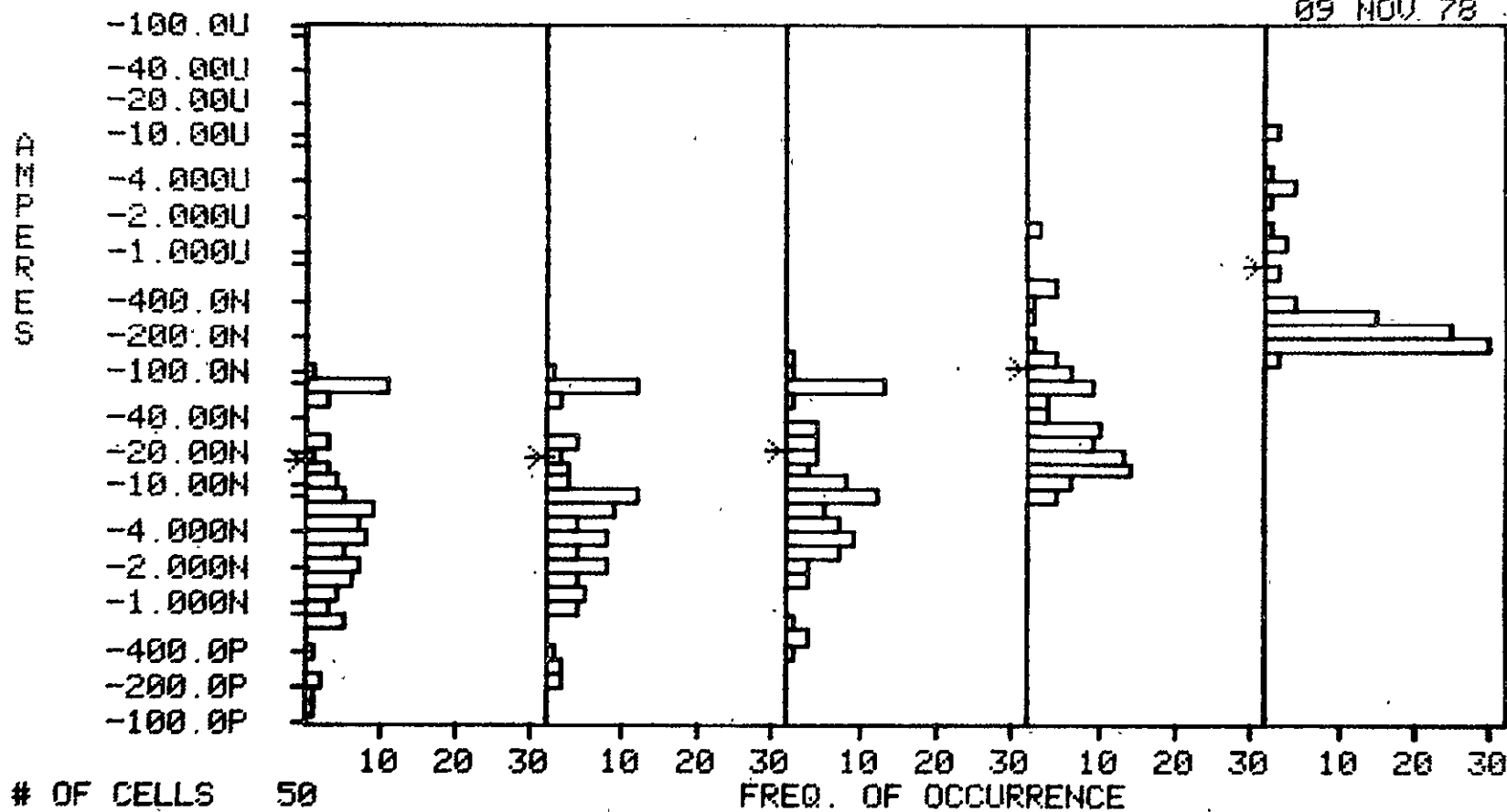


READINGS:	90	90	90	90	90
MAXIMUM:	-137.5P	-100.0P	-225.0P	-4.500N	-117.0N
MEAN:	-9.885N	-10.07N	-10.41N	-20.87N	-218.9N
MINIMUM:	-58.50N	-60.00N	-62.50N	-114.5N	-1.130U
STD. DEV.:	20.55N	20.60N	20.43N	22.90N	157.2N

S-3260 DATA FOR ISSB

ISS: UDD=13U

09 NOV 78



READINGS:	90	90	90	90	90
MAXIMUM:	-125.0P	-212.5P	-387.5P	-7.550N	-146.5N
MEAN:	-16.25N	-17.42N	-21.31N	-109.0N	-771.9N
MINIMUM:	-92.00N	-99.50N	-116.5N	-1.725U	-11.80U
STD. DEV.:	25.38N	25.81N	28.00N	273.3N	1.883U

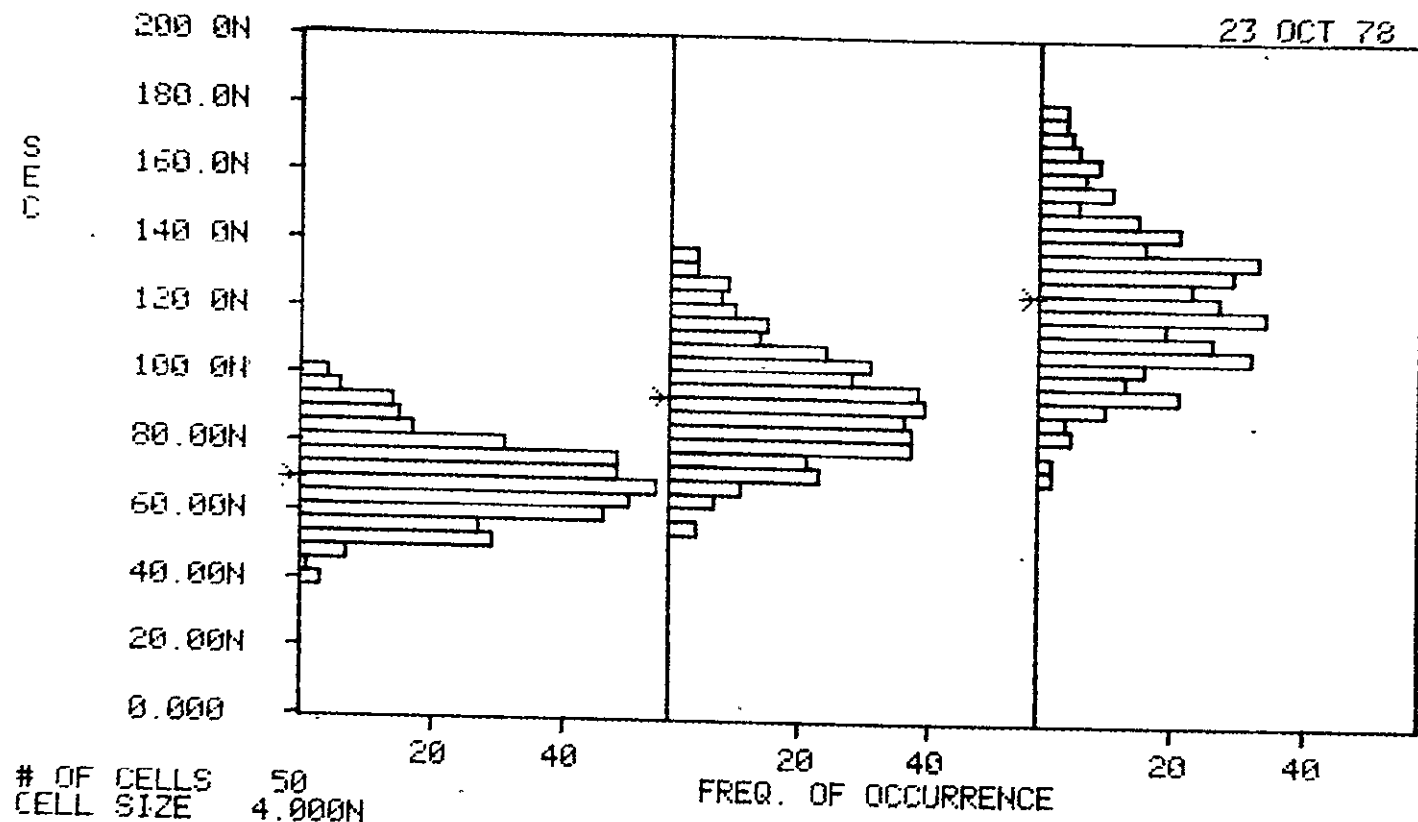
STANDARD DEVICES

S-3260

DATA FOR TEB03H

TEB0.1,2,3 AT 5U

23 OCT 78



OF CELLS 50
CELL SIZE 4.000N

READINGS:

MAXIMUM: 400

MEAN: 99.85N

MINIMUM: 69.25N

STD. DEV: 41.25N

11.66N

400

137.0N

93.65N

55.15N

16.33N

400

179.5N

125.3N

73.05N

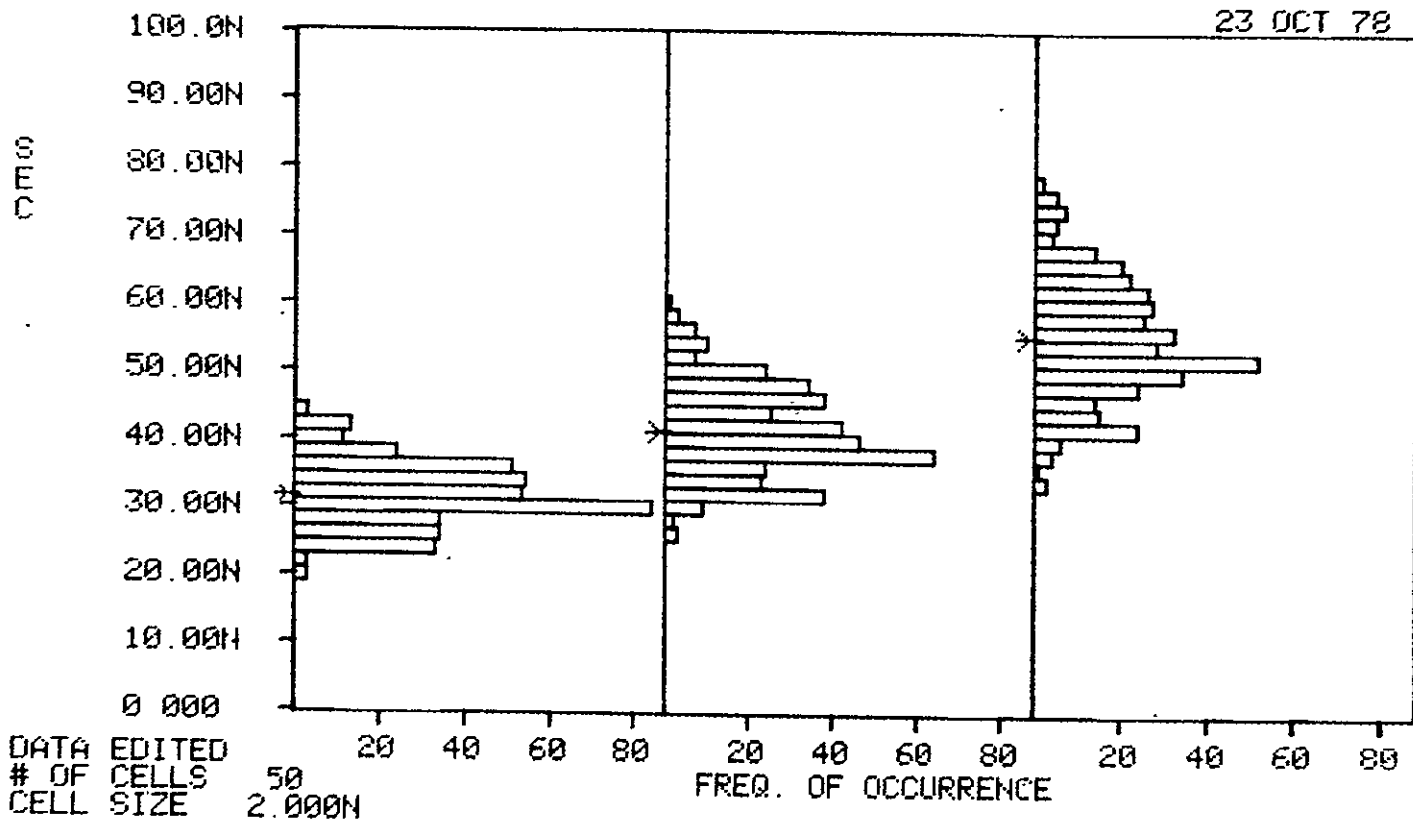
21.80N

S-3260

DATA FOR TEB03B

TEB0.1,2,3 AT 10V

23 OCT 78



READINGS:

MAXIMUM:

MEAN:

MINIMUM:

STD. DEV.:

400

44.35N

31.63N

20.25N

4.778N

400

59.05N

41.26N

26.00N

6.610N

394

77.20N

55.21N

33.95N

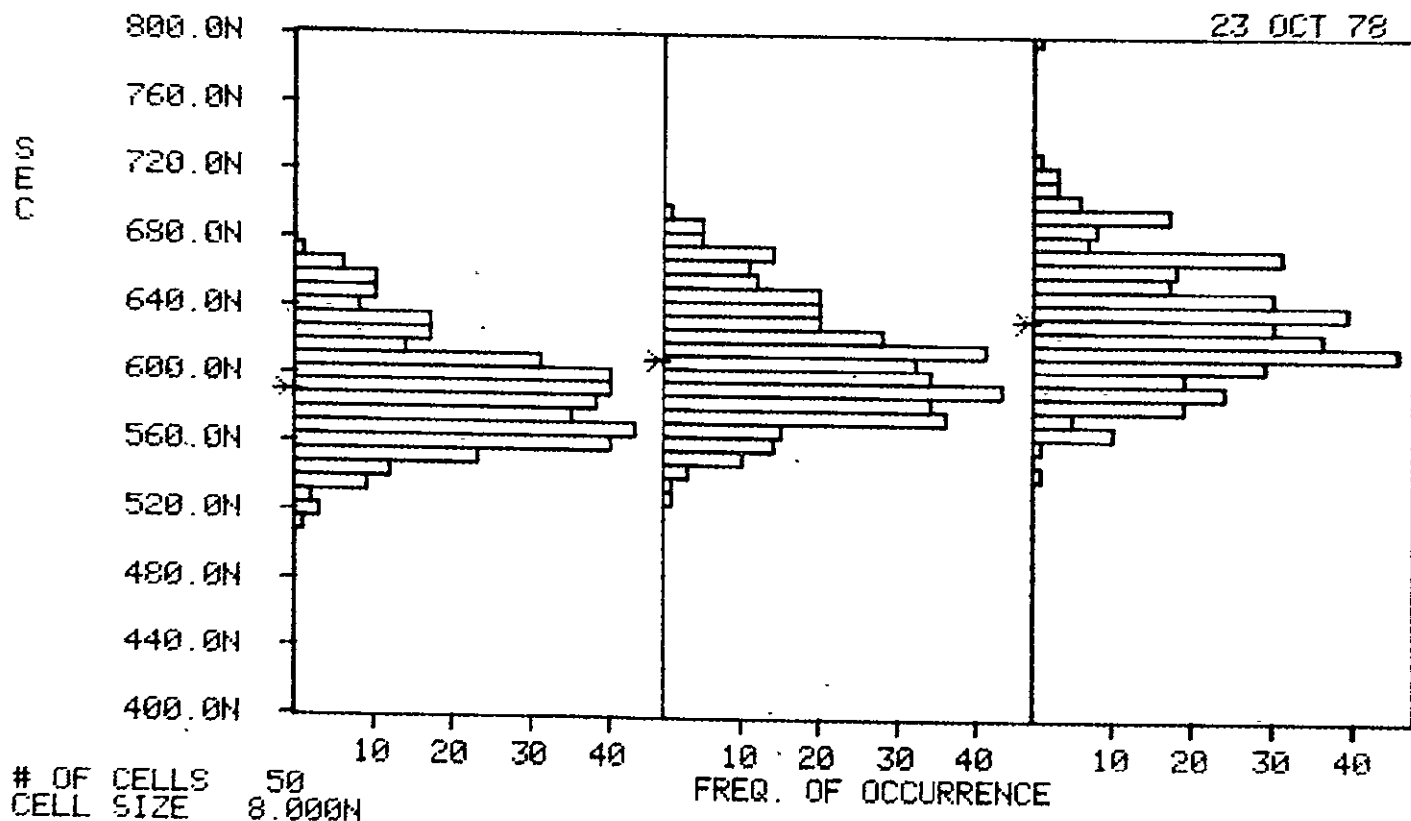
8.795N

S-3260

DATA FOR TEB47A

TEB4,5,6,7 AT 50

23 OCT 78



READINGS:

MAXIMUM:

MEAN:

MINIMUM:

STD. DEV.:

400
672.0N
588.8N
512.0N
31.23N

400
699.5N
609.0N
527.0N
33.28N

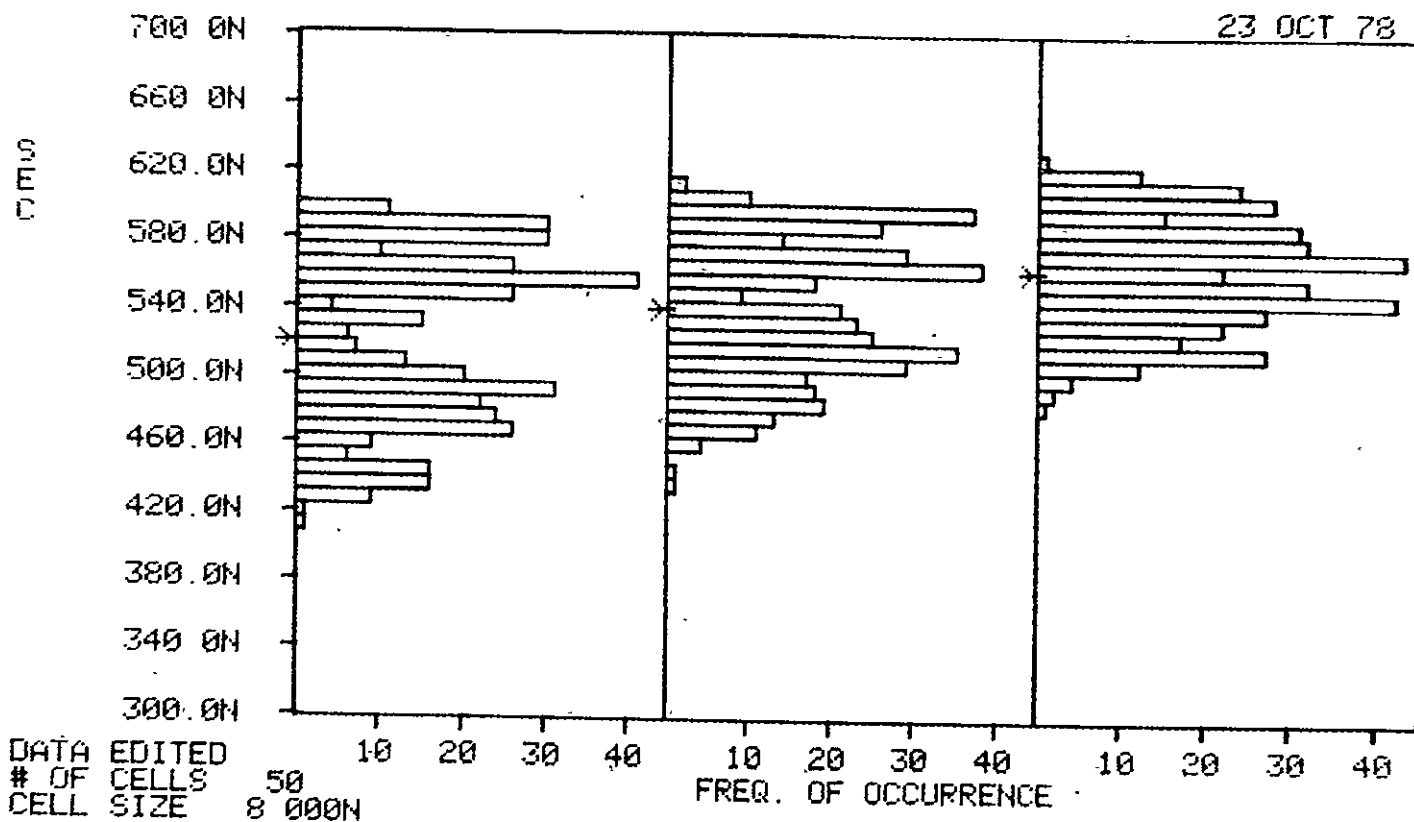
400
796.5N
633.8N
544.0N
35.48N

S-3260

DATA FOR TEB47B

TEB4,5,6,7 AT 10U

23 OCT 78



READINGS:

MAXIMUM

MEAN:

MINIMUM

STD. DEV

400

597.5N

518.8N

413.5N

50.21N

400

612.0N

539.1N

435.0N

40.34N

394

624.0N

562.8N

487.0N

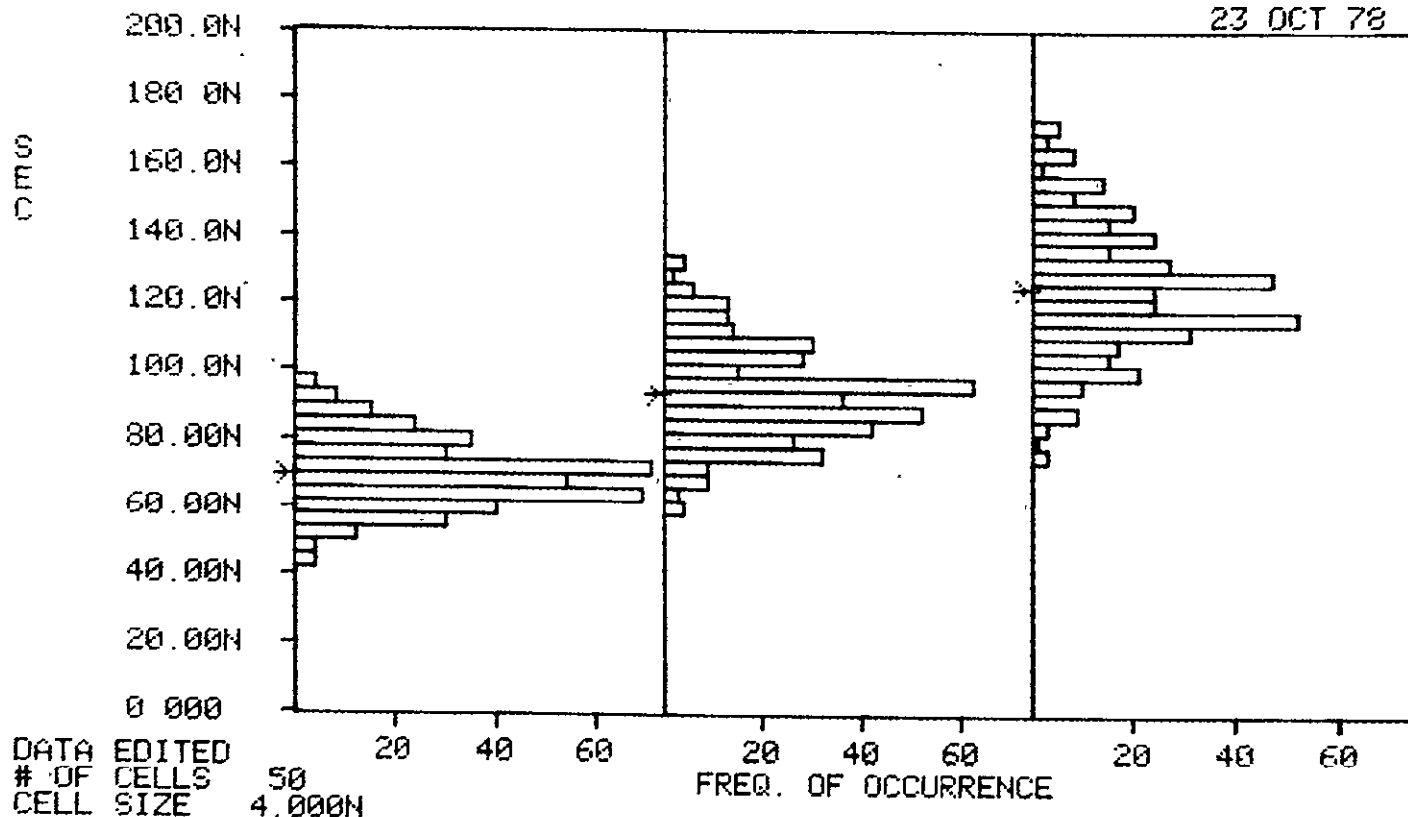
31.62N

S-3260

DATA FOR TED03A

TED0.1,2,3 AT 5V

23 OCT 78



READINGS:

MAXIMUM:

MEAN:

MINIMUM:

STD. DEV.:

400

95.80N

69.43N

43.45N

10.16N

400

131.0N

93.31N

58.10N

14.27N

398

170.5N

124.6N

76.55N

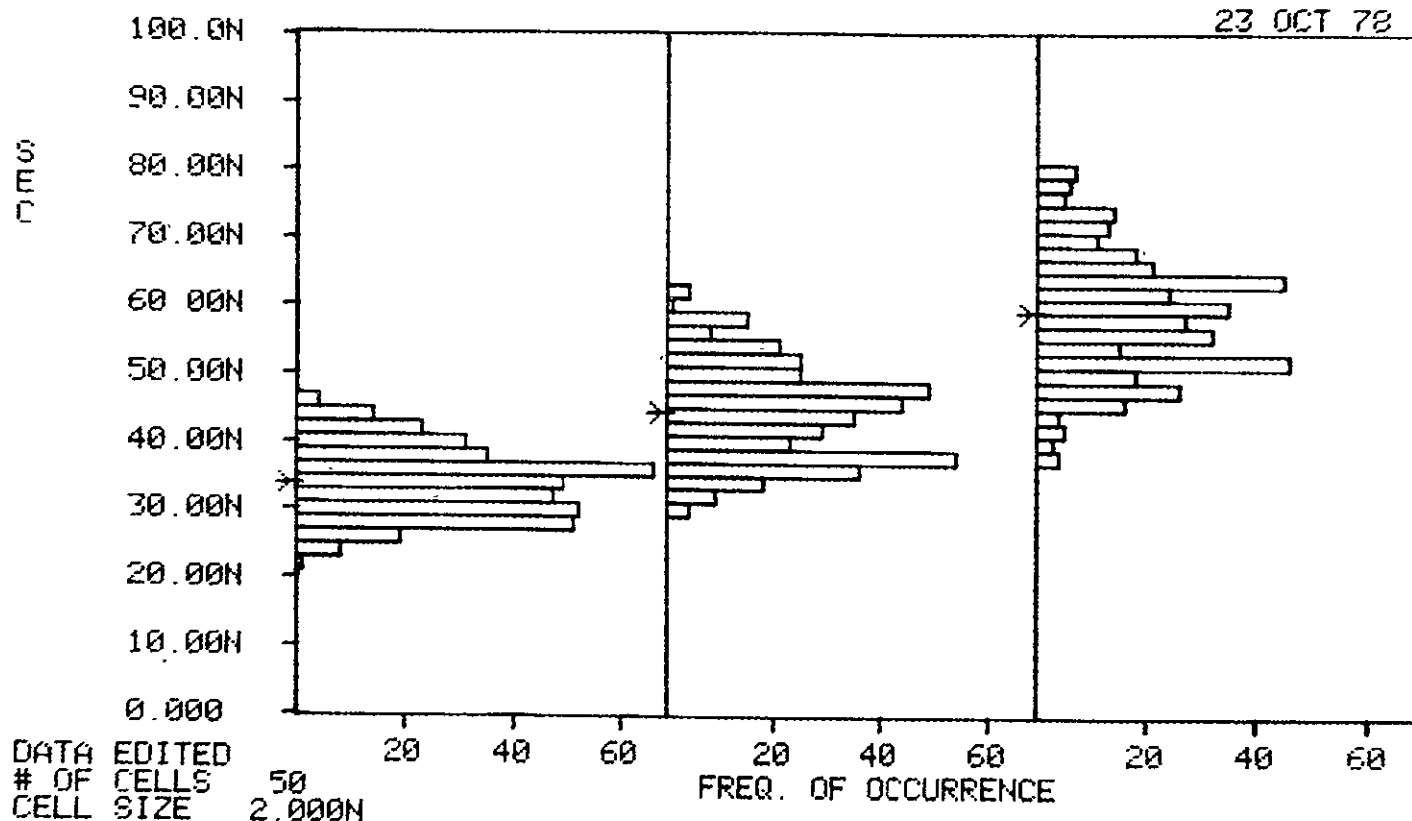
18.98N

S-3250

DATA FOR TED03B

TED0,1,2,3 AT 10V

23 OCT 78



READINGS:

MAXIMUM:

MEAN:

MINIMUM:

STD.DEV.:

400
46.25N
33.85N
22.70N
5.062N

400
61.75N
44.31N
29.00N
7.029N

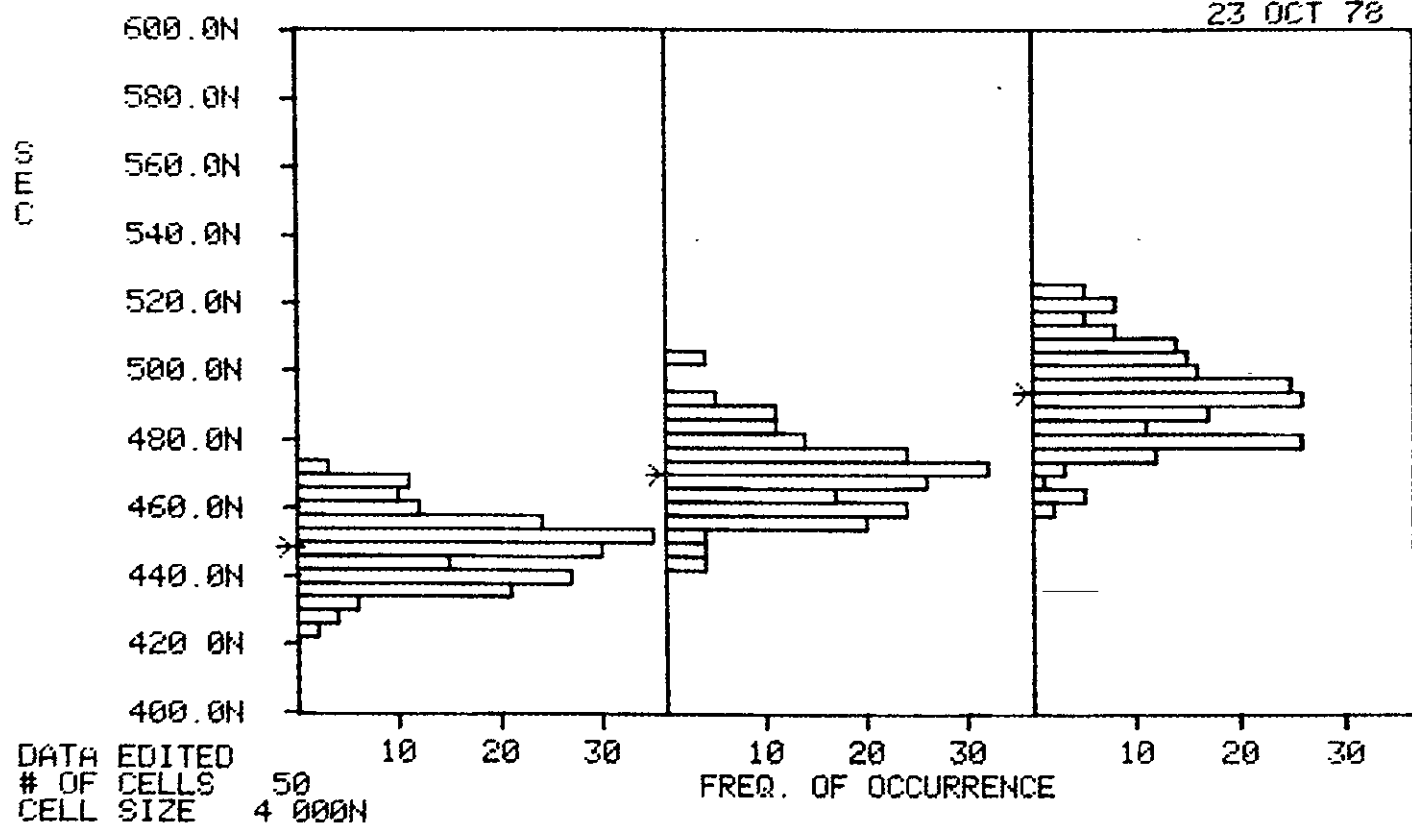
395
80.30N
59.01N
37.60N
9.076N

S-3260

DATA FOR TED46A

TED4/TED6 AT SU

23 OCT 78



DATA EDITED

OF CELLS 50

CELL SIZE 4 000N

READINGS:

MAXIMUM: 200 472.0N

MEAN: 448.5N

MINIMUM: 422.5N

STD.DEV.: 10.34N

200

504.0N

469.8N

443.0N

11.80N

199

525.0N

493.5N

461.0N

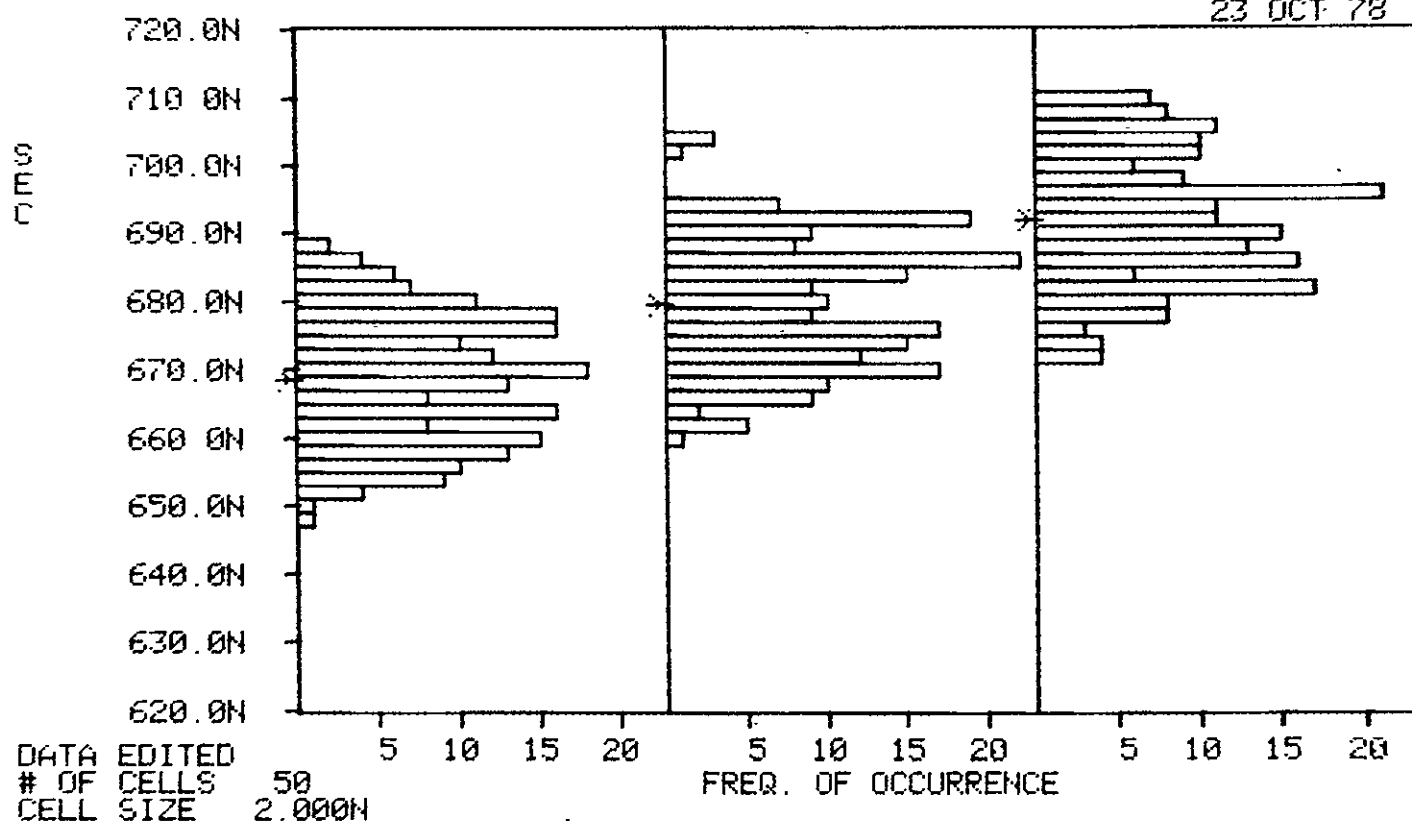
13.96N

S-3260

DATA FOR TED46B

TED4/TED6 AT 100

23 OCT 78



DATA EDITED

OF CELLS

CELL SIZE

50

2.000N

READINGS

MAXIMUM

MEAN

MINIMUM

STD. DEV.

200

688.5N

668.5N

648.0N

9.355N

200

704.0N

679.4N

660.5N

9.417N

198

710.5N

691.9N

671.5N

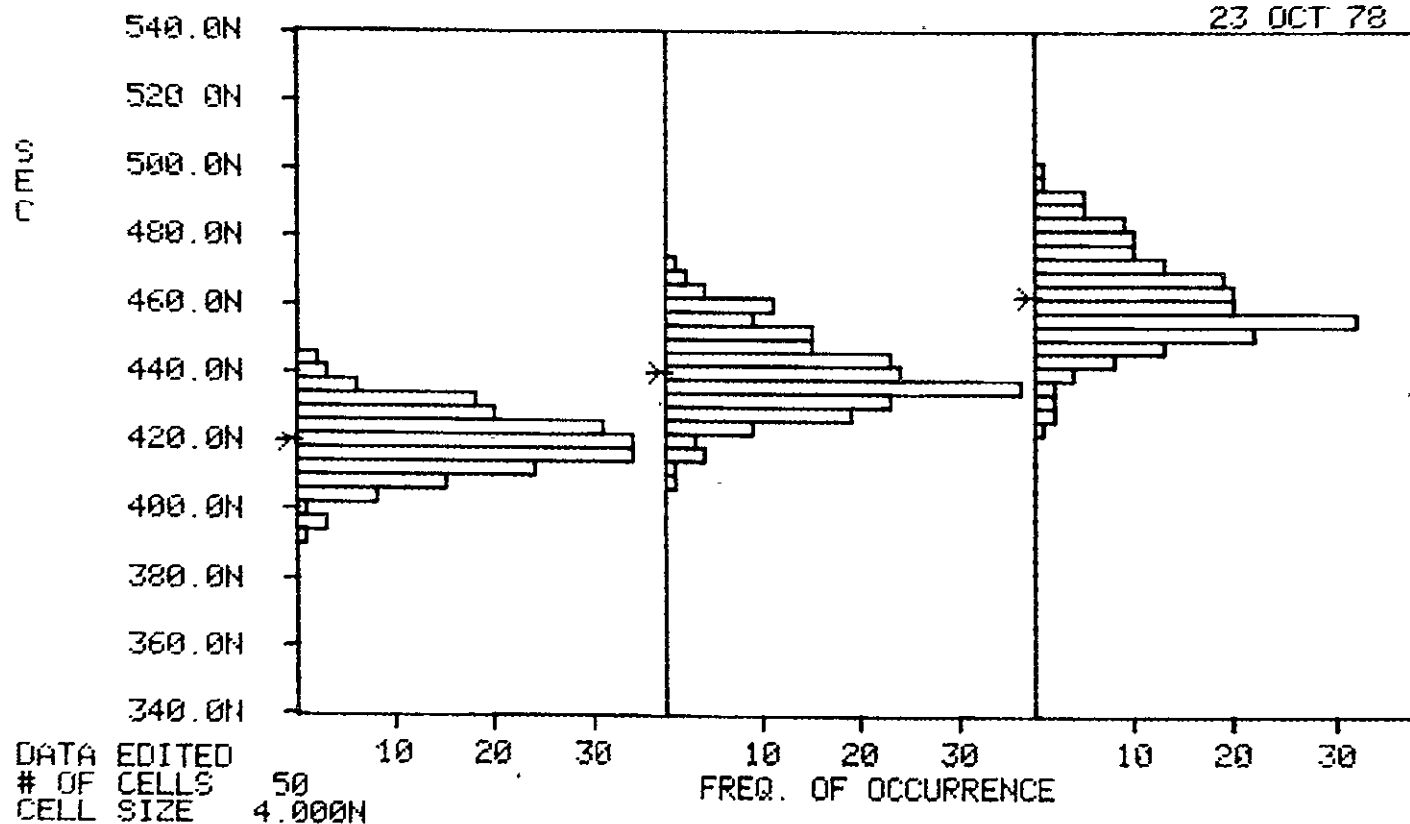
9.876N

S-3260

DATA FOR TED57A

TED5/TED7 AT 50

23 OCT 78



READINGS:

MAXIMUM:

MEAN:

MINIMUM:

STD DEV.:

200

443.5N

419.5N

390.0N

9.348N

200

472.0N

439.8N

407.0N

11.65N

199

500.5N

462.2N

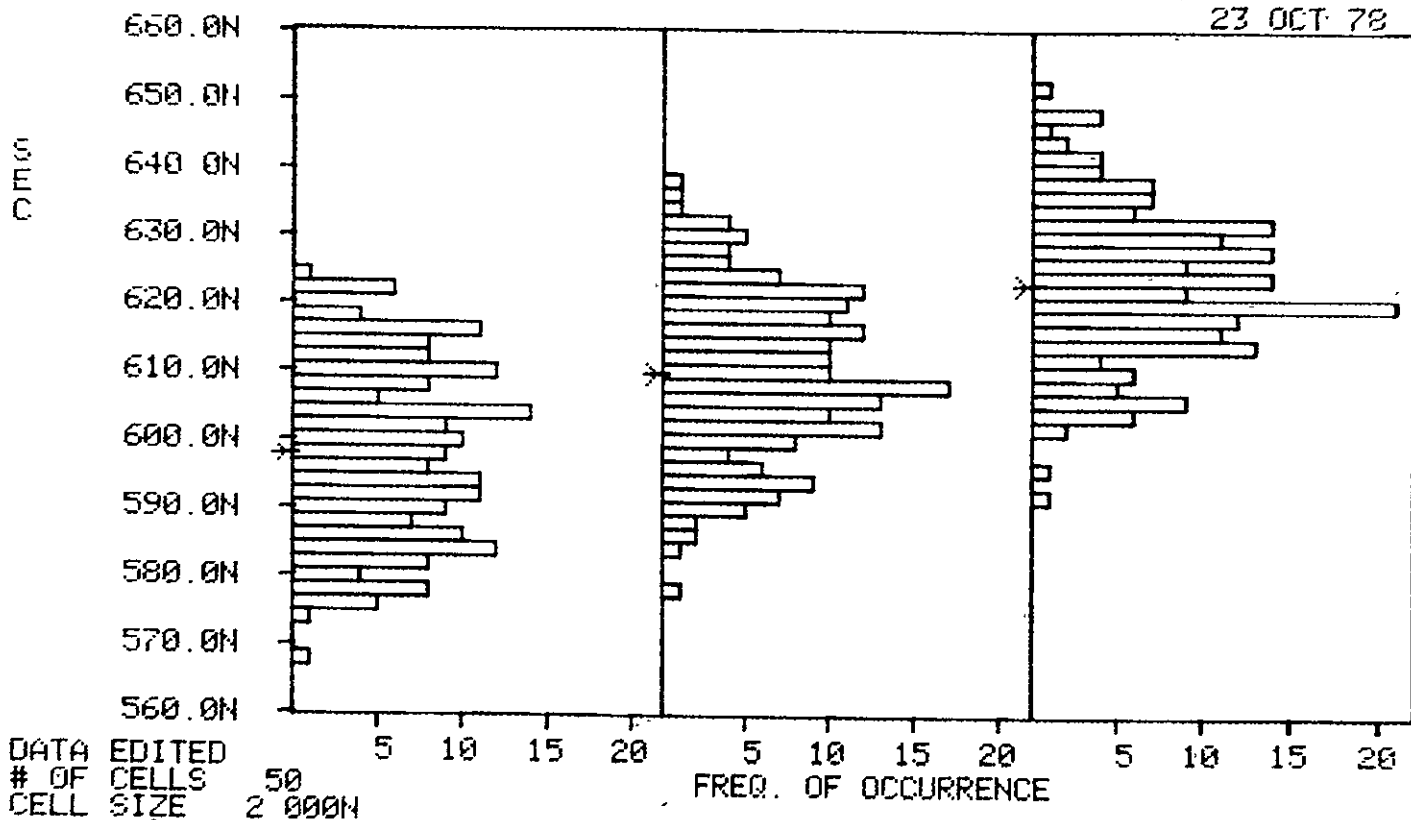
423.5N

14.11N

S-3260 DATA FOR TED57B

TED5/TED7 AT 10V

23 OCT 78



DATA EDITED
OF CELLS 50
CELL SIZE 2.000N

READINGS: 200
MAXIMUM: 624.0N
MEAN: 597.9N
MINIMUM: 568.5N
STD. DEV: 12.76N

200
637.5N
609.6N
578.0N
11.89N

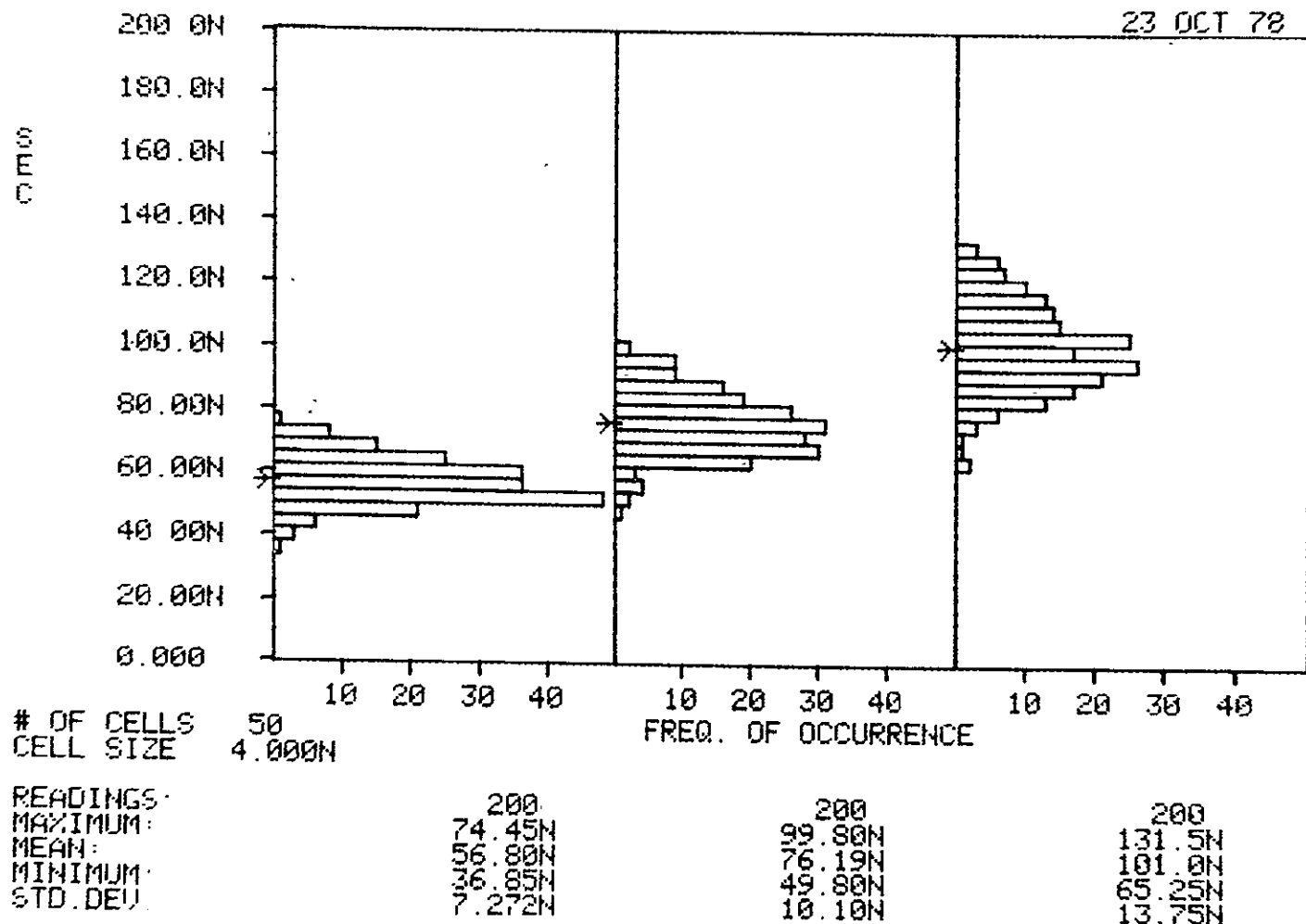
198
652.5N
622.8N
591.0N
11.14N

S-3260

DATA FOR TIB01A

TIB0/TIB1 AT 5U

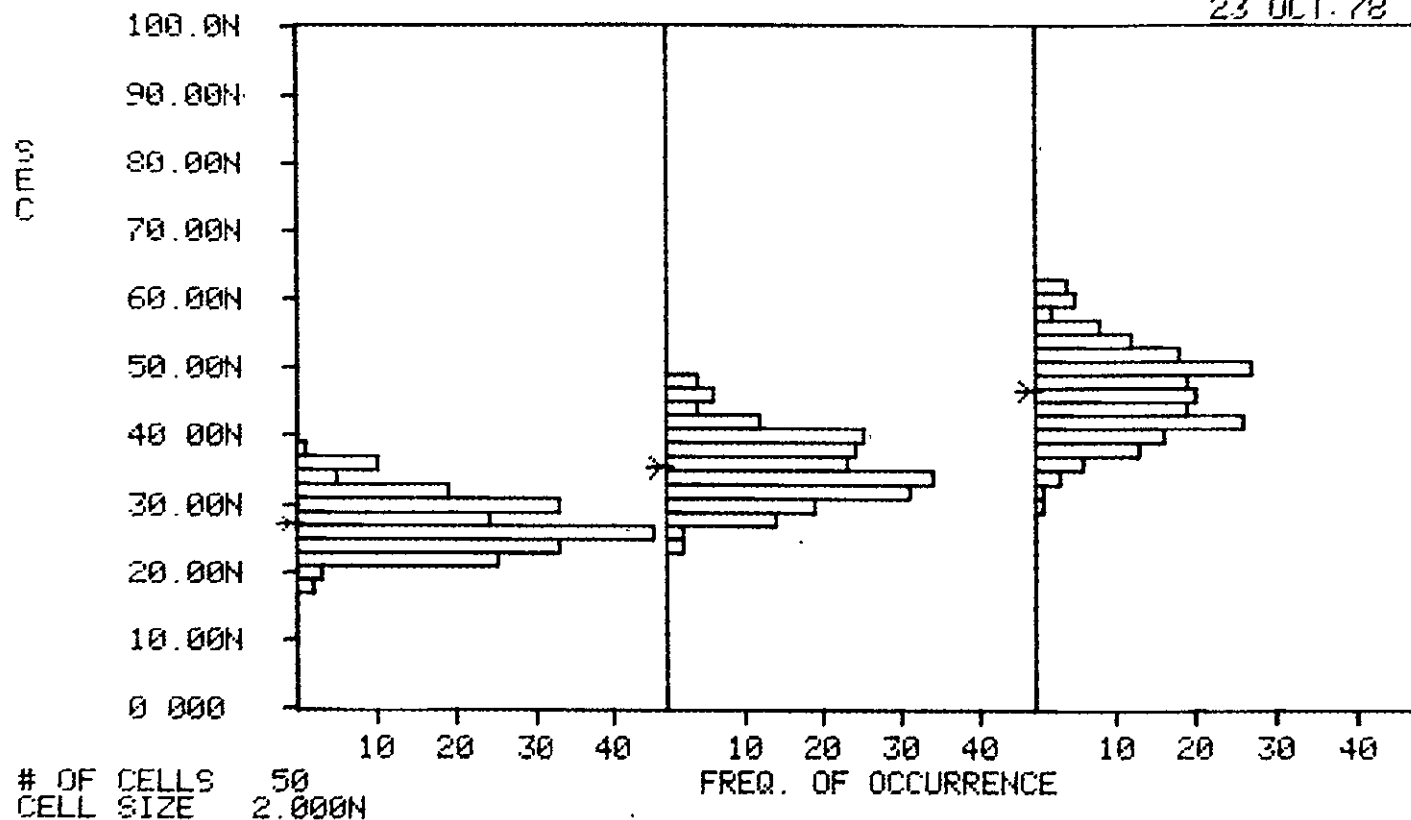
23 OCT 78



S-3260 DATA FOR TIB01B

TIB0/TIB1 AT 100

23 OCT. 78



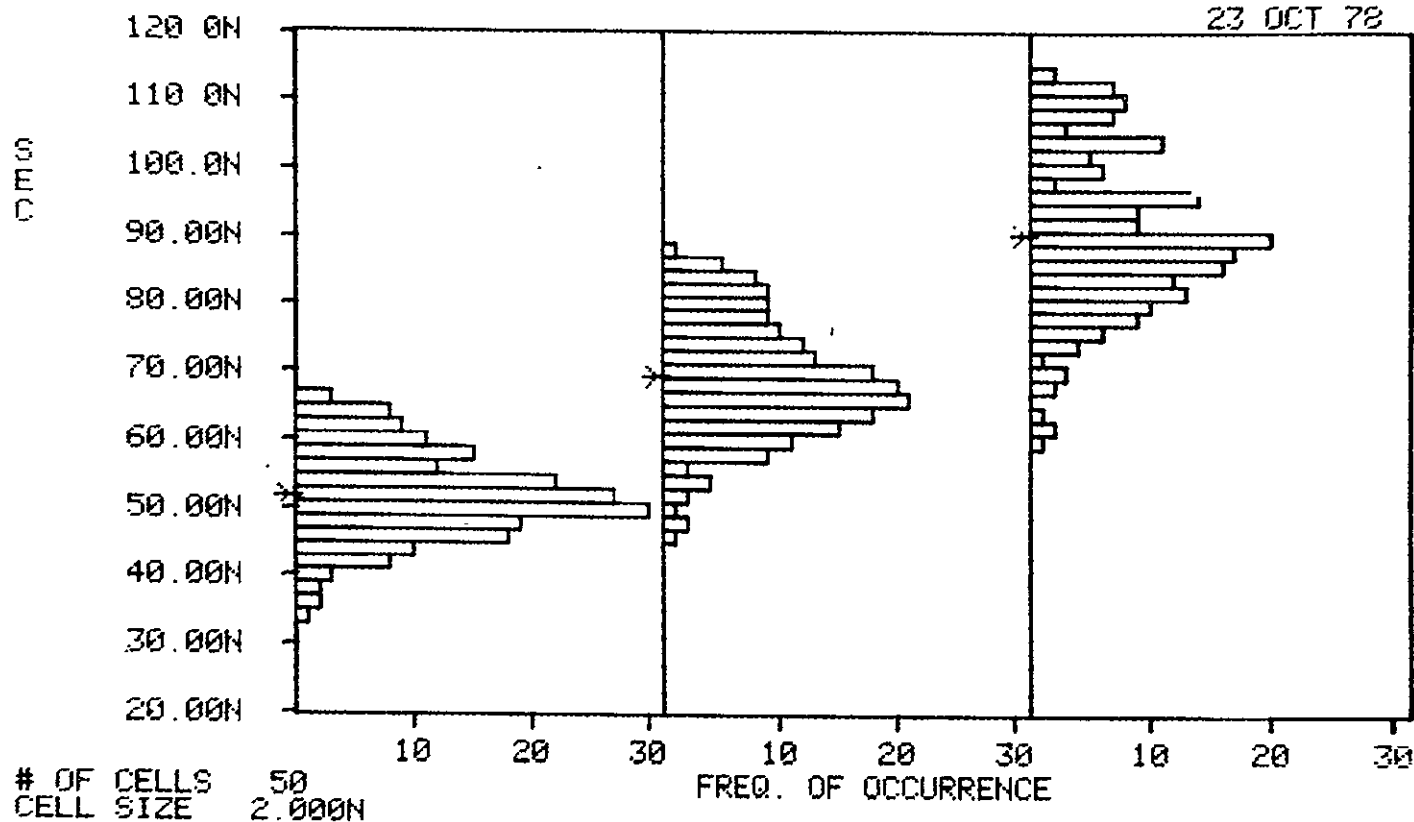
READINGS:	200	200	200
MAXIMUM:	37.25N	48.60N	61.80N
MEAN:	27.20N	35.44N	46.53N
MINIMUM:	18.15N	23.40N	30.65N
STD. DEV. :	4.019N	5.067N	6.416N

S-3260

DATA FOR TB001A

TB00/TB01 AT 50'

23 OCT 78



READINGS:

MAXIMUM: 200 66.55N

MEAN: 51.86N

MINIMUM: 33.85N

STD. DEV.: 6.462N

200

88.55N

69.14N

45.50N

8.663N

200

113.5N

90.42N

59.90N

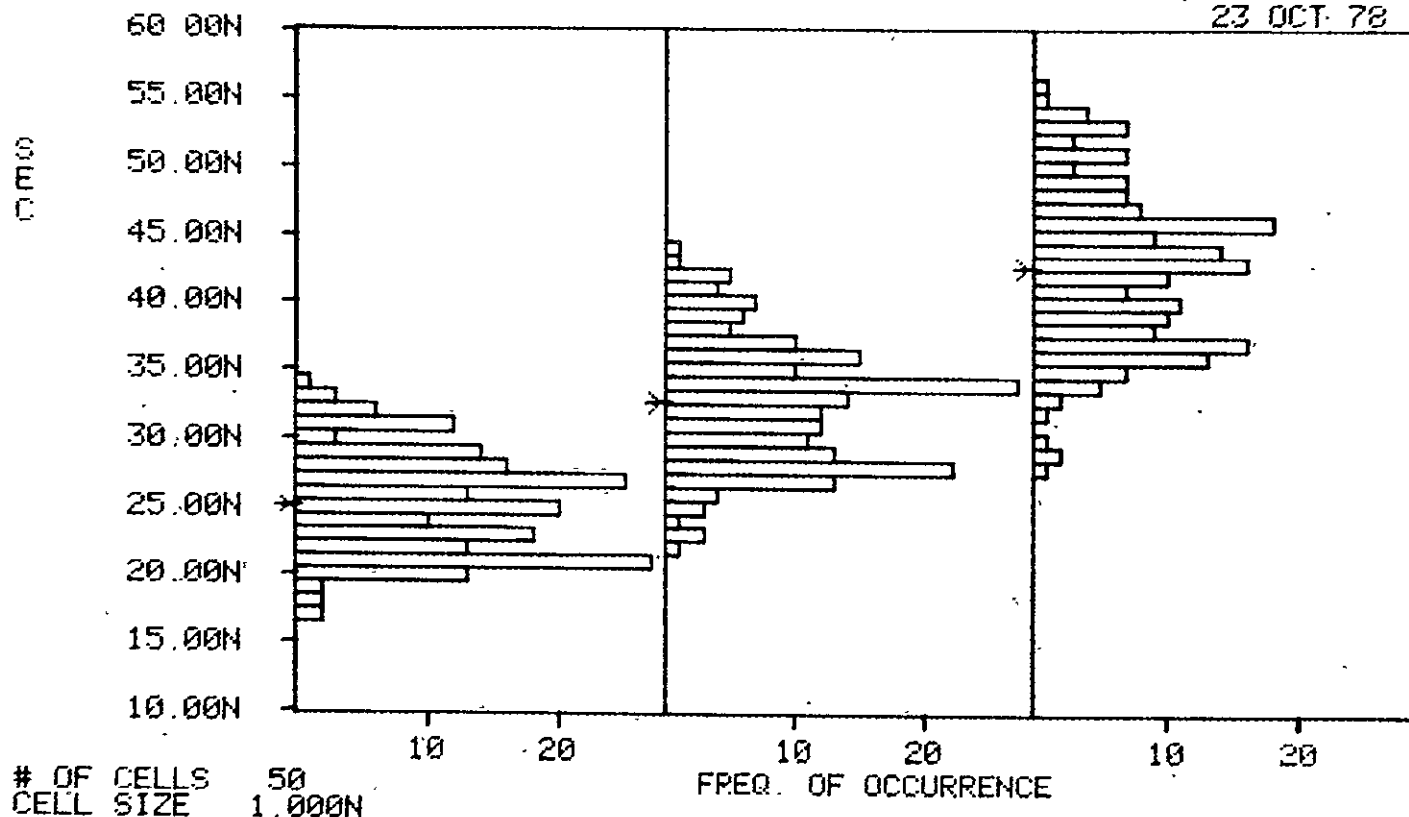
11.51N

S-3260

DATA FOR TB001B

TB00/TB01 AT 10U

23 OCT 78



OF CELLS 50
CELL SIZE 1.000N

READINGS:

MAXIMUM:

MEAN:

MINIMUM:

STD. DEV.:

200
33.90N
25.12N
16.65N
3.744N

200
44.05N
32.63N
21.60N
4.576N

200
56.00N
42.60N
28.25N
5.791N

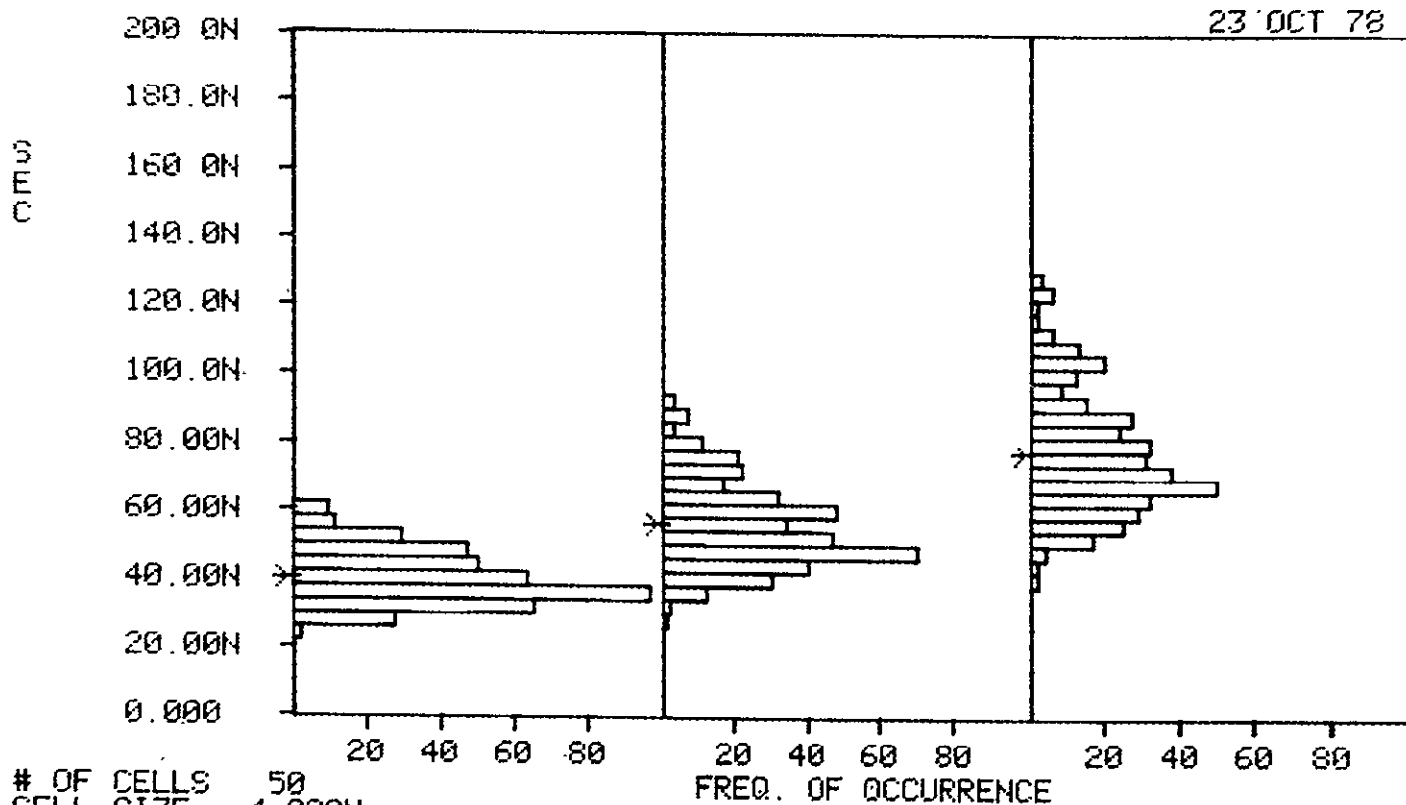
**NASA
FORMAL
REPORT**

S-3260

DATA FOR TTA

TTLH/TTHL AT 50

23 OCT 78



READINGS:

MAXIMUM:

MEAN:

MINIMUM:

STD. DEV

400
61.80N
40.04N
22.20N
7.760N

400
93.40N
56.19N
29.65N
12.66N

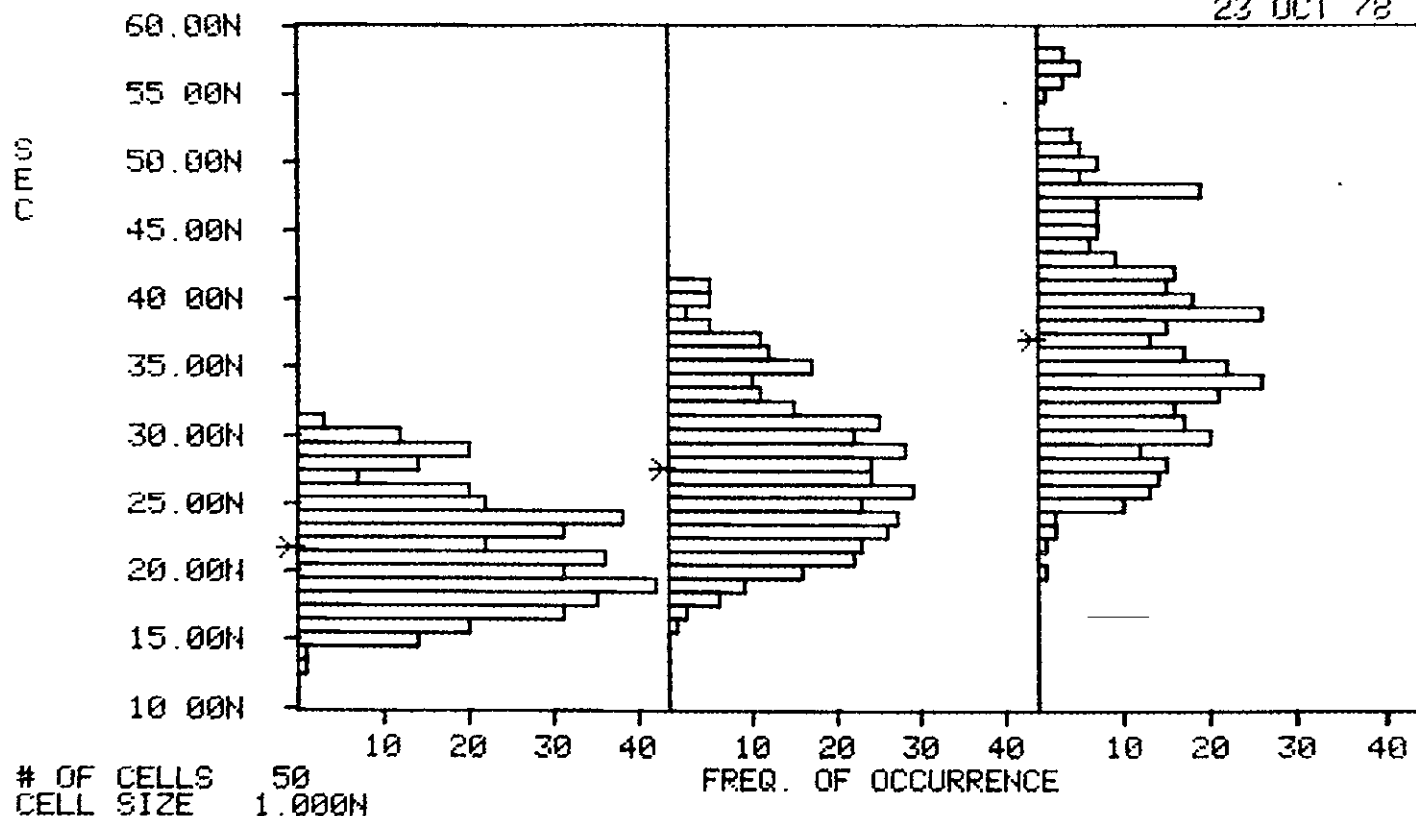
400
129.3N
77.51N
40.10N
17.97N

S-3260

DATA FOR TTB

TTLH/TTHL AT 100

23 OCT 78



READINGS:

MAXIMUM:

MEAN:

MINIMUM:

STD. DEV.:

400
30.85N
21.69N
13.20N
4.115N

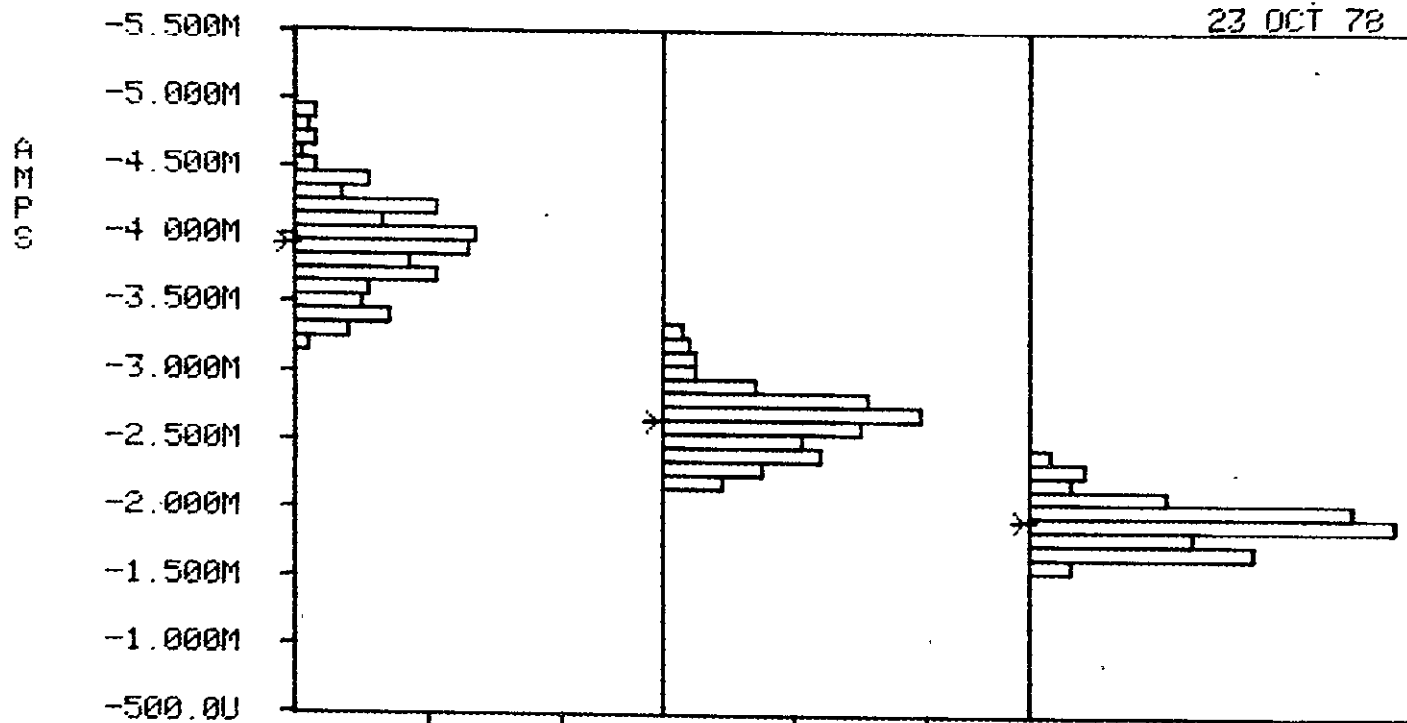
400
40.90N
27.60N
16.10N
5.465N

400
57.90N
37.01N
20.45N
7.823N

S-3260 DATA FOR IOH1

IOH: VDD=5V VOH=4.6V

23 OCT 78



OF CELLS 50
CELL SIZE 100.0U

FREQ. OF OCCURRENCE

READINGS:
MAXIMUM:
MEAN:
MINIMUM:
STD DEV :

200
-3.220M
-3.917M
-4.910M
356.3U

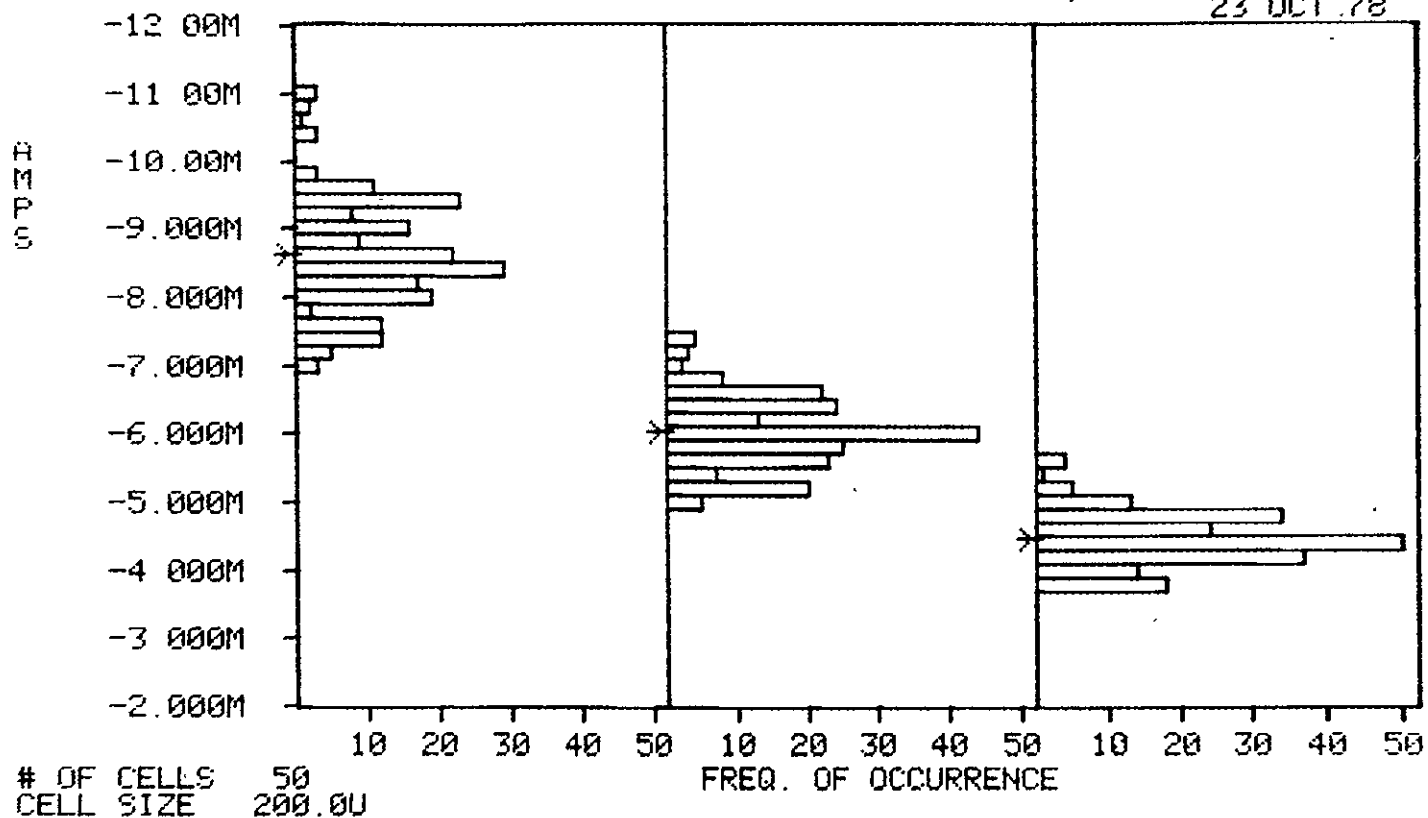
200
-2.200M
-2.639M
-3.305M
237.2U

200
-1.620M
-1.919M
-2.420M
168.3U

S-3260 DATA FOR IOH3

IOH: VDD=10V VOH=9.5V

23 OCT 78



READINGS:

MAXIMUM:

MEAN:

MINIMUM:

STD. DEV.:

200
-7.050M
-8.601M
-11.05M
822.8U

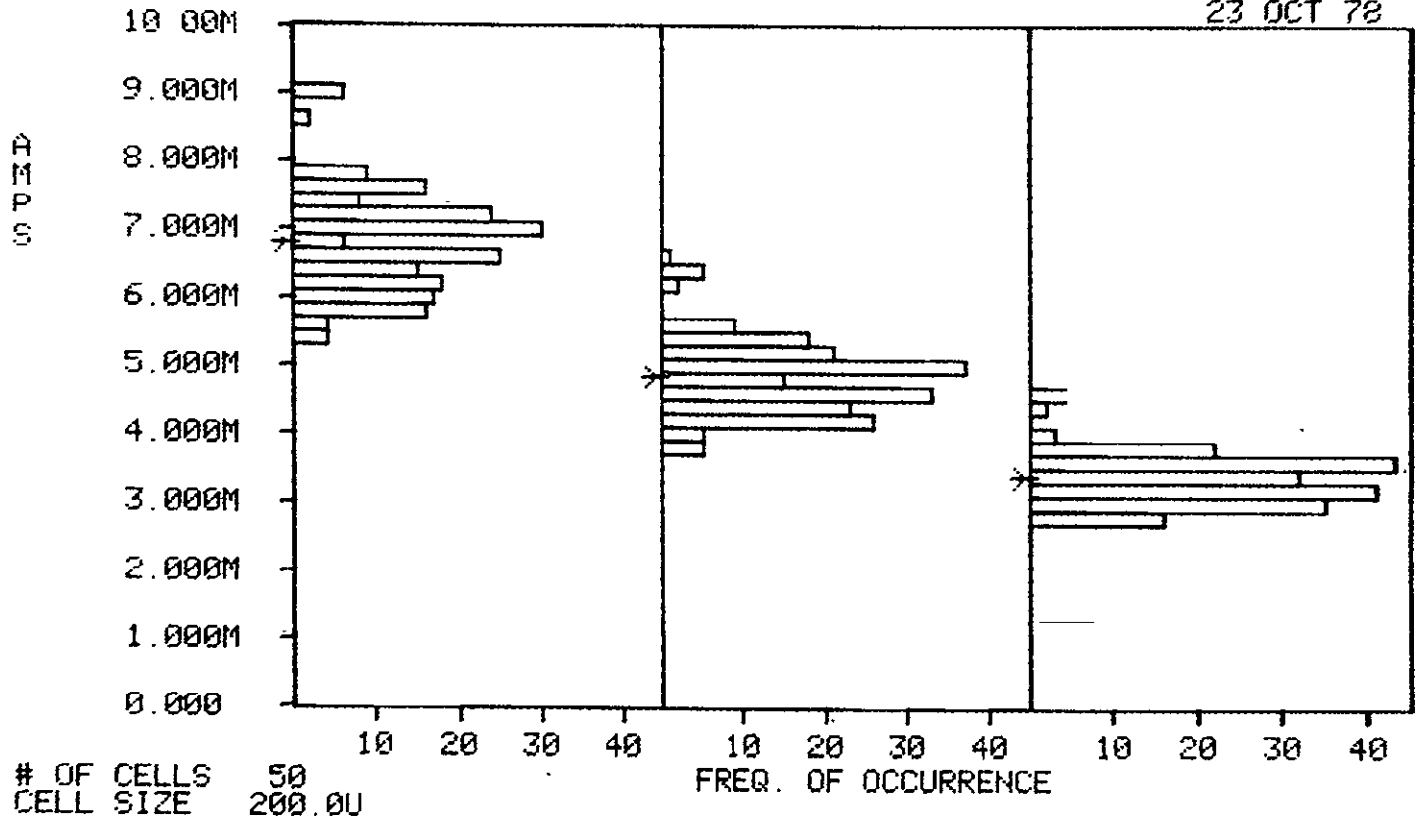
200
-5.000M
-6.021M
-7.480M
530.1U

200
-3.745M
-4.460M
-5.560M
379.7U

S-3260 DATA FOR IOL1

IOL: VDD=5V VOL=0.4V

23 OCT 78



READINGS:

MAXIMUM: 9.090M

MEAN: 6.780M

MINIMUM: 5.310M

STD DEV.: 750.9U

200

6.505M

4.831M

3.775M

543.7U

200

4.600M

3.382M

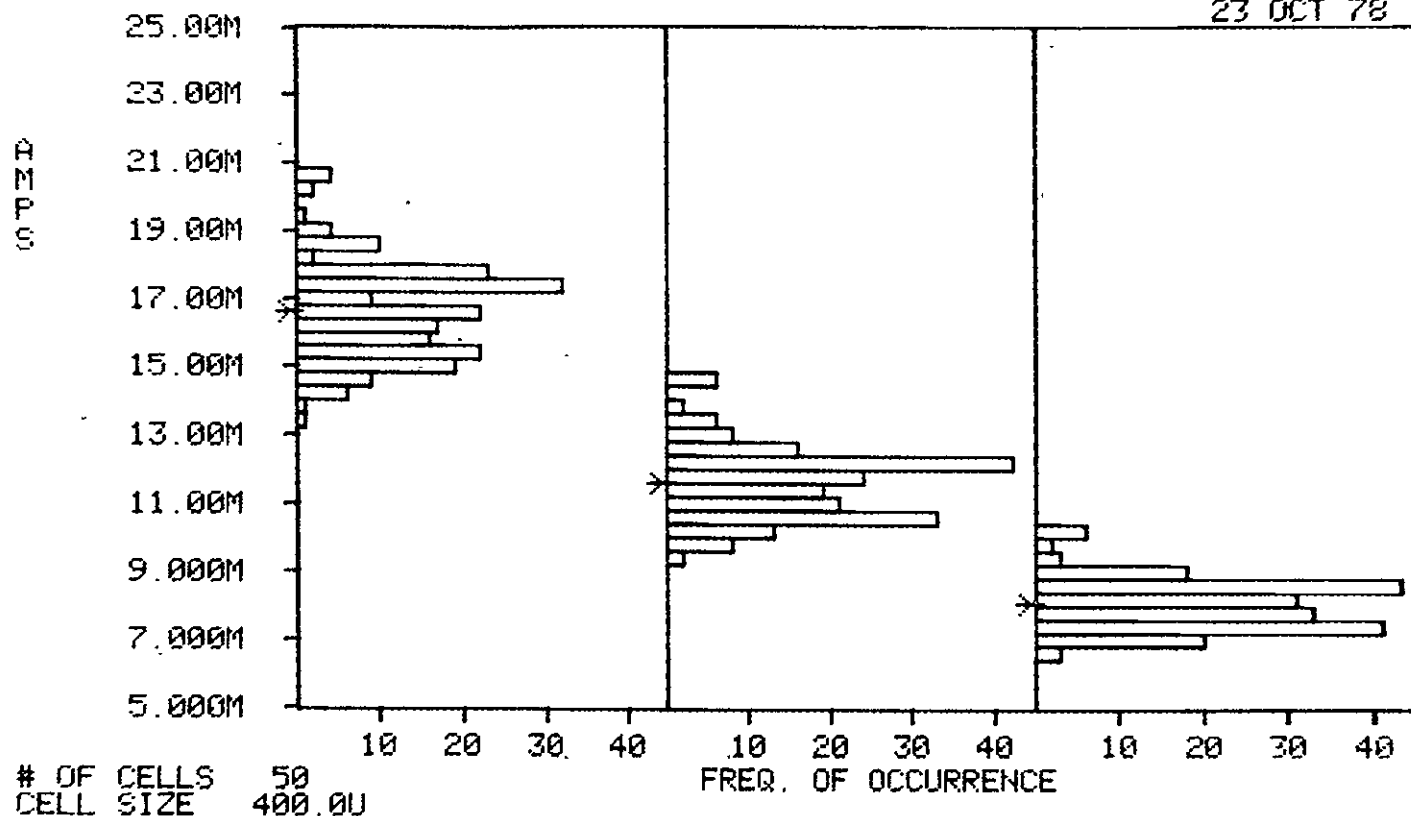
2.710M

382.5U

S-3260 DATA FOR IOL3

IOL: VDD=10V VOL=0.5V

23 OCT 78



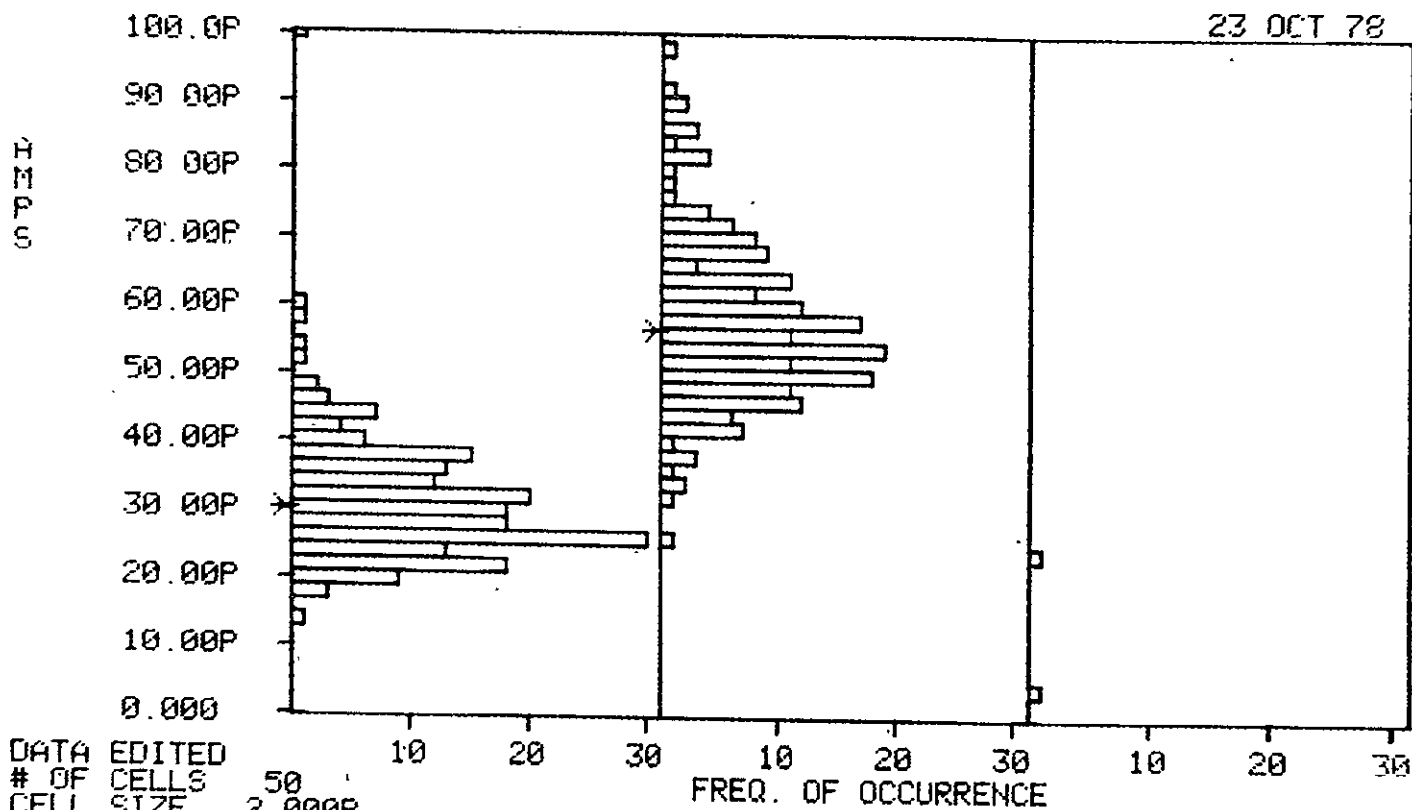
READINGS:	200	200	200
MAXIMUM:	20.60M	14.65M	10.30M
MEAN:	16.62M	11.62M	8.074M
MINIMUM:	13.40M	9.410M	6.645M
STD. DEV.:	1.435M	1.064M	759.6U

S-3260

DATA FOR IOZ1

IOZ1. VDD=15V V0=15V

23 OCT 78



DATA EDITED

OF CELLS 50

CELL SIZE 2.000P

DATA OUTSIDE= '+'

READINGS

MAXIMUM:

MEAN:

MINIMUM:

STD. DEV.:

197
98.06P
30.18P
13.27P
9.218P

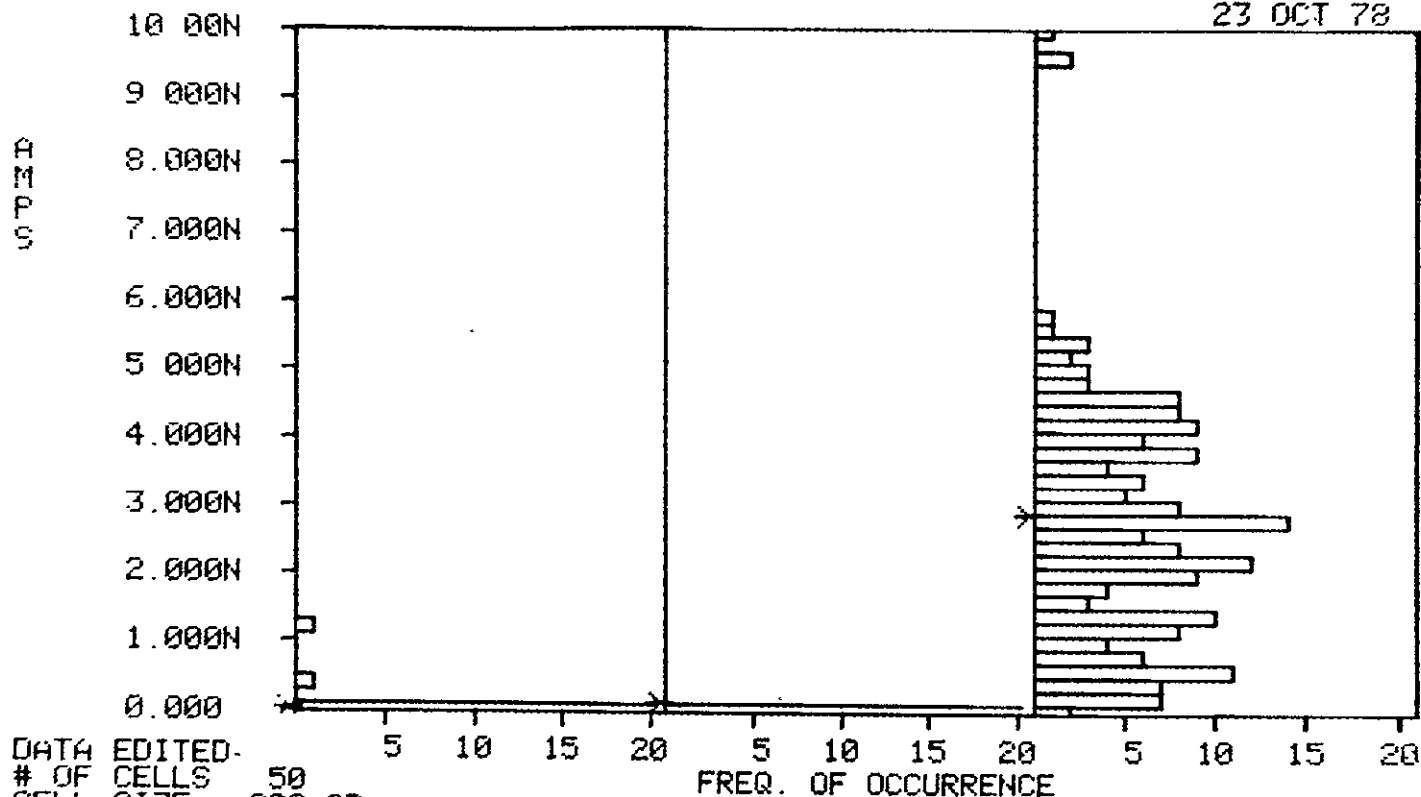
197
96.00P
56.58P
25.87P
12.15P

7
186.7P
123.9P
3.333P
77.49P

S-3260 DATA FOR 1021

1021: VDD=15V V0=15V

23 OCT 78



DATA EDITED-
OF CELLS 50
CELL SIZE 200.0P
DATA OUTSIDE= '+'
READINGS:
MAXIMUM
MEAN
MINIMUM
STD. DEV.:

199
1.241N
37.72P
13.27P
88.63P

198
10.96N
111.6P
25.87P
774.7P

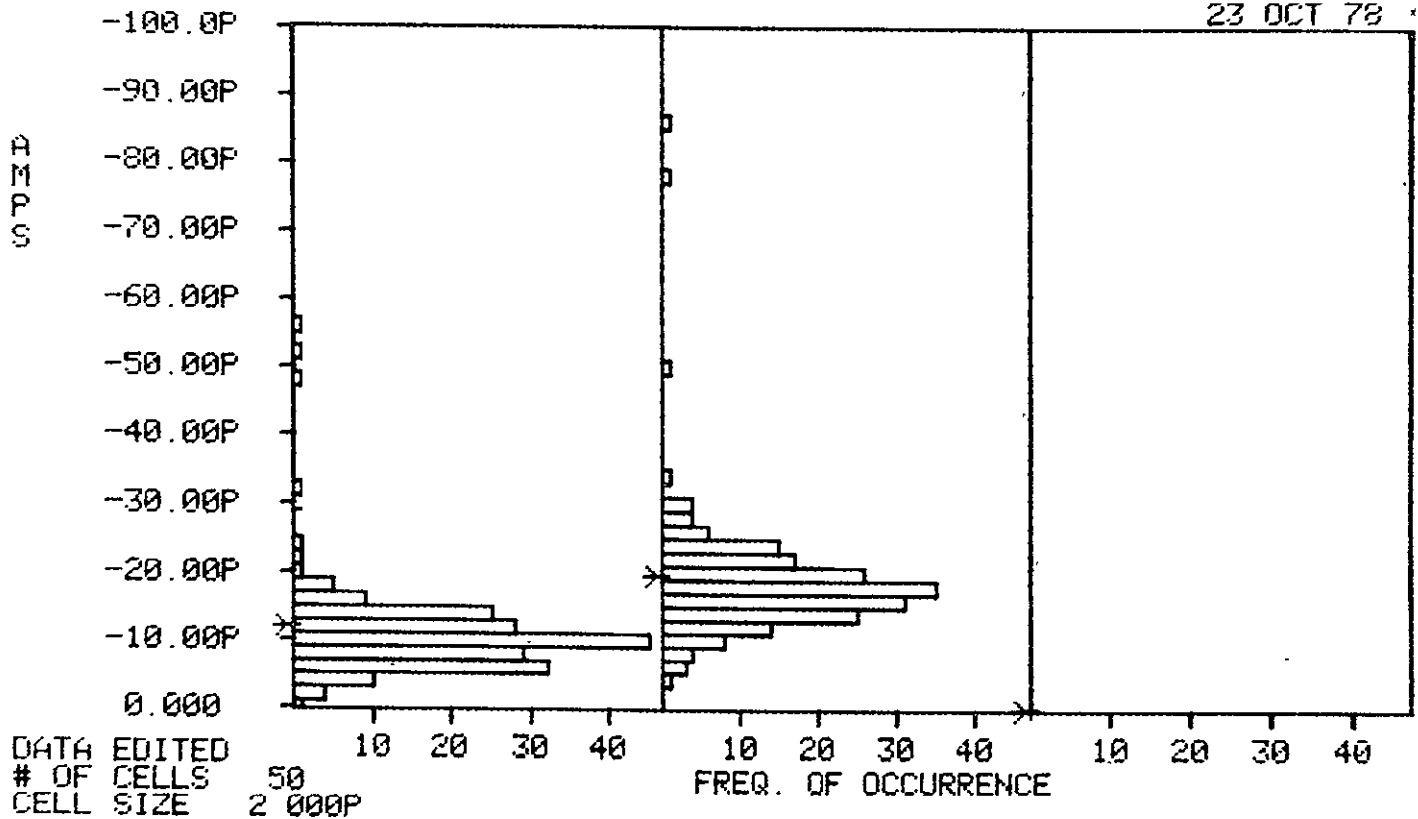
194
11.48N
2.872N
3.333P
2.060N

S-3260

DATA FOR IO22

IO22: VDD=15V V0=0V

23 OCT 78



READINGS:

MAXIMUM:

197
-333.3E-15197
-4.867P0
0.000

MEAN:

-11.92P

-19.65P

0.000

MINIMUM:

-56.84P

-86.38P

0.000

STD. DEV.:

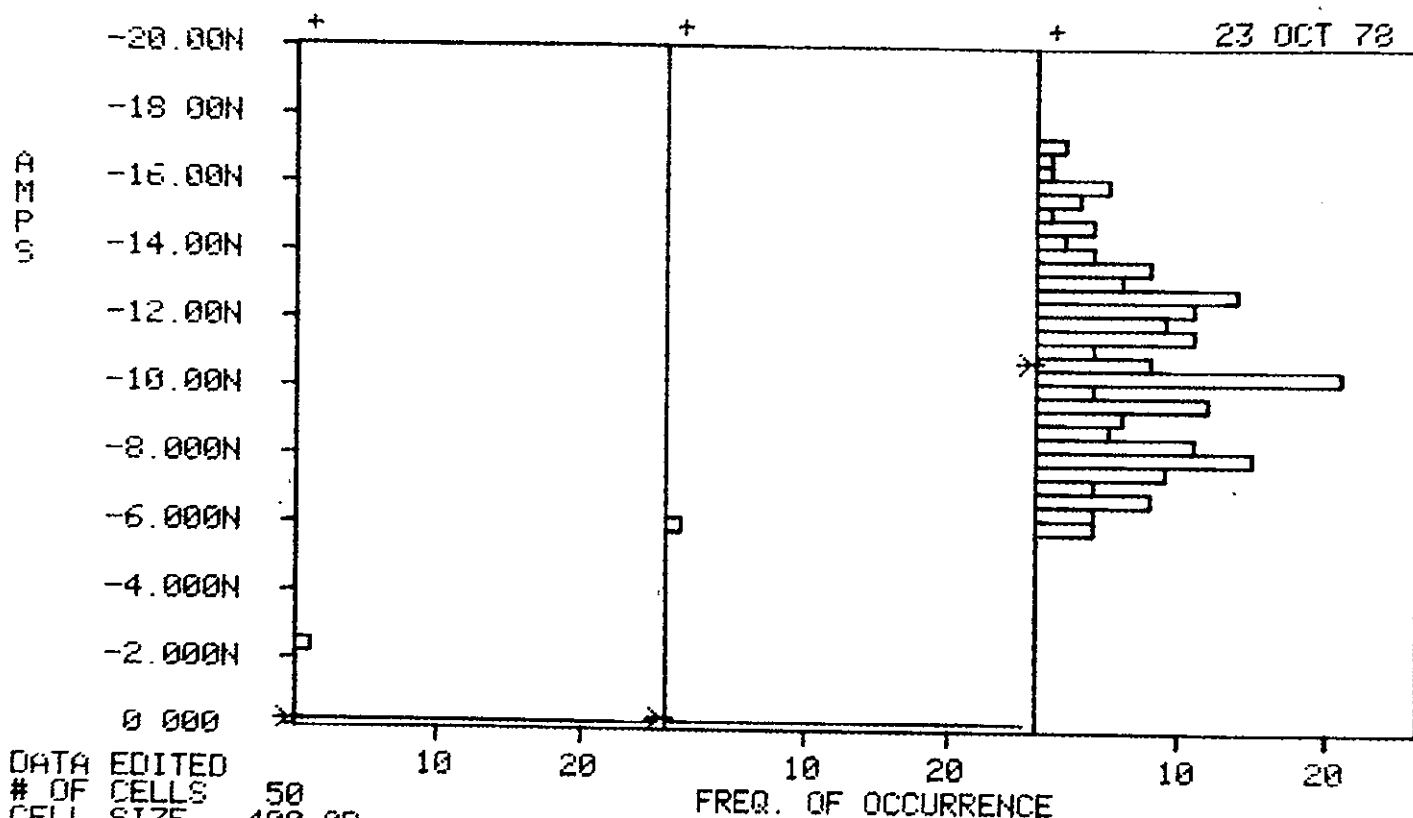
6.867P

8.507P

S-3260 DATA FOR IO22

IO22: VDD=15V V0=0V

23 OCT 78



DATA EDITED
OF CELLS 50
CELL SIZE 400.0P
DATA OUTSIDE= '+'
READINGS:
MAXIMUM
MEAN:
MINIMUM
STD. DEV

199
-333.3E-15
-219.3P
-38.87N
2.759N

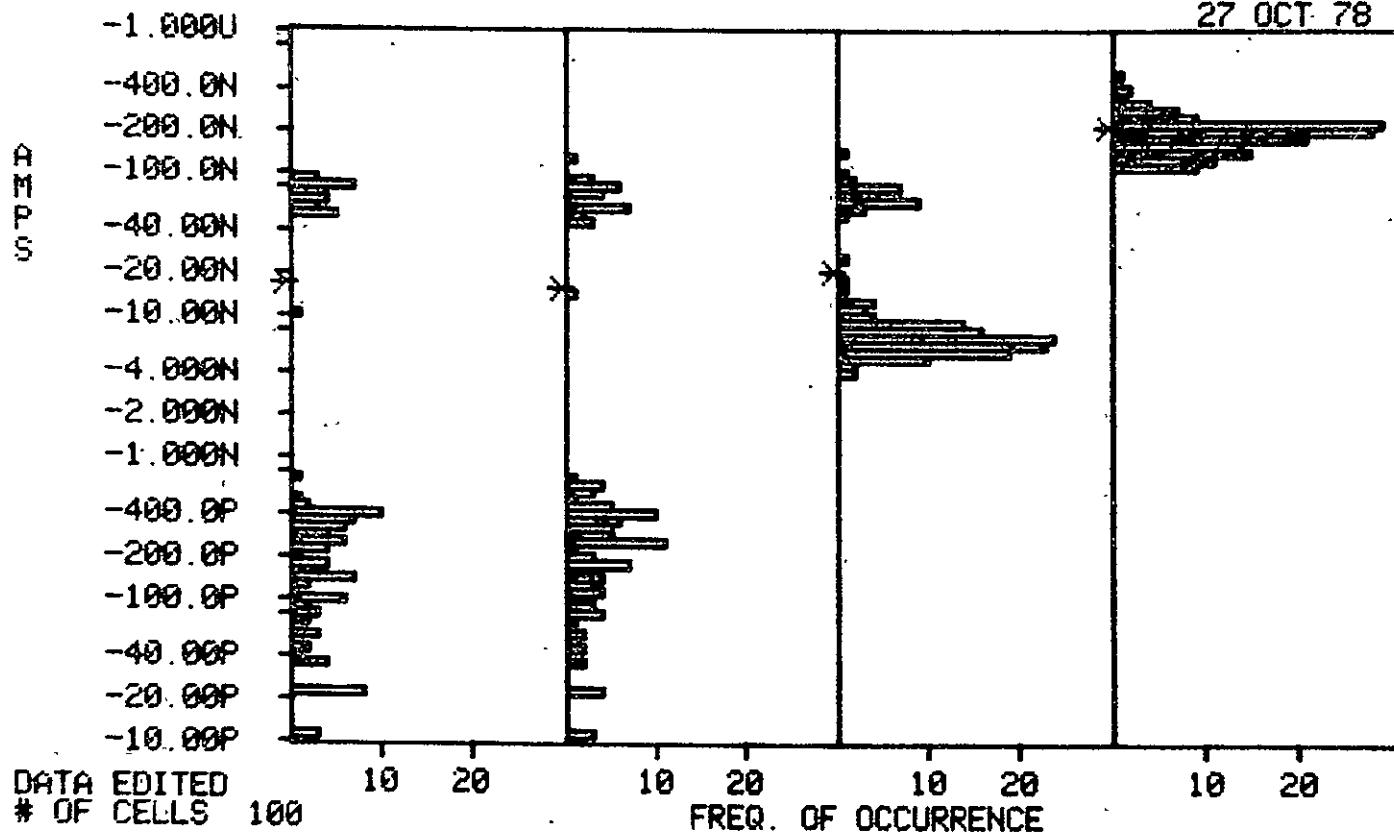
199
-4.867P
-304.4P
-50.81N
3.622N

198
-5.893N
-10.80N
-28.81N
2.944N

S-3260 DATA FOR ISS10

ISS AT 10V (-55,25,85,125 C)

27 OCT 78

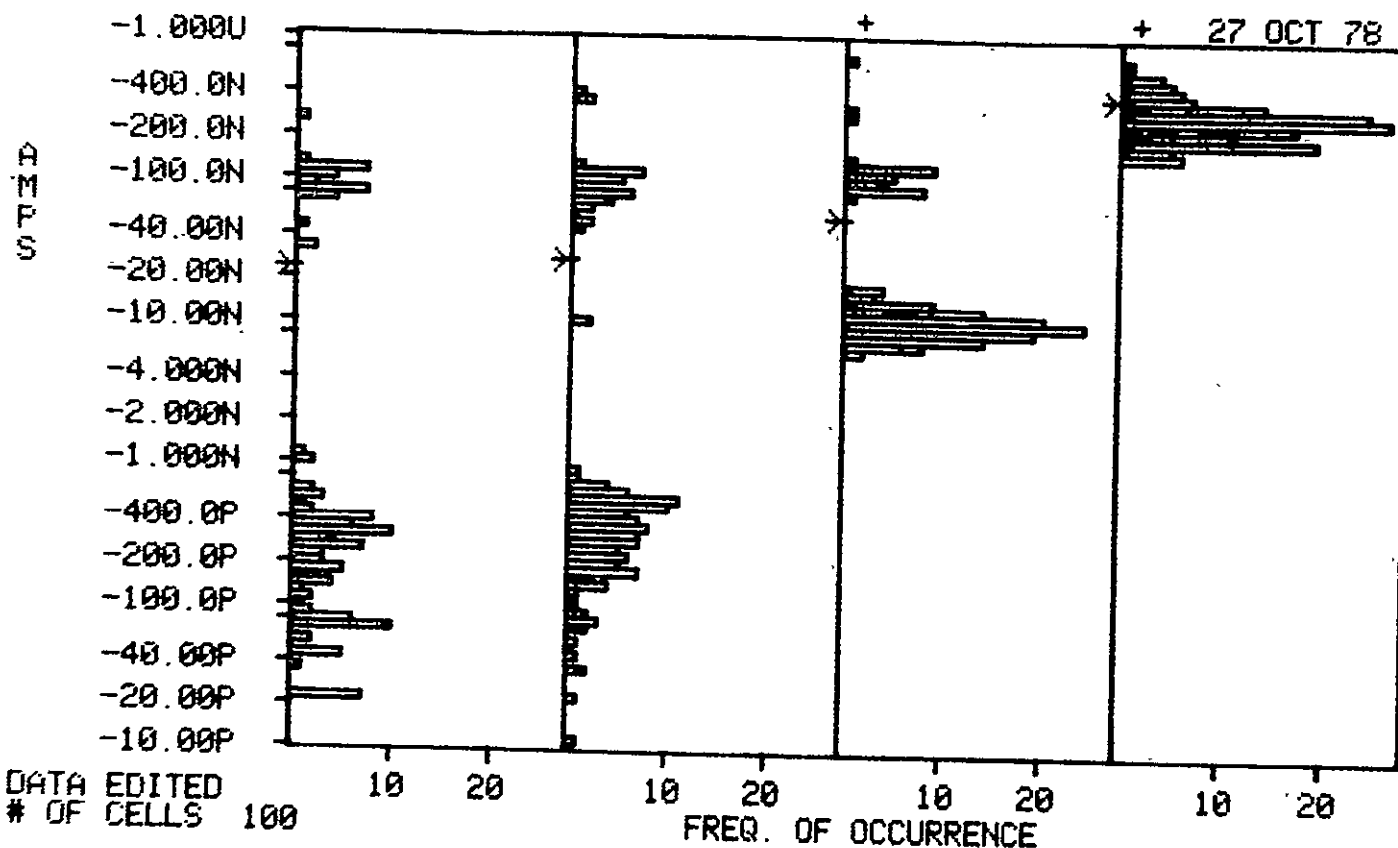


READINGS:	119	129	150	150
MAXIMUM:	0.000	0.000	-4.463N	-120.5N
MEAN:	-16.57N	-15.55N	-20.60N	-214.4N
MINIMUM:	-98.50N	-141.5N	-155.0N	-566.5N
STD DEV	31.63N	31.60N	28.50N	65.47N

-ORIGINAL PAGE IS
OF POOR QUALITY

S-3260 DATA FOR ISS15

ISS AT 15U (-55,25,85,125 C)



DATA EDITED
OF CELLS 100

DATA OUTSIDE= '+'

READINGS:

MAXIMUM:

MEAN:

MINIMUM:

STD DEV:

130
0.000
-22.94N
-273.5N
46.87N

146
-12.50P
-27.14N
-455.0N
68.27N

150
-7.050N
-54.59N
-1.065U
141.4N

150
-170.0N
-389.5N
-3.240U
295.6N